



Product Catalog

Connectors • Test Sockets • Spring Contact Probes

smiths bringing technology to life

IDI Joins Smiths Interconnect

In April of 2010, Interconnect Devices, Inc. (IDI), joined Smiths Interconnect, a division of a global technology business, Smiths Group plc. IDI is a part of the Connector Technology Group within Smiths Interconnect.

The complementary technologies product offerings, routes to market and critical mass of IDI and the Connectors Technology Group, supported by the global presence and financial resources of Smiths, provides IDI with a strong and stable platform to continue to build a successful future.

As a member of the Smiths family of companies, IDI is committed to maintaining the strong Antares and Synergetix brands, our engineering expertise, products, and commitment to excellent customer service. Our position as an industry-leading producer of spring probe technology is now further supported by the extensive global resources of Smiths Group.

SMITHS INTERCONNECT

Smiths Interconnect, (www.smithsinterconnect.com), is a leader in technically differentiated electronic and radio frequency products that connect, protect and control critical systems for the wireless aerospace, telecommunications, defense, industrial, medical and rail markets. Smiths Interconnect is part of Smiths Group, (www.smiths.com), a global leader in applying various advanced technologies for markets in threat and contraband detection, communications, energy, medical devices, and engineered components. Smiths Group employs around 22,000 people in more than 50 countries.



INTERCONNECT DEVICES, INC.

Interconnect Devices, Inc. (IDI) (www.idinet.com), is a leading provider of spring contact probe based technologies that includes custom connectors and advanced semiconductor test sockets and spring contact probes. Founded in 1979, Interconnect Devices, Inc. (IDI) was organized to supply spring contact probes for the PCB test industry. IDI quickly established itself as the World's Leader in Spring Contact Probe Technology.

SPRING CONTACT PROBE TECHNOLOGY

Spring contact probes provide many design and performance advantages that are proven to deliver consistent, reliable connections over multiple mating cycles. For overall reliability, long life and serviceability, spring loaded contact probes will always outperform stamped metal, elastomer, and wire mesh designs. When these spring contact probes are integrated into IDI's custom interconnect devices, IDI technology can provide you with the best interconnections that your application demands:

- Consistent performance, first stroke, every stroke
- Reliability over the life span of the product
- · Million-cycle mechanical lifetimes
- Low, consistent resistance
- High current capacities
- Constant contact when exposed to shock, vibration, and acceleration
- Versatility of mounting and profile
- · High performance under extreme conditions
- Extremely high density
- · Z Axis compliancy

A SOLUTION FOR YOUR NEEDS

IDI's spring probe technology is easily modified to become the precise solution for your application. Whether you are a large product manufacturer or a start-up company, no application is too big or too small. IDI connectors and interfaces are found in a variety of industries, where performance requirements are stringent, including:

- Medical
- Aerospace
- Military
- Automated Test Equipment
- Automotive
- Telecommunications
- Portable Electronics



Interconnect Devices, Inc.

IDI SPRING CONTACT PROBES

IDI is the world's largest probe manufacturer of spring contact probes for the Automate Test Industry. For over three decades, test engineers have turned to IDI for the most reliable

probe designs available, both off-the-shelf and custom connectors.



IDI TEST SOCKETS

IDI leads the innovation in the semiconductor test industry today with its Antares and Synergetix brand test socket designs. These semiconductor test sockets were the first to use spring contact probe technology.



IDI CONNECTORS

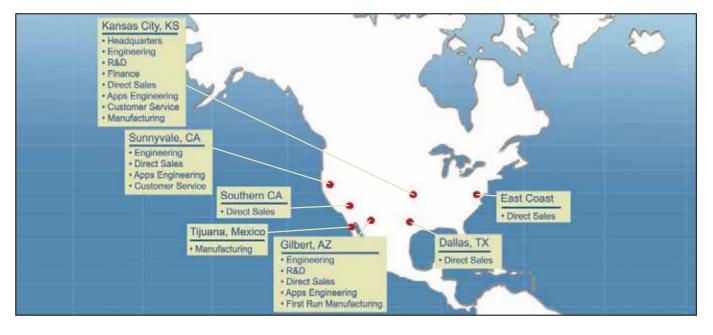
IDI is known for designing probes for use outside of the test environment in a variety of industries. In the early 1990's, the company began a strategic initiative to identify a variety of new marketplaces where its core competencies could be utilized competitively.

IDI expanded its markets to include custom connectors.

IDI's custom connectors can be found in a variety of applications within the test and measurement, military, aerospace,



medical, homeland security and industrial markets. IDI's spring contact probe connectors are renowned for their performance in high reliability, fail-safe applications.



Interconnect Devices, Inc. welcomes your e-mail at info@idinet.com

GLOBAL SALES

IDI has sales offices located throughout the world. Our customer service departments locations are:

- Kansas City, KS
- Suzhou, China

Our sales and applications engineering locations are:

- Kansas City, KS
- Sunnyvale, CA
- Dallas, TX
- Boston, MA
- Gilbert, AZ
- Southern CA
- Taiwan
- Europe

China

Korea

Sunnyvale, CA

Singapore

France

Malaysia

Singapore

Philippines

Germany

Italy

GLOBAL ENGINEERING

Experts in mechanical, electrical software and thermal engineering, we use the latest tools that are available to develop unique solutions that are based upon real-time, real-world customer requirements. Through the use of a multi-talented engineering staff, we are able to develop solutions for the most stringent of applications. Our engineering offices are located throughout the US and Asia.

GLOBAL MANUFACTURING

IDI is an ISO 9001:2008 certified manufacturer. Our flexible approach to manufacturing and assembly uses the most advanced tools, techniques and Quality Assurance methods that allow us to ramp quickly to meet our customers' needs. Our Kansas City, Tijuana, Mexico and Suzhou, China facilities are equipped with a Class 10,000 clean room, minimizing and controlling contaminants. Our global footprint ensures 24/7 support from numerous locations. Our commitment to "first-cycle, every-cycle reliability" is backed by extensive product testing and evaluation in our Analysis and Validation labs.

IDI Global Presence

GLOBAL ANALYSIS AND VALIDATION CAPABILITIES

Metallurgical Testing - Kansas City, KS

- Scanning electron microscope (SEM)
- Energy dispersive spectrometer
- Micro-hardness tester

Electrical Performance Testing – Kansas City, KS; Gilbert, AZ; Suzhou, China

- Six life cycle simulation testers
 - Resistance budgeting R2D2
- High current testing

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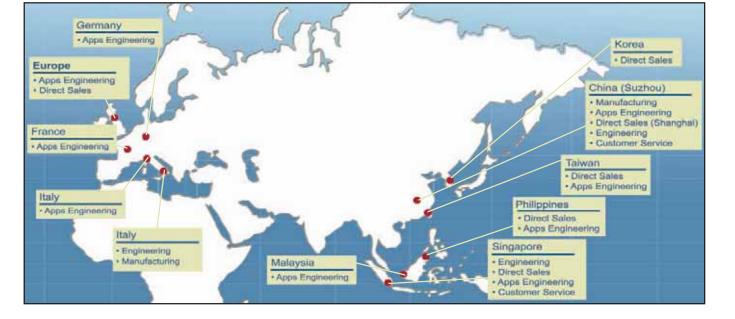
• Current carrying capacity testing (CCC)

Signal Integrity Testing - Kansas City, KS; Gilbert, AZ

- Network analyzers
- SPICE modeling software
- Time Domain Reflectometry (TDR)

Mechanical Testing - Kansas City, KS

- Real-time x-ray with CT scan capabilities
- Micro-tribometer
- Temperature and humidity chamber
- X-ray fluorescence plating thickness
- 3D non-contract profrilometer
- Several other specialized test systems



OEM Connectors & Probes

Whether it's vibration, shock, rotation, wipe, water, salt, sand, dust, heat or the vacuum of space, you can depend on IDI to deliver products that will withstand adverse conditions and perform on demand. IDI harsh environment probes and connectors offer many other design features including:

- One-piece compression mount connector
- Consistently low resistance < 10 mΩ throughout hundreds of thousands of cycles
- 20 GHz @ -.5db
- High density —
 .010 (0.25) pitch
- Short signal paths as low as 0.070"
- Blind mate
- Surface mount, through hole mount or cabled termination

IDI custom connectors ensure a reliable, fail-safe connection even in the harshest of environments. At the core of most IDI connectors is the spring contact probe, a connection technology inherently well suited to harsh environments.

SHOCK AND VIBRATION

Spring contact probes provide a constant force against the mating contact surface, easily absorbing and compensating for movement seen during shock and vibration without contact interruption as defined by MIL-STD-810F.

WATER, SALT, SAND AND DUST

IDI utilizes various design features for ingress protection to IP68 and MIL-810F on our connectors. And IDI offers the world's first and only Environmentally Sealed Probe (pg. 21) with ingress protection to IP68 and MIL-STD-810F.

ROTATION AND WIPE

The contact or plunger in the spring contact probe is free to rotate and slide within the housing or barrel of the probe. This inherent design characteristic makes spring probe connectors ideal for bayonet and sliding mate connector designs.

HEAT AND VACUUM OF SPACE

IDI connectors and probes operate under a wide variety of temperature extremes. Most designs are rated from -55° C to 250° C. Alternate materials allow for even more aggressive temperature extremes.

IDI SPRING PROBE CONNECTORS

Spring contact probes provide repeatable contact in the field for modular components, reduce costs, and eliminate cabled connections by providing a dependable direct connection in rotating or sliding joints.



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Connectors & Contacts

IDI is the world leader in spring contact probe design and the industry's expert in applying spring probes as connector contacts. Embodied in IDI's connector product lines, probes are an enabling technology that fundamentally change the capabilities of the products in which they are incorporated.

EXCELLENT FOR BLIND MATE

IDI connectors featuring spring contact probes are compliant on the surface of their mating half, rather than extending into it as with conventional pin and socket connectors. This grants them their unique blind-mate capabilities.

An IDI connector may be designed to engage at a 90° angle to its target, wiping into position to clear contaminants. Conversely, the IDI connector may be disengaged at that same at any angle, making probe technology the best approach to quick-disconnect applications.

LOW PROFILE, HIGH COMPLIANCE RATIO

IDI's advanced spring contact probe technology permits a very high compliance-to-length ratio. This allows IDI to make connectors as compact as 2 mm, while maintaining 0.5 mm of compliance – low profile connectors have never been so practical or forgiving of mating conditions or vibration.

HIGH FREQUENCY

This short signal path, combined with IDI's industry leading expertise, permits remarkable signal integrity for both analog and digital applications. Speeds of 12 Gb/S and bandwidths of 20 GHz can be achieved with spring probe interposers, and coaxial arrays and contacts can be used to permit excellent isolation.

LOW STABLE RESISTANCE

Through IDI's decades of probe design experience, our connectors feature several innovations for control of DC performance. Advanced biasing techniques provide excellent stability of contact resistance, even under conditions of heavy shock and vibration. Our connectors can be designed to withstand up to 30 Amps of current.

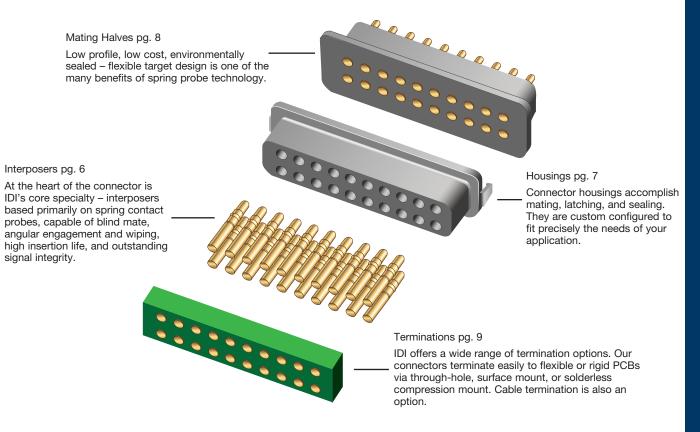
HIGH INSERTION LIFE

Connectors based on spring contact probes are capable of remarkable longevity. Our probes are driven by helical coil springs, which maintain a constant force of contact over millions of cycles. IDI's plating and materials expertise combined with this engineering, delivers contacts that exceed the highest customer specifications for insertion life.

ENVIRONMENTALLY SEALED

IDI's application expertise and the durable nature of our contacts, permits us to design connectors with excellent performance in harsh environments. IP68 and Mil810 requirements can be accommodated without sacrificing performance.

Contact IDI today to find out how we can make your interconnection possible.



Interposers

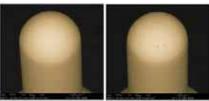
The interposer, or contact array, is the heart of the connector. It is also IDI's specialty – as the world's leading spring contact probe manufacturer we are uniquely positioned to bring the advantages of this contact mechanism to life.

IDI is able to bring our customers the most benefit when providing a total solution, but we can provide our technology at any level. Loose contacts, simple interposers, cabled mating halves, and complex docking solutions are all within our portfolio.

Contact IDI today to find your own unique solution.

INSERTION LIFE

Spring contact probes are driven by helical coil springs. This, combined with IDI's advanced materials and plating expertise, allows us to offer connectors which are capable of hundreds of thousands of insertions. In addition, wiping interconnects can be made to withstand millions of rotations.

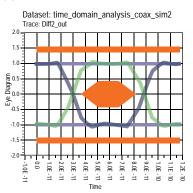


101050 Probe

101050 Probe cycled 50,000 times on a Lifecycle tester

SIGNAL INTEGRITY

Bandwidths of 20 GHz and data rates of 12 Gb/S are possible with simple pin field interposers. This is due to IDI's remarkably short contacts and our expertise in predicting their behavior in application.



Interposers may also be made coaxial through the use of precision-machined insulators and metal interposer bodies. IDI is the inventor of the independent coaxial spring contact probe, featuring a spring-loaded shielding plunger; this may be added to a connector to provide one or more discrete high speed lines.

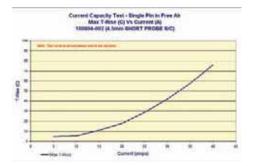
DC STABILITY

Through innovative design features such as our patented Eccentric Drill, IDI's interposers maintain low and consistent contact resistance through their long insertion lives.

Maintaining peak performance through the required life of the interposer requires a careful selection of biasing features. IDI maintains a staff of dedicated experts who can guide you to the optimal contact engine for your application.



Properly specified interposers can withstand the intense shock and vibration associated with aerospace and military applications, maintaining reliable contact without fail even when launched onboard munitions.



IDI's interposers can be designed to take advantage of spring contact probes' surprising current carrying capacity. Individual contacts are capable of handling as much as 30 Amps in free air; combined with IDI's advanced thermal analysis capabilities, connectors can be designed which can handle substantial amounts of power safely.

Housings

ENVIRONMENTAL SEALING

The ruggedness and reliability of spring contact probes make them ideal for applications in harsh environments. IDI's connectors have a wide array of available features which permit sealing to IP68 or Mil standards in either the mated or unmated condition.



Accomplishing a seal while mated is a process of combining gaskets with a latching mechanism reliable enough to prevent ingress, and IDI has several variations on that architecture to draw from.

Creating an unmated seal is more challenging, but IDI is equal to the task. Contacts may be selected which prevent ingress into the housing or even into the spring cavity. IDI's experience is the key to our success – our experts can easily match your requirements to our product line.

QUICK DISCONNECT

IDI capitalizes on the unique engagement of spring contact probes with our innovative quick disconnect connector designs.



Magnets may be used to draw the connector into engagement. This, combined with the blind mate characteristic of probes, allows the connector to be disengaged safely and instantly. Magnetic engagement features almost no wear of the engaging surfaces, and may be mated and demated repeatedly with no degradation in performance.



OTHER FEATURES

Connectors can be created which feature metal housings for shielding. Special latching designs can be employed to overcome significant engagement or sealing forces. Bayonet designs which wipe the contacts across a field of targets are uniquely possible with spring contact probes.



Where magnets are impractical for reasons of engagement force, sealing, or other considerations, IDI can create special latching features which also permit a quick disconnection. These may be designed for a single break or for repeated disengagement, depending on the requirements of the application. Spring contact probes are a flexible, adaptable contact technology, and IDI has extensive experience in creating solutions to unusual problems.

That design agility often finds its application in the housing of the connector, which provides the alignment and latching functions for the connector.

Special features to accommodate environmental sealing, low-force insertion or quick-disconnect extraction, or a host of other requirements are at your disposal.

Contact IDI to find out more about how we can make your application a success.

Mating Halves

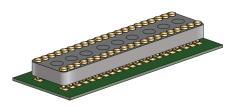
IDI's spring contact probe based connectors have the unique advantage of requiring only a flat pad as their target. This greatly simplifies the design of the complete connector.

The mating halves for our connectors are often customer-created by simply exposing pads on a printed circuit board.

IDI can provide target pins, or can supply a complete mating half which accomplishes alignment and sealing functions.

PCB MATE

Simple gold-plated pads on a printed circuit board are a reliable, easy-to-implement, and very low profile target structure for a spring contact probe based connector; this is also often a nearly zero-cost option for our customers. IDI can provide design guidelines to help our customers easily integrate our mating half into their design.



TARGET PINS

IDI can construct a plastic mating half for the connector with solid metal pins for target contacts. This allows for an extremely robust and repeatable interconnection, and is often a good way to extend the interconnection into the customer's device in a manner which permits sealing and a short Z-axis transfer. A selection of pins is available from IDI for those customers who wish to create their own mating half.

ENVIRONMENTAL SEALING

The mating half of the connector can incorporate features which help to protect the customer's device from the ingress of water and other contaminants. IDI has the experience in sealing target pins, and in providing gaskets and design guidelines to make customer applications safe for harsh environments.



BLIND MATE CAPABILITY

Spring contact probes contact only the surface of their target; they do not engage into the target in the manner of a pin and socket connector. This permits IDI's connectors to mate at up to a 90° angle. Our connectors can rotate after the fashion of brush contacts for millions of cvcles.

Critically, it is difficult to harm a spring probe based connector through mismating, and this makes our connector designs uniquely attractive in blind mate applications.



A spring contact probe requires only a flat pad for its target. It will safely mate to that target if its tip strikes within the target's diameter, and that diameter is only limited by the desired pitch of the connector. A probe-based connector is thus very forgiving of X-Y misalignment; and if the probe strikes off the pad, little harm comes to the connector and it may be safely re-engaged.





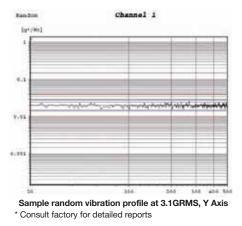
Terminations

COMPRESSION MOUNT

IDI's extensive involvement in the semiconductor test industry provides us with a wellspring of expertise in the creation of spring contact interposers that are compliant from each side.



IDI's compression-mount interposers feature highly developed contact designs. Our contacts, even when used in interposers having thousands of pins, mate faultlessly to their mounting PCB on the first insertion. They retain their excellent electrical characteristics through as much as 58G of shock and 9G RMS of vibration.



IDI's compression mount connectors greatly simplify the manufacturing process, and are often used where space or a path to manufacturing constraints make soldering or cabling prohibitive. By choosing a compression mount contact, users can simply drop the connector into place, assemble the unit, and be assured that all connections will be secure on the first attempt.

PCB TERMINATION

IDI offers two highly refined options for termination by solder to a rigid or flexible printed circuit board. Our thru-hole designs offer a tremendous design flexibility and are ideal for a simple, tooling-free approach to custom connector implementation. IDI's surface mount connectors integrate easily with the modern manufacturing processes, and keep connector profile to a minimum.

Through-hole contacts require no plastic body for the interposer; individual contacts may be populated directly into the PCB and soldered by hand. This is ideal for quick-turn, instantly implemented customized solutions.



Our surface mount contacts are supported by a plastic interposer body. IDI's expertise in press fitting and insert molding contacts guarantees the user a reliable, trouble-free interposer.

CABLE TERMINATION

When termination to cable is desired, IDI offers crimp tails and solder tails for its contacts. IDI is well equipped to supply cabling to meet customer requirements as well. IDI offers termination options that are designed to preserve the many unique advantages of our connectors.

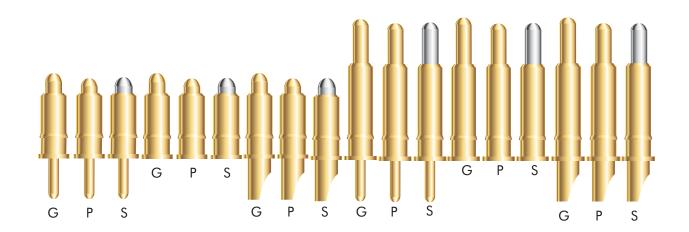
Our highly reliable compression mount technology offers a solderless solution that you can count on; our PCB termination options are refined to ensure manufacturability and keep our profile low; and our cabling options are robust and adaptable.

C Series Connectors

IDI's C Series Connectors ensure a reliable, rugged connection in the harshest environments. Based on our C Series Probe technology, they provide:

- Standard pins offered in custom configurations to meet your applications exact footprint
- 0.100 (2.54) pitch
- Ground, Power & Signal options
- 6mm & 4mm lengths
- Up to 10 amps current rating
- Contact resistance < 10 mΩ typical
- Great for RF, high speed and mixed signal connectors
- Consistently low resistance through tens of thousands of connections
- Ground contacts mate first, break last to support hot swap applications.
- Power contacts probe design supports increased current carrying capacity

- Surface mount, thru hole and solder cup termination options
- Consistent performance throughout broad temperature ranges
- Blind mates
- Superior continuity in high shock and vibration environments
- Minimal insertion and return loss for signals up to 10 GHz
- · Resistance to dust and a range of chemicals
- Ingress protection under the most stringent requirements
- Direction connections for rotating or sliding joints



C-SERIES EXAMPLES

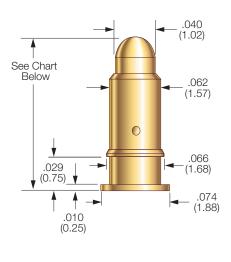


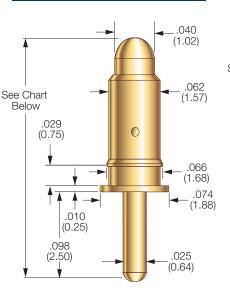
.100 CENTERS C Series Probes

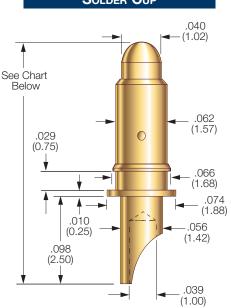
SURFACE MOUNT

THRU HOLE MOUNT

SOLDER CUP







PROBE SPECIFICATIONS

Minimum Centers: .100 (2.54)

Current Rating:

CG Series: 10 amps continuous CP Series: 10 amps continuous

- CS Series: .5 amp continuous
- (Individual probe in free air @ ambient temperature)

Typical Resistances:

CG Series: < 10 mΩ

CP Series: < 10 m Ω CS Series: < 60 m Ω

Spring Force:

3.1 oz. (88g) @ working travel for 4mm compressed length series

2.9 oz. (82g) @ working travel for 6mm compressed length series

Overall Length						
Series	SURFACE Mount	Thru Hole	Solder Cup			
CG-2.5-4	.197 (5.00)	.295 (7.50)	.295 (7.50)			
CG-2.5-6	.335 (8.50)	.433 (11.00)	.433 (11.00)			
CP-2.5-4	.185 (4.70)	.283 (7.20)	.283 (7.20)			
CP-2.5-6	.315 (8.00)	.413 (10.50)	.413 (10.50)			
CS-2.5-4	.185 (4.70)	.283 (7.20)	.283 (7.20)			
CS-2.5-6	.315 (8.00)	.413 (10.50)	.413 (10.50)			

Travel		
Series	Working Travel	Maximum Travel
CG-2.5-4	.039 (1.00)	.039 (1.00)
CG-2.5-6	.098 (2.50)	.098 (2.50)
CP-2.5-4	.028 (0.71)	.028 (0.71)
CP-2.5-6	.079 (2.00)	.079 (2.00)
CS-2.5-4	.028 (0.71)	.028 (0.71)
CS-2.5-6	.079 (2.00)	.079 (2.00)

MATERIALS

Barrel: Brass, gold plated

Spring: Stainless steel

Plunger:

- CG Series: Brass, gold plated
- CP Series: Brass, gold plated
- CS Series: Brass, Duralloy[™] plated

Special Features:

- CG Series: Bias plunger design
- CP Series: Bias plunger design
- CS Series: Standard design

Recommendations:

- Mounting hole: .064/.065 (1.62/1.65) Pad size for Surface Mount: .085 (2.20)
- Wire gage for Solder Cup: 20 gage max.
- Drill size for Thru Hole Tail: .035 (0.89)

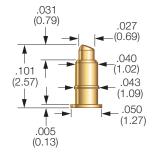
How to Order					
CS	2.5	4	SM		
Series	Рпсн (мм)	Compressed Length (mm)	TERMINATION		
SERIES: CG: Ground Connector Probe CP: Power Connector Probe CS: Signal Connector Probe		4: 4 mm 6: 6 mm	SM: Surface Mount TH: Thru Hole SC: Solder Cup		

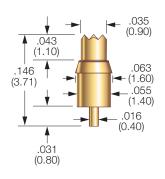
View updates of this information at www.idinet.com

Specifications subject to change without notice. Dimensions in inches (millimeters)

101582 PROBE

101438 PROBE





PROBE SPECIFICATIONS

Minimum Centers: .070 (1.78) .050 (1.27) staggered rows Current Rating: 20 amps continuous (Individual probe in free air @ ambient temperature) Spring Force: 1.7 oz. (48g) @ .030 (0.76) travel Typical Resistance: < 10 mΩ Maximum Travel: .030 (0.76) Working Travel: .030 (0.76)

MATERIALS

Barrel: Brass, gold plated Spring: Stainless steel Plungers: Beryllium copper, gold plated

PROBE SPECIFICATIONS

Minimum Centers: .080 (2.03) Current Rating: 1 amp continuous (Individual probe in free air @ ambient temperature) Spring Force: 3.5 oz. (99g) @ .020 (0.51) travel Typical Resistance: < 10 mΩ Maximum Travel: .039 (0.99) Working Travel: .020 (0.51)

MATERIALS

Barrel: Brass, gold plated Spring: Stainless steel, gold plated Plunger: Beryllium copper, gold plated

How to Order

101582-000

Specifications subject to change without notice. Dimensions in inches (millimeters)

How to ORDER

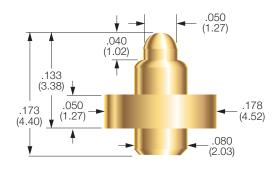
101438-000

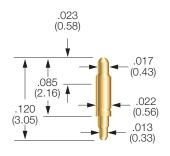
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IDI

100671 PROBE

101111 PROBE





PROBE SPECIFICATIONS

Minimum Centers: .175 (4.45) Current Rating: 3 amps continuous (Individual probe in free air @ ambient temperature) Spring Force: 5.1 oz. (145g) @ .027 (0.69) travel Typical Resistance: < 10 mΩ Maximum Travel: .040 (1.02)* Working Travel: .027 (0.69)

MATERIALS

Barrel: Nickel/silver, gold plated Spring: Stainless steel, gold plated Plunger: Beryllium copper, gold plated

* not recommended for use at maximum travel

How to Order

100671-000

PROBE SPECIFICATIONS

 $\begin{array}{l} \mbox{Minimum Centers: .029 (0.75)} \\ \mbox{Current Rating: 6 amps continuous} \\ (Individual probe in free air @ ambient temperature) \\ \mbox{Spring Force: 1.5 oz. (43g) @ .022 (0.55) travel} \\ \mbox{Typical Resistance: < 50 m} \\ \mbox{Maximum Travel: .025 (0.58)} \\ \mbox{Working Travel: .022 (0.55)} \end{array}$

MATERIALS

Barrel: Phosphor bronze, gold plated Spring: Music wire, gold plated Plunger: Phosphor bronze, gold plated

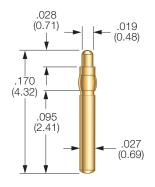
How to Order

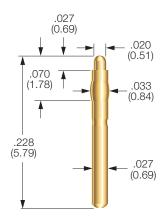
101111-008

Specifications subject to change without notice. Dimensions in inches (millimeters)

101506

101294 PROBE





PROBE SPECIFICATIONS

Minimum Centers: .050 (1.27) Current Rating: 5 amps continuous (Individual probe in free air @ ambient temperature) Spring Force: 1.38 oz. (39g) @ .020 (0.51) travel Typical Resistance: < 20 m Ω Maximum Travel: .028 (0.71) Working Travel: .020 (0.51)

PROBE SPECIFICATIONS

Minimum Centers: .050 (1.27)
Current Rating: 5 amps continuous (Individual probe in free air @ ambient temperature)
Spring Force: 0.9 oz. (26g) @ .020 (0.51) travel
Typical Resistance: < 20 mΩ
Maximum Travel: .027 (0.69)
Working Travel: .020 (0.51)

MATERIALS

Barrel: Nickel/silver, gold plated Spring: Stainless steel, gold plated Plunger: Beryllium copper, gold plated

MATERIALS

Barrel: Nickel/silver, gold plated Spring: Stainless steel, gold plated Plunger: Beryllium copper, gold plated

How to Order

101506-000

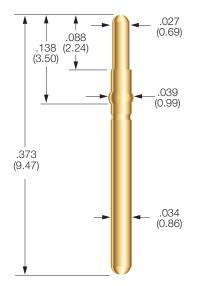
Specifications subject to change without notice. Dimensions in inches (millimeters)

How to Order

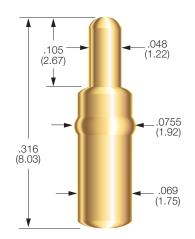
101294-000

IDI

100803 PROBE



101190 PROBE



PROBE SPECIFICATIONS

Minimum Centers: .050 (1.27) Current Rating: 5 amps continuous (Individual probe in free air @ ambient temperature) Spring Force: 1.2 oz. (34g) @ .050 (1.27) travel Typical Resistance: $< 50 \text{ m}\Omega$ Maximum Travel: .060 (1.52) Working Travel: .050 (1.27)

PROBE SPECIFICATIONS

 $\begin{array}{l} \mbox{Minimum Centers: .100 (2.54)} \\ \mbox{Current Rating: 15 amps continuous} \\ (Individual probe in free air @ ambient temperature) \\ \mbox{Spring Force: 2.6 oz. (74g) @ .067 (1.70) travel} \\ \mbox{Typical Resistance: < 6 m} \\ \mbox{Maximum Travel: .100 (2.54)} \\ \mbox{Working Travel: .067 (1.70)} \end{array}$

MATERIALS

Barrel: Nickel/silver, gold plated Spring: Stainless steel, gold plated Plunger: Beryllium copper, gold plated

MATERIALS

Barrel: Nickel/silver, gold plated Spring: Stainless steel Plungers: Beryllium copper, gold plated

How to ORDER

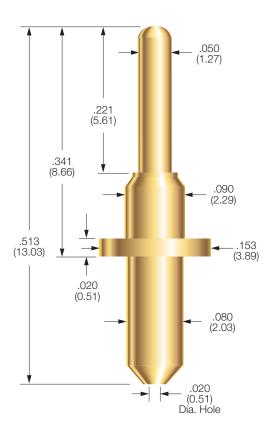
100803-011

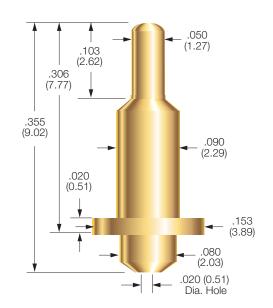
How to Order

101190-002

Specifications subject to change without notice. Dimensions in inches (millimeters)

100606 PROBE





100891 PROBE

PROBE SPECIFICATIONS

Minimum Centers: .175 (4.45) Current Rating: 15 amps continuous (Individual probe in free air @ ambient temperature) Spring Force: 6.2 oz. (176g) @ .060 (1.52) travel Typical Resistance: < 10 mΩ Maximum Travel: .090 (2.29) Working Travel: .060 (1.52)

MATERIALS

Barrel: Nickel/silver, gold plated Spring: Stainless steel, passivated Plunger: Beryllium copper, gold plated Bias Ball: Stainless steel

PROBE SPECIFICATIONS

Minimum Centers: .175 (4.45) Current Rating: 15 amps continuous (Individual probe in free air @ ambient temperature) Spring Force: 9.0 oz. (256g) @ .067 (1.70) travel Typical Resistance: $< 5 m\Omega$ Maximum Travel: .100 (2.54) Working Travel: .067 (1.70)

MATERIALS

Barrel: Nickel/silver, gold plated Spring: Stainless steel, gold plated Plunger: Beryllium copper, gold plated

How to Order

100606-000

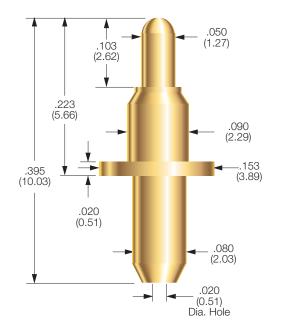
Specifications subject to change without notice. Dimensions in inches (millimeters)

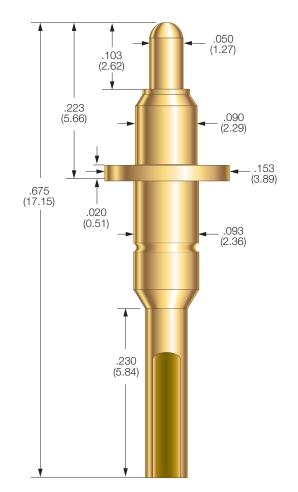
How to Order

100891-002

IDI

100410 PROBE





101119 PROBE

PROBE SPECIFICATIONS

Minimum Centers: .175 (4.45)
Current Rating: 15 amps continuous (Individual probe in free air @ ambient temperature)
Spring Force: 6.2 oz. (176g) @ .060 (1.52) travel
Typical Resistance: < 5 mΩ
Maximum Travel: .090 (2.29)
Working Travel: .060 (1.52)

MATERIALS

Barrel: Nickel/silver, gold plated Spring: Stainless steel Plunger: Beryllium copper, gold plated Bias Ball: Stainless steel

How to Order

100410-005

PROBE SPECIFICATIONS

Minimum Centers: .175 (4.45) Current Rating: 15 amps continuous (Individual probe in free air @ ambient temperature) Spring Force: 6.2 oz. (176g) @ .060 (1.52) travel Typical Resistance: < 10 mΩ Maximum Travel: .090 (2.29) Working Travel: .060 (1.52)

MATERIALS

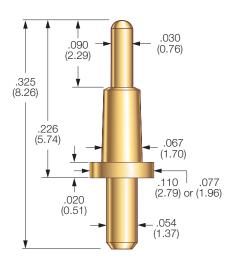
Barrel: Nickel/silver, gold plated Spring: Stainless steel Plunger: Beryllium copper, gold plated Bias Ball: Stainless steel Receptacle: Nickel/silver, gold plated

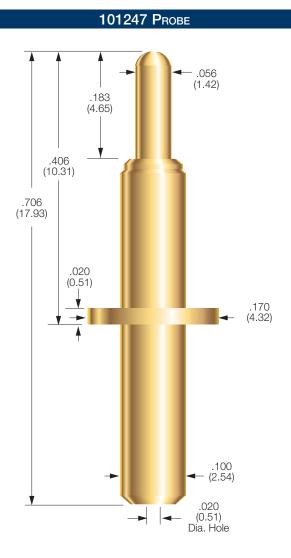
How to Order

101119-001

Specifications subject to change without notice. Dimensions in inches (millimeters)

101050 PROBE





PROBE SPECIFICATIONS

Minimum Centers: .125 (3.18)
Current Rating: 10 amps continuous (Individual probe in free air @ ambient temperature)
Spring Force: 2.3 oz. (65g) @ .060 (1.52) travel
Typical Resistance: < 10 mΩ
Maximum Travel: .090 (2.29)
Working Travel: .060 (1.52)

MATERIALS

Barrel: Nickel/silver, gold plated Spring: Stainless steel, passivated Plunger: Beryllium copper, gold plated Ball: Stainless steel, gold plated

How to Order

101050-003 for .110 dia. flange 101050-005 for .077 dia. flange

Specifications subject to change without notice. Dimensions in inches (millimeters)

PROBE SPECIFICATIONS

 $\begin{array}{l} \mbox{Minimum Centers: .200 (5.08)} \\ \mbox{Current Rating: 20 amps continuous} \\ (Individual probe in free air @ ambient temperature) \\ \mbox{Spring Force: 11.7 oz. (256g) @ .147 (3.73) travel} \\ \mbox{Typical Resistance: < 10 m} \\ \mbox{Maximum Travel: .180 (4.57)} \\ \mbox{Working Travel: .147 (3.73)} \end{array}$

MATERIALS

Barrel: Brass, gold plated Spring: Stainless steel, passivated Plunger: Beryllium copper, gold plated

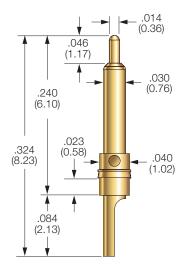
How to Order

101247-001

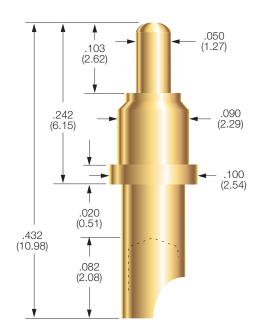
smiths



101679 Ргове



101628 PROBE



PROBE SPECIFICATIONS

Minimum Centers: .055 (1.40)
Current Rating: 3 amps continuous (Individual probe in free air @ ambient temperature)
Spring Force: 1.3 oz. (37g) @ .023 (0.58) travel
Typical Resistance: < 25 mΩ
Maximum Travel: .023 (0.58)
Working Travel: .023 (0.58)

MATERIALS

Barrel: Brass, gold plated Spring: Stainless steel Plunger: Brass, gold plated

How to Order

101679-000

PROBE SPECIFICATIONS

Minimum Centers: .125 (3.18) Current Rating: 25 amps continuous (Individual probe in free air @ ambient temperature) Spring Force: 5.3 oz. (150g) @ .040 (1.02) travel Typical Resistance: $< 5 m\Omega$ Maximum Travel: .040 (1.02) Working Travel: .040 (1.02)

MATERIALS

Barrel: Brass, gold plated Spring: Music wire, nickel plated Plunger: Beryllium copper, gold plated Ball: Stainless steel

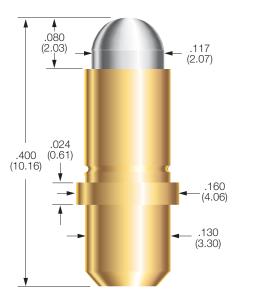
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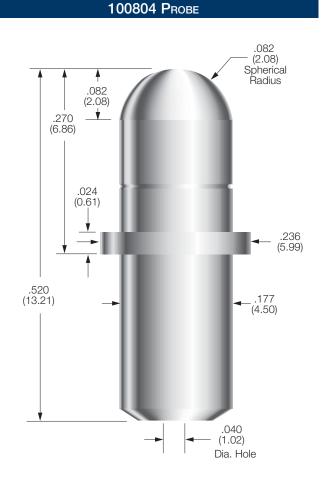
How to Order

101628-000

Specifications subject to change without notice. Dimensions in inches (millimeters)

101402 PROBE





PROBE SPECIFICATIONS

Minimum Centers: .175 (4.45) Current Rating: 20 amps continuous (Individual probe in free air @ ambient temperature) Spring Force: 9.7 oz. (275g) @ .050 (1.27) travel Typical Resistance: < 10 mΩ Maximum Travel: .080 (2.03) Working Travel: .050 (1.27)

MATERIALS

Barrel: Nickel silver, gold plated Spring: Stainless steel, passivated Plunger: Brass, Duralloy[™]

PROBE SPECIFICATIONS

Minimum Centers: .250 (6.35) Current Rating: 30 amps continuous (Individual probe in free air @ ambient temperature) Spring Force: 8.9 oz. (252g) @ .054 (1.37) travel Typical Resistance: < 5 mΩ Maximum Travel: .082 (2.08) Working Travel: .054 (1.37)

MATERIALS

Barrel: Brass, Duralloy[™] plated Spring: Stainless steel, passivated Plunger: Brass, Duralloy[™] plated

How to Order

101402-000

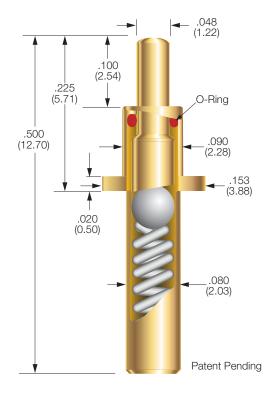
smiths

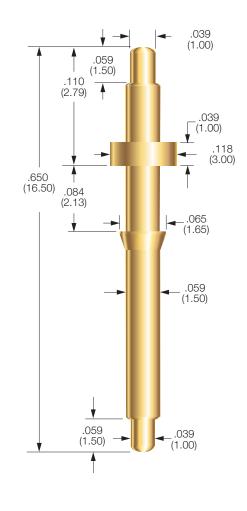
Specifications subject to change without notice. Dimensions in inches (millimeters)

How to Order

100804-002

101602 Environmentally Sealed Probe





101549 PROBE

PROBE SPECIFICATIONS

Minimum Centers: .175 (4.44) Current Rating: 10 amps with 80° C rise (Individual probe in free air @ ambient temperature) Typical Resistance: < 10 mΩ Spring Force: 6.7 oz. (190 g) @ .070 (1.77) travel Maximum Travel: .100 (2.54) Working Travel: .070 (1.77)

MATERIALS

Barrel: Nickel silver, gold plated Plunger: Full-hard beryllium copper, gold plated Spring: Stainless steel Bias Ball: Stainless steel O-ring: Silicone Cap & Plug: Stainless steel, gold plated

How to Order

101602-000

PROBE SPECIFICATIONS

Minimum Centers: .125 (3.18)
Current Rating: 3 amps with 80° C rise (Individual probe in free air @ ambient temperature)
Typical Resistance: < 50 mΩ
Spring Force: 3.5 oz. (100 g) @ .039 (1.00) travel, each end
Maximum Travel: .059 (1.50) travel, each end
Working Travel: .039 (1.00) travel, each end

MATERIALS

Barrel: Nickel silver, gold plated Plunger: Full-hard beryllium copper, gold plated Spring: Stainless steel

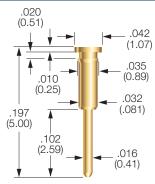
How to Order

101549-000

Specifications subject to change without notice. Dimensions in inches (millimeters)

Target Contact

PI-5328



PIN SPECIFICATIONS

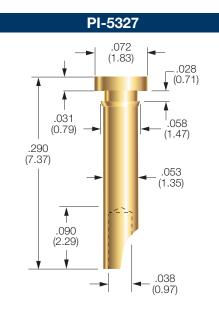
Mounting Hole: .034 (0.86)

MATERIALS

Material: Brass Plating: Gold over nickel

How to ORDER

PI-5328



PIN SPECIFICATIONS

Mounting Hole: .057 (1.45)

MATERIALS

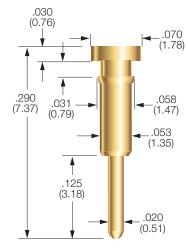
Material: Brass Plating: Gold over nickel

How to ORDER

PI-5327

Specifications subject to change without notice. Dimensions in inches (millimeters)

PI-5329



PIN SPECIFICATIONS

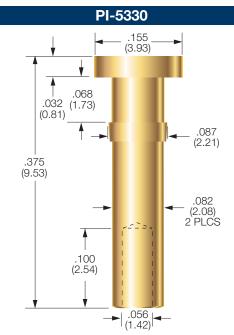
Mounting Hole: .057 (1.45)

MATERIALS

Material: Brass Plating: Gold over nickel

How to ORDER

PI-5329



PIN SPECIFICATIONS

Mounting Hole: .084 (2.15)

MATERIALS

Material: Brass Plating: Gold over nickel

How to ORDER

PI-5330



Page

TEST SOCKETS AND PROBES Semiconductor

HIGH PERFORMANCE TEST SOCKETS

IDI provides a variety of high-performance test sockets and lids to meet virtually any lab, system level or ATE requirement for analog, power and logic devices.

All of our products share the same standard features such as best-in-class materials, field replaceable interconnects and unsurpassed quality in design and manufacturing. IDI test sockets and lids are custom designed and manufactured to meet your specific application.

We work closely with you to fully understand your needs. Our engineers time and time again have proven the ability to rapidly develop comprehensive solutions that far exceed your expectations and continually outperform other competitive products.

SYNERGETIX BRAND TEST SOCKETS

Synergetix brand test sockets have utilized IDI's three piece probe design. This innovation allowed the base resistance to be dramatically reduced and more importantly, introduced a truly consistent spring probe design that is considered to be the industry standard. IDI has continued our innovations throughout the years by introducing many new test socket designs in our Synergetix brand including the Dyno test socket for QFN devices, the Offset Kelvin Socket for 0.5mm QFN devices and Wafer Level CSP sockets.

ANTARES BRAND TEST SOCKETS

In 2009, IDI acquired the Antares brand test sockets. Antares has offered test socket solutions for over 25 years. Antares brand test sockets offer some of the most complex designs including PoP test sockets, impedance controlled test sockets, elastomer test sockets and thermal management solutions as well as conventional test sockets. The design process used for Antares and Synergetix brand test sockets, is automated from a computer aided design process that includes 3D electrical and mechanical modeling. Our engineers are well versed in mechanical and thermal FEA and signal integrity simulation.

IDI has Sales and Application Engineering support located throughout US, Asia and Europe, providing 24/7 service and support.



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Family Sockets

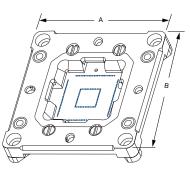
Applying standard designs to IDI sockets and lids allows for expedited design and delivery of our products. By utilizing design templates, socket and lid drawings for specific packages can be quickly completed and the components procured allowing for improved delivery cycles. Applying the IDI family standards will allow designs to have the same dimensioning features and overall look among multiple packages.

PERIPHERAL FAMILY SOCKETS

Peripheral family standard sockets include an alignment ring. Designing the socket with an alignment ring allows replacement of the alignment features without replacing the entire socket.

- Sockets are configurable with any portfolio spring pin, at any pitch.
- Socket frames are made from aluminium, thus eliminating or reducing the amount of bowing that occurs in high pin count socket applications.
- Sockets are designed with the maximum component clearance and are top mounted for easy removal. Bottom mount is available upon request.

PERIPHERAL FAMILY SOCKETS



FAMILY SERIES - DEVICE SIDE					
Family	Min	Max*	DIM A	DIM B	
1	3mm	6mm	29.50 (1.16)	29.50 (1.16)	
2	6mm	10mm	34.00 (1.34)	34.00 (1.34)	
3	10mm	17mm	39.50 (1.55)	39.50 (1.55)	

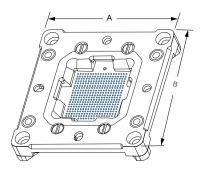
* not inclusive

ARRAY FAMILY SOCKETS

Array standard family sockets can be configured with either a floating base or non-floating base design.

- Sockets are configurable with any portfolio spring pin, at any pitch.
- Socket frames are made from aluminum, thus eliminating or reducing the amount of bowing that occurs in high pin count socket applications.
- Sockets are designed with maximum component clearance and are top mount for easy removal. Bottom mount is available upon request.

ARRAY FAMILY SOCKETS



FAMILY SERIES - DEVICE SIDE							
Family	Min	Max*	DIM A	DIM B			
1	3mm	6mm	29.50 (1.16)	29.50 (1.16)			
2	6mm	10mm	34.00 (1.34)	34.00 (1.34)			
3	10mm	17mm	39.50 (1.55)	39.50 (1.55)			
4	17mm	25mm	48.00 (1.89)	48.00 (1.89)			
5	25mm	32mm	55.00 (2.16)	55.00 (2.16)			
6	32mm	40mm	65.00 (2.56)	65.00 (2.56)			
7	40mm	50mm	75.00 (2.95)	75.00 (2.95)			

* not inclusive



Specifications subject to change without notice. Dimensions in millimeters (inches)

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Family Lids and Footprints

IDI offers two styles of lids for our family sockets, clamping and clamshell. Each family socket has a footprint drawing available on-line for immediate download.

FAMILY SOCKET LIDS

- Lids are top mounted to allow more component clearance surrounding the socket.
- Top mounted lid frames include clearance holes, allowing the sockets to be installed and removed from the PCB without removing the lid.
- Standard lids are configurable, thus allowing the addition of heatsinks and fans to existing designs.
- Lids are adjustable to cover a wide range of package thicknesses.
- Lever is optional.

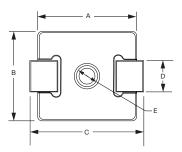
FAMILY SOCKET FOOTPRINTS

• Family socket footprints are available for download on our web site:

www.idinet.com/arrayfp.aspx

www.idinet.com/peripheralfp.aspx

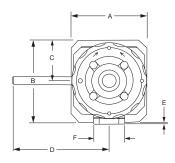
CLAMPING FAMILY LIDS



CLAMPING FAMILY LIDS						
Family	Min	Max*	DIM A	DIM B		
1	3mm	6mm	33.00 (1.29)	29.50 (1.16)		
2	6mm	10mm	37.50 (1.47)	34.00 (1.34)		
3	10mm	17mm	43.00 (1.55)	39.50 (1.55)		

* not inclusive

CLAMSHELL FAMILY LIDS



CLAMSHELL FAMILY LIDS							
Family	Min	Max*	DIM A	DIM B			
1	3mm	6mm	29.50 (1.16)	32.80 (1.29)			
2	6mm	10mm	34.00 (1.34)	37.30 (1.49)			
3	10mm	17mm	39.50 (1.55)	42.80 (1.68)			
4	17mm	25mm	48.00 (1.89)	51.85 (2.041)			
5	25mm	32mm	55.00 (2.16)	59.35 (2.33)			
6	32mm	40mm	65.00 (2.56)	69.00 (2.71)			
7	40mm	50mm	75.00 (2.95)	79.00 (3.11)			

* not inclusive

Standard Sockets

IDI is the leading manufacturer of High Performance Test Sockets used for virtually any package and for wafer level CSP test. Socket designs utilize our IDI's proprietary spring probe and/or the patent pending Dyno™ contact technology. IDI test sockets are ideal for lead free device test and provides high cycle life, consistent contact resistance, and bandwidths greater than 10 GHz.

For over three decades, IDI has led the industry in innovation. This assures you that when you

purchase an IDI test socket, you are using the most advanced interconnect available for semiconductor



test. Our design approach is application specific to optimize the performance, reliability and cost effectiveness.

CSP, BGA AND LGA TEST SOCKETS

IDI's high performance CSP, BGA and LGA test sockets offer high bandwidths, consistently low resistance and low inductance for your high performance testing requirements. We employ spring probes and other alternate contact technologies in a fixed or a floating nest test socket design that best meets the requirements of your specific test application.

PACKAGE ON PACKAGE TEST SOCKET

Our PoP test sockets for years have been providing reliable solutions for both manual and automated testing of package-on-package (PoP) devices. The unique ability of our

PoP test sockets to accurately and simultaneously align both the upper and lower device leads increases the versatility and lowers the cost of test.



IMPEDANCE CONTROLLED TEST SOCKETS

IDI brings new innovative solutions to IC testing using spring probes. Our high performance and impedance controlled test sockets have a true controlled impedance which achieves a high bandwidth performance (27GHz @ -1dB) that high speed applications and RF require.

WAFER LEVEL CSP TEST INTERPOSERS

IDI is changing the face of wafer level chip scale testing as more companies move towards bare die testing. Our interposers are

being used in vertical probe test applications at a much lower cost,



with a faster delivery cycle than the typical probe card solutions. IDI's interposers utilizes spring probe technology allowing for high cycle life, stable performance, reduced testing downtime and the ease of maintenance.

QFN TEST SOCKETS



IDI's innovative new leadless device test solution is the patented Dyno Test Socket. The Dyno utilizes a monolithic contact that boasts of a mechanical life in excess of 500,000 cycles and requires minimal cleaning. The typical resistance is less than 20 m Ω against both matte tin and NiPdAu. There is minimal board scrubbing, yet a slight wiping action on the device side for penetration of any contaminants and oxides on the device. The Dyno footprint is compatible with most all competitive offset designs.

MULTI-SITE TEST SOCKETS

Our Multi-Site test sockets include strip test sockets, wafer level test sockets and multiple position, singulated device test sockets. Our multi-site test sockets are available with interchangeable inserts and a large socket frame for the ultimate in adaptability.

QFN KELVIN TEST SOCKETS

IDI's has developed an innovative and robust contact technology for making Kelvin contact to 0.5mm pitch QFNs. The contact uses a tip that is angled to one side and flat. Two such contacts placed in opposition will touch the pad within 0.125mm. The tip is offset making the probe diameter a robust 0.39mm which allows the load board pad pitch to remain at 0.5mm.

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For handler setup or hand test, a manual lid is often required as part of the test hardware set. We have refined our own standard offerings so that with each socket you can receive a lid that is designed for your specific application from one of five standard lid form factors. The most basic function of a test socket lid is to provide mechanical stability that helps form a strong mechanical and electrical connection between the leads of the device under test and the test socket contacts.

Our design approach for lids is the same as our approach to sockets; application specific to optimize the performance, the reliability and the cost effectiveness.

In order to guarantee that the lid design meets your application requirements we offer a variety of options for our lids including:

- Multiple plunger configurations
- Spring loaded latches
- Thermal stream access holes
- Liquid heatsinks
- Passive heatsinks
- Heat dissipating fans

CLAMSHELL LID

Clamshell Lids are used primarily in manual test applications. These lids provide an easy-to-use solution for repetitive cycling. Our innovative controlled travel design permits virtually effortless actuation and adjusts to accommodate a wide range of device thicknesses.



The Clip-On Lid design has been given a new body to provide a user friendly solution while offering the same quick turn around, which is often a key requirement in handler setup hardware.

Standard Lids

VCC LID

The Vertical Compression Clamshell Lid

(VCC), is a clamshell lid without secondary actuation. Numerous customers prefer the convenience of pushing the device into the pocket with a single actuation. The



VCC's unique design offers natural linear compression of the device.

FAILURE ANALYSIS ONE-PIECE-BOLT-ON LID

One-Piece Bolt-On Lids are one of the most straightforward style of manual

lid. When test times are long and the price is the primary driver, this can be the optimal solution.



INTEGRAL LID

Integral Lid solutions are permanently attached to the socket and offer a more simplistic approach to low end test.



CLIP-ON LID OR CLAMPING LID

The Clip-On Lid design has been given a new body to provide a user friendly solution while offering the same quick turn around, which is often a key requirement in handler setup hardware.



yno[™] Test Sockets for QFN Devices

IDI's patented Dyno[™] Test Sockets for QFN testing, has significant advantages over any competitive technology.

- Self-cleaning contact design
- The Dyno footprint is compatible with most all competitive offset designs.
- Unmatched reliability
- Fast delivery time

The Dyno[™] Test Socket employs an innovative contact design that slightly wipes across the surface of the device lead during compression. This ensures low and consistent contact resistance and high first pass yields in even the harshest and most demanding applications.

DESIGNED FOR EFFICIENCY

The Dyno[™] contact is a monolithic element which derives compliance to the load board from a simple elastomeric rod and device compliance from a painstakingly crafted contact bending effect. The Dyno boasts of a mechanical life in excess of 500,000 cycles and requires minimal cleaning with little fatigue.

Because the contact tip scrubs across the device lead with each compression, contaminants and tin oxides are wiped from both the lead and the contact surface, ensuring a low and consistent resistance and high yields throughout the contact's life. Minimal cleaning is required, and the user can expect the contact to deliver cycle after cycle with little attention.

THE ENDURA ADVANTAGE

The Dyno contact is a beryllium copper shaped metal, contact featuring IDI's Endura plating. This proprietary plating provides a contact surface that is more resistant to debris build up in lead free device testing.

DYNO CONTACTS AND PROBES IN A SINGLE SOCKET

The Dyno contact is designed to be compatible with the Synergetix flagship, the 3-piece probe. The peripheral leads on the QFN can be tested with the Dyno contact and the ground pad in the center of the device can utilize our 101267 probe. Depending on package and ground pad site, Dyno contacts can be used on center ground pads as well.

A LONG-LASTING TEST SOCKET

The Dyno Test Socket requires a minimal amount of cleaning and has mechanical life of over 500,000 cycles. Its unique design provides a slight wiping action on the device to penetrate contaminants and oxides on the hard, lead-free surfaces. Because compliance to the load board is derived from the elastomer and isolated from the movement of the contact tip, board scrub is minimized and board pad life should be relatively infinite.

EASY CONTACT REPLACEMENT

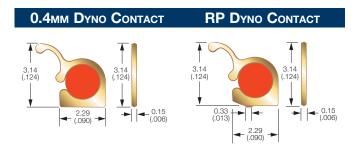
With a cycle life well in excess of 500,000 insertions, the Dyno contact and silicone elastomer do not require frequent refurbishment. However, should the need arise both items are field replaceable with relative ease. The Dyno contacts can be individually replaced.

THE DYNO DIFFERENCE

Only IDI has the Dyno contact – a revolutionary breakthrough in High-Performance QFN testing.

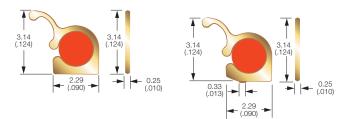
- Patented design
- Resistance < 20 mΩ against a matte-tin device
- Bandwidths > 10GHz @ -1dB on 0.50mm pitch
- Mechanical life >500,000 cycles
- Endura plating resists solder build-up
- Wiping action ensures good device contact with minimal board side scrub
- Requires minimal cleaning





0.5MM DYNO CONTACT

RP DYNO CONTACT



SPECIFICATIONS

Minimum Device Pitch: 0.40mm (.016) Test Height: 2.92mm (.115) Force per Contact: 42g (1.5 oz.) @ 0.38mm (.015) travel for RP 51g (1.8 oz.) @ 0.38mm (.015) travel Device Compliance: 0.23mm (.009) DUT Board Compliance: 0.15mm (.006) Operating Temperature: -55°C to 150°C Insertions: > 500,000

MATERIALS

Contact: Full-hard beryllium copper, Endura plated Insulator: Silicone

ELECTRICAL SPECIFICATIONS

Typical Resistance: $< 20 \text{ m}\Omega$ Current Carrying Capacity: 5 amps continuous (Current DC carry capability @ 80° C steady state) Pattern 2a: 3 3 at 0.4mm pitch Characteristic Impedance: 34Ω Time Delay: 37 pSecLoop Inductance: 1.51 nHSignal Pin to Return Capacitance: 0.90 pF-1dB Insertion Loss Bandwidth: >10 GHz

SPECIFICATIONS

Minimum Device Pitch: 0.50mm (.020) Test Height: 2.92mm (.115) Force per Contact: 52g (1.8 oz.) @ 0.38mm (.015) travel for RP 85g (3.0 oz.) @ 0.38mm (.015) travel Device Compliance: 0.23mm (.009) DUT Board Compliance: 0.15mm (.006) Operating Temperature: -55°C to 150°C Insertions: >500,000

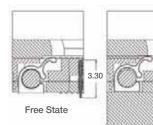
MATERIALS

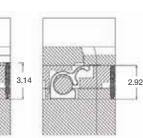
Contact: Full-hard beryllium copper, Endura plated Insulator: Silicone

ELECTRICAL SPECIFICATIONS

Typical Resistance: $< 20 \text{ m}\Omega$ Current Carrying Capacity: 5 amps continuous (Current DC carry capability @ 80° C steady state) Pattern 2a: 3 3 at 0.5mm pitch Characteristic Impedance: 34Ω Time Delay: 48 pSecLoop Inductance: 1.74 nHSignal Pin to Return Capacitance: 1.34 pF-1dB Insertion Loss Bandwidth: >10 GHz

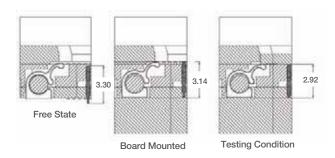
TESTING CONDITION





Board Mounted Testing Condition

TESTING CONDITION



Specifications subject to change without notice. Dimensions in millimeters (inches)

PoP Sockets

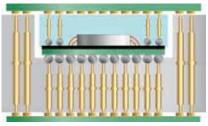
IDI's Antares brand PoP test sockets for years have been providing reliable solutions for both the manual and automated testing of package-on-package devices. Our PoP test sockets accurately and simultaneously align both the upper and lower device pads and leads which increases versatility and lowers the cost of test.



IDI Offers three distinct types of PoP sockets designs to meet your specific requirements.

MEMORY-LESS

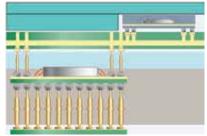
Memory-Less (ML) PoP Socket – top and bottom access to leads on devices with memory information supplied from the tester thru the socket assembly.



MEMORY-LESS

MEMORY-BEARING

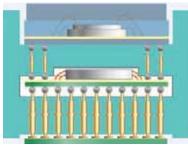
Memory-Bearing (MB) PoP Socket – top and bottom access to leads on devices with a known good memory device that is contained within the socket assembly providing a temporary connection to the PoP device test.



MEMORY-BEARING

MANUAL TEST

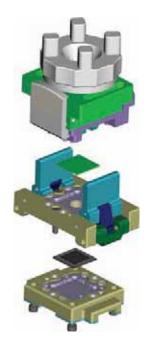
Manual Test (MT) PoP Socket – top and bottom access to leads on devices with a known good memory device contained within the lid assembly providing a temporary connection to the PoP device test.



MANUAL TEST

POP TEST SOCKETS

- Proven design over two years in the field
- Reliable alignment to the top and bottom leads
- Superior Signal Integrity to both packages
- Interface bandwidths to 10 GHz
- 0.40mm pitch & above production ready solutions
- 0.25mm pitch is in development



WLCSP Test Sockets

IDI's interposers are revolutionizing the testing of wafer-level chip scale packages (WLCSP) in vertical probing applications. Test engineers are realizing tremendous savings in cost of ownership as IDI delivers a highly reliable, easily maintained, and eminently capable solution for this rapidly emerging form of test. Where engineers were previously required to use expensive and difficult to maintain vertical probing solutions, IDI interposers can:

- Be implemented at a fraction of the initial cost and lead time as compared to most traditional technologies.
- Produce a radical improvement in maintenance downtime and contact life.

REMARKABLY LOW COST OF OWNERSHIP

IDI sockets for production test of packaged devices are well known for their extreme durability and ease of maintenance. Now, IDI brings this same degree of ease to the wafer probing level.

An IDI WLCSP interposer solution is typically less than 20% of the cost of a comparably effective vertical probing card.

IDI's WLSCP interposers have a low cost of ownership that begins with their initial cost. The interposer is a simple plastic assembly that contains IDI's proven semiconductor probe technology. This is combined with an easy-to-design and fabricated load board.

The savings continue as the WLSCP interposer is put into action. IDI's spring probe technology provides more than 300 microns travel, therefore allowing for easy probe set-up and forgiving performance cycle after cycle.

FAST DELIVERY TIME

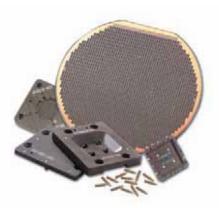
Delivery times are greatly reduced on the WLCSP interposers as well. IDI designs its interposers within a week and ships within three weeks – a fraction of the lead time that is associated with vertical probe card technologies.

A LONG LASTING INTERPOSER SOLUTION

IDI WLCSP interposers run long and hard, with minimal attention required. They are easily maintained by the test technician with little tooling or training. Their resulting minimal downtime combined with their fractional initial investment equals a far lower cost of ownership than any other vertical probing solution available.

EFFORTLESS CLEANING & MAINTENANCE

Recommended off-line cleaning techniques take only minutes, and in many cases the interposer may be left attached to the load board. Online cleaning can be done depending on the medium used. When contact replacement is required, it may be done at the test technician level with tools no more complex than tweezers and a screwdriver.



Modeling and Analysis

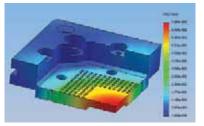
In more complex socket designs, it is often necessary to model the socket's performance to guarantee that the socket design is mechanically robust while delivering virtually transparent signal paths.

STRUCTURAL FINITE ELEMENT ANALYSIS

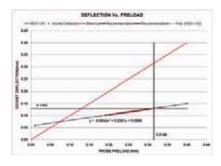
Determines the yield failure due to pin array and lid force, as well as socket deflection at the pin array.

THERMAL FEA

Determines power dissipation from the package. Steady State Analysis is performed.



SPRING PROBE TRAVEL ANALYSIS



<u>Preload – Level</u> 1 - The Monte Carlo analysis verifies the spring probe is always in contact with the load board when mounted. This analysis assumes a constant socket deflection.

<u>Preload – Level 2</u> - Analysis is typically required for higher pin count sockets. It uses variable socket deflection based on additional structural FEA.

<u>Preload – Level 3</u> - This level adds a lid travel analysis.

<u>Compression</u> - Monte Carlo analysis optimizes spring life, contact life, CRES and force.

Post Preload Compression - Monte Carlo analysis checks for continuity and pin bottoming in socket.

CONTACTOR ALIGNMENT ANALYSIS

<u>Alignment to Load Board</u> - Analysis checks the dowel pin's size and position.

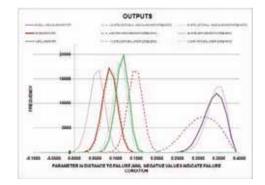
Spring Probe to Load Board - Monte Carlo analysis checks the probe contact to load board pad alignment.

<u>DUT Into IC Pocket Fit</u> - Analysis checks that the min/max package body against the IC pocket.

Spring Probe to DUT - Monte Carlo analysis method checks the DUT to top contact alignment.

Package Damage due to Misalignment -Monte Carlo analysis checks for ball or pin shear.

Alignment with CTE Considerations -Monte Carlo analysis checks the CTE of each material in the specific test temperature environment.



Lid Alignment - Platen to IC Pocket -Prevent damage to IC pocket walls. Heatsink to Die - Prevent die cracking

DUT/LID/Heatsink Travel - Analysis for DUT force balance. Force balancing for PoP systems - substrate and die. Prevents damage to package or die.

<u>Handler Alignment</u> - Handler placement and positional accuracy into IC pocket. Package theta rotational accuracy.

Spring Probe Pointing Accuracy -Prevents damage to spring probe tip and to the load board pads.

smiths

Socket Cleaning

IDI recommends cleaning sockets on either as needed or per cycle basis for regular maintenance.

Generally, the most effective cycle for cleaning of sockets can be determined by tracking test yields, and establishing a maintenance schedule based on when they begin to fall measurably below the acceptable performance level.

ACETONE CLEANING SOCKET MOUNTED ON BOARD

- 1. Visually inspect socket and probes for contamination, particles, scratches, etc.
- 2. Blow filtered air or inert gas on the surfaces to remove all loose particles of contaminations.
- 3. If contaminants still exist, apply the acetone to a soft bristle brush or soft pad to clean the surfaces. Blow filtered air or inert gas on socket and probe to remove solvent and any contaminants.
- 4. If contaminants are still present, the socket should be removed from the board to perform offline cleaning.

ACETONE CLEANING - SOCKET REMOVED FROM BOARD

- 1. Dismantle the socket; remove the bottom retainer plate and all the probes from the socket.
- 2. Place socket parts in one glass beaker and probes in a separate glass beaker containing the acetone, IPA or methanol. All parts should be submersed in the liquid.
- 3. Place the glass beakers in the ultrasonic cleaner cleaning the parts for a minimum of 30 minutes.
- 4. Remove all the parts individually from the ultrasonic bath and place on a white absorbent paper.
- 5. Use a nylon hog hair or horse tail brush to remove any left over contaminants on the socket parts.

 Place the socket and/or probes in a beaker or other oven suitable container; place in a pre-heated oven at 60°C for 30 minutes to dry all parts. (This process must

be performed for IPA or methanol cleaned parts. Acetone cleaned parts must be



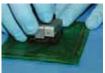
dried with clean compressed air only (30psi); no oven drying).

7. Reassemble socket.

IDI CLEANING KITS - SOCKET REMOVED FROM THE BOARD

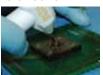
- 1. Remove socket and load board from the tester and place both on a clean work surface (do not remove socket from load board if possible).
- 2. If a floating nest is included in your socket's design, remove the nest and set it aside. Be sure to retain the springs which drive the floating nest.
- If the socket is removed from the load board, you must compress the board-side tips of the probes. Use a flat instrument. This will cause the probe tips to project from the top surface of the socket, allowing for easier and more effective cleaning.
- 4. Trim the pre-saturated cleaning cloth with scissors to the size of the pocket and place in pocket; if the device is larger than the cloth, multiple cloths may be overlaid.
- 5. Place the sacrificial device in the pocket over the cloth and attach the lid to the socket.
- 6. Turn the socket lid handle to the test position and allow to soak. Longer soak times have proven to be the most effective; soak for a minimum of one minute.





Longer soak times will not hurt the socket performance; the cleaning agent continues to remove solder and oxides as long as the cloth is in place.

- If a socket lid is not available, cycle the device 10 times over the cloth. Allow the cloth to remain in place over the device for the recommended soak time, then cycle the device 10 more times.
- 8. After completion, remove the device and the cleaning cloth from the socket pocket. Discard cleaning cloth after each use.
- 9. Remove rotary tool from the kit and insert the nylon brush tip into the tool.
- 10. Approach the probe tips at a 30° angle with the rotary tool brush, and apply light pressure.
- 11. Actuate the rotary tool and work slowly across the probe tips in a sweeping manner working left to right (work in one direction only).
- 12. Rotate socket 90° and repeat.



13. Visually inspect probe tips to

ensure tin removal. Repeat as necessary to loosen stubborn deposits.

- 14. The nylon hand brush tool may be used to remove any loose particles remaining on the socket.
- 15. Do not rinse the socket; the chemical left on the socket by the cloth is safe for the device and will help to limit any further contamination.
 - Use safety goggles and latex gloves during the cleaning
 - Preserve cleaning kit; rinse nylon brushes with isopropyl alcohol (IPA) after each cleaning. Allow IPA to evaporate from the brush bristles before using.
 - Keep the saturated cleaning cloth in a closed package when not in use for maximum life.

Homogeneous Probes

IDI's spring test probe designs combine conductivity and rigidity to form a reliable electrical path with excellent force distribution and compliance. Mechanical probe tip designs can be varied at each end of the contact to provide the absolute best socket-to-package and socket-to-PCB interconnection.

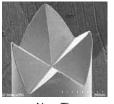
Tips styles can also be designed for specific applications to optimize contact surface area while minimizing contact wear factors, as well as lead and solder ball deformation. Elements can be scaled and materials chosen to produce a contact that optimizes performance for high-speed signals, or for high or low power requirements. Scaling also allows the design and production of spring probes to meet high pin-count and tight pitch requirements.

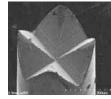
The homogeneous probe series features device contact tips made from custom developed solid precious metal alloy, usable without an additional plating process. This method of construction offers a more robust structure that is capable of withstanding the extreme cleaning techniques associated with the testing of SAC-105 BGA and NiPdAu QFN packages. Measured against typical contact materials, this alloy offers less wear than beryllium copper, increased hardness and superior electrical conductivity compared to carbon steel.

HOMOGENEOUS PROBE ADVANTAGES

- In-Situ Cycle Life in excess of 800K
- Improved test yields up to 80% increase in FPY vs. standard product
- Increased "uptime"
- Low and stable contact resistance
- Drop-in replacement for standard IDI – Antares & Synergetix probes
- · Available for all pitches 0.4mm and higher

CHARACTERISTICS					
Material	Conductivity % IACS	Hardness HV			
Beryllium Copper	25%	HV360			
Carbon Steel	-9%	HV620			
Homogeneous	15%	HV450			





New Tip

Clean and Sharp After 400K Cycles

Semiconductor Probe Table of Contents							
Base Part No.	Pitch	Length	-1 dB Insertion Loss Bandwidth	Loop Inductance	Homogeneous Option	Page	
101500	0.50mm	5.74mm or 6.74mm	-	—	No	35	
101245	0.50mm	5.74mm	> 14.6 GHz	1.6nH	No	35	
101303	0.40mm	3.30mm	> 20.0 GHz	1.02nH	No	36	
101795	0.40mm	3.30mm	> 20.0 GHz	1.02nH	Yes	36	
623-0286	0.40mm	3.30mm	> 17.5 GHz	0.98nH	Yes	37	
623-0334	0.40mm	3.80mm	> 15.4 GHz	1.01nH	Yes	37	
200-000940	0.40mm	4.75mm	> 20 GHz	0.95nH	Yes	38	
623-0248	0.40mm	5.44mm to 5.64mm	> 13.2 GHz	1.38nH	Yes	38	
623-0249	0.50mm	2.87mm	> 20 GHz	0.89nH	Yes	39	
623-0290	0.50mm	5.16mm	> 9.6 GHz	1.19nH	Yes	39	
101267	0.50mm	3.30mm	> 20 GHz	1.12nH	No	40	
623-0326	0.50mm	3.30mm	> 20 GHz	1.12nH	Yes	40	
623-0047	0.50mm	5.99mm	> 20 GHz	1.56nH	Yes	41	
623-0303	0.65mm	3.70mm	> 20 GHz	0.85nH	Yes	41	
100938	0.65mm	5.72mm	> 2.4 GHz	1.46nH	No	42	
623-0270	0.80mm	2.65mm	> 20 GHz	0.59nH	Yes	42	
623-0271	0.80mm	2.65mm	> 20 GHz	0.72nH	No	43	
623-0195	0.80mm	4.84mm	> 20 GHz	0.86nH	Yes	43	
101785	0.80mm	5.94mm	> 10 GHz	1.03nH	No	44	
101312	1.00mm	7.37mm	> 10 GHz	1.19nH	No	44	
623-0117	1.00mm	4.75mm	> 20 GHz	1.02nH	No	45	
100785	1.27mm	10.72mm	> 16.2 GHz	1.93nH	No	45	

Specifications subject to change without notice. Dimensions in millimeters (inches)

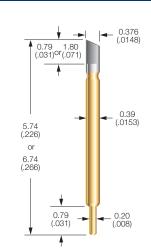
34



Offset Kelvin Test Probes

101500 KELVIN TEST PROBE





PROBE SPECIFICATIONS

Minimum Device Pitch: 0.50mm (.020) Signal Path Length: 5.26mm (.207) for 101500-000 6.26mm (.247) for 101500-001 Spring Force per Contact: 35g (1.25 oz.) @ 0.48mm (.019) travel Device Compliance: 0.33mm (.013) DUT Board Compliance: 0.15mm (.006) Operating Temperature: -55°C to 150°C Insertions: > 500,000

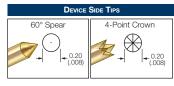
MATERIALS

Barrel: Phosphorus Bronze, gold plated
Spring: Stainless steel, gold plated
Device Side Contact: Stainless steel, palladium cobalt plated
Board Side Plunger: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

Typical Resistance: < 100 mΩ Current Carrying Capacity: 3 amps continuous (Current DC carry capability @ 80° C steady state)

101245 GROUND PROBE





PROBE SPECIFICATIONS

Minimum Device Pitch: 0.50mm (.020) Signal Path Length: 5.26mm (.207) Force per Contact: 35g (1.25 oz.) @ 0.48mm (.019) travel Device Compliance: 0.33mm (.013) DUT Board Compliance: 0.15mm (.006) Operating Temperature: -55°C to 150°C Insertions: > 500,000

MATERIALS

Barrel: Phosphorous bronze, gold plating
Spring: Stainless steel, gold plated
Device Side Contact: Full-hard beryllium copper, gold plated
Board Side Contact: Full-hard beryllium copper,

gold plated

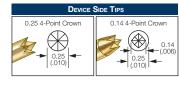
ELECTRICAL SPECIFICATIONS

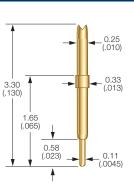
Typical Resistance: $< 50 \text{ m}\Omega$ Current Carrying Capacity: 3 amps continuous (Current DC carry capability @ 80° C steady state) Pattern 2a: **® § ®** 0.5mm pitch Characteristic Impedance: 41 Ω Time Delay: 28 pSec Loop Inductance: 1.16 nH Signal Pin to Return Capacitance: 0.68 pF -1 dB Insertion Loss Bandwidth: > 14.6 GHz

How to Order			How to Order	
Part No.	Overall Length	Part No.	Device Side Tip	PCB Side Tip
101500-000	5.74mm (.226)	101245-000	0.20 4-pt. Crown	Radius
101500-001	6.74mm (.266)	101245-001	Spear Tip	Radius

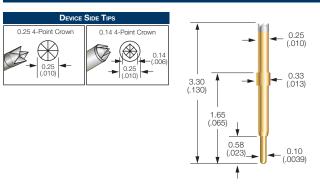
Semiconductor Probes 0.40MM PITCH

101303 PROBE





101795 PROBE



PROBE SPECIFICATIONS

Minimum Device Pitch: 0.40mm (.016) Signal Path Length: 2.92mm (.115)

Spring Force per Contact:

202 & 210 - 21.2g (0.75 oz.) @ 0.38mm (.015) travel 207 & 211 - 16.7g (0.59 oz.) @ 0.38mm (.015) travel Device Compliance: 0.25mm (.010)

DUT Board Compliance: 0.15mm (.006)

Operating Temperature:

-55°C to 150°C for stainless steel spring -55°C to 120°C for music wire spring Insertions: > 500,000

MATERIALS

Barrel: Beryllium copper, Endura plating Spring: Stainless steel, gold plated - 17g spring; Music wire, gold plated - 21g spring

Device Side Contact: Full-hard beryllium copper, gold plated Board Side Contact: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

How to Order			
Part No.	Device Side Tip	PCB Side Tip	Spring Force
101303-202	0.25 4-pt. Crown	Radius	21.2g
101303-207	0.25 4-pt. Crown	Radius	16.7g
101303-210	0.14 4-pt. Crown	Radius	21.2g
101303-211	0.14 4-pt. Crown	Radius	16.7g

Specifications subject to change without notice. Dimensions in millimeters (inches)

PROBE SPECIFICATIONS

Minimum Device Pitch: 0.40mm (.016) Signal Path Length: 2.92mm (.115) Force per Contact: 21g (0.74 oz.) @ 0.38mm (.015) travel Device Compliance: 0.25mm (.010) DUT Board Compliance: 0.15mm (.006) Operating Temperature: -55°C to 120°C Insertions: > 500,000

MATERIALS

Barrel: Brass, gold plating Spring: Music wire, gold plated Device Side Contact: Homogeneous alloy Board Side Contact: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

Typical Resistance: $< 50 \text{ m}\Omega$ Current Carrying Capacity: 3 amps continuous (Current DC carry capability @ 80° C steady state) Pattern 2a: 9 9 9 0.4mm pitch Characteristic Impedance: 54 Ω Time Delay: 19 pSec Loop Inductance: 1.02 nH Signal Pin to Return Capacitance: 0.35 pF -1 dB Insertion Loss Bandwidth: > 20 GHz

How to Order			
Part No. Device Side Tip PCB Side Tip Spring Force			
101795-H2	0.25 4-pt. Crown	Radius	21g
101795-H10	0.14 4-pt. Crown	Radius	21g

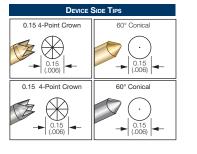
Prolonged exposure of greater than one hour reduces the maximum operating temperature of music wire springs to 85° C.

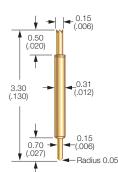
36



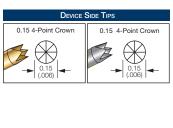
0.40MM PITCH Semiconductor Probes

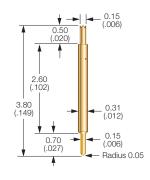
623-0286 PROBE





623-0334 Ркове





PROBE SPECIFICATIONS

Minimum Device Pitch: 0.40mm (.016) Signal Path Length: 2.80mm (.110) Force per Contact: 19.2g (0.68 oz.) @ 0.50mm (.020) travel Device Compliance: 0.30mm (.012) DUT Board Compliance: 0.20mm (.008) Operating Temperature: -55°C to 120°C Insertions: > 500,000

PROBE SPECIFICATIONS

Minimum Device Pitch: 0.40mm (.016) Signal Path Length: 3.30mm (.130) Force per Contact: 25g (.88 oz.) @ 0.50mm (.020) travel Device Compliance: 0.30mm (.012) DUT Board Compliance: 0.20mm (.008) Operating Temperature: -55°C to 120°C Insertions: > 500,000

MATERIALS

Barrel: Phosphorous bronze, gold plating
Spring: Music wire, gold plated
Device Side Contact: Carbon steel, gold plated or Homogeneous alloy
Board Side Contact: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

Typical Resistance: $< 60 \text{ m}\Omega$ Current Carrying Capacity: 2.5 amps continuous (Current DC carry capability @ 80° C steady state) Pattern 2a: (R) (S) (R) @ 0.4mm pitch Characteristic Impedance: 49 Ω Time Delay: 20 pSec Loop Inductance: 0.98 nH Signal Pin to Return Capacitance: 0.41 pF -1 dB Insertion Loss Bandwidth: > 17.5 GHz

How to Order			
Part No.	Device Side Tip	PCB Side Tip	Spring Force
623-0286-02	0.15 4-pt. Crown	Conical	19.2g
623-0286-03	Conical	Conical	19.2g
623-0286-H2	0.15 4-pt. Crown	Conical	19.2g
623-0286-H3	Conical	Conical	19.2g

H2 & H3 have the homogeneous alloy on the device side of the contact.

MATERIALS

Barrel: Phosphorous bronze, gold plating
Spring: Music wire, gold plated
Device Side Contact: Carbon steel, gold plated or Homogeneous alloy
Board Side Contact: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

Typical Resistance: < 60 mΩ Current Carrying Capacity: 3 amps continuous (Current DC carry capability @ 80° C steady state) Pattern 2a:
S

Pattern 2a:
S

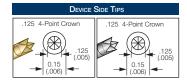
Pattern 2a:
P

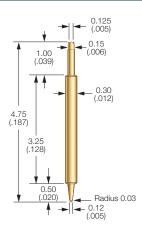
How to Order				
Part No. Device Side Tip PCB Side Tip Spring Force				
623-0334-01	0.15 4-pt. Crown	Conical	25g	
623-0334-H1	0.15 4-pt. Crown	Conical	25g	

H1 has the homogeneous alloy on the device side of the contact. Prolonged exposure of greater than one hour reduces the maximum operating temperature of music wire springs to 85°C.

Semiconductor Probes 0.40MM PITCH

200-000940 Ргове





PROBE SPECIFICATIONS

Minimum Device Pitch: 0.40mm (.016) Signal Path Length: 4.05mm (.160) Force per Contact: 26g (0.92 oz.) @ 0.70mm (.027) travel Device Compliance: 0.50mm (.020) DUT Board Compliance: 0.20mm (.008) Operating Temperature: -55°C to 120°C Insertions: > 500,000

MATERIALS

Barrel: Phosphorous bronze, gold plating Spring: Music wire, gold plated

Device Side Contact: Full-hard beryllium copper, gold plated or Homogeneous alloy

Board Side Contact: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

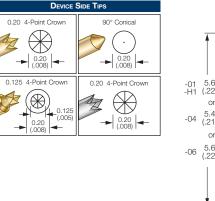
Typical Resistance: < 80 mΩ Current Carrying Capacity: 1.5 amps continuous (Current DC carry capability @ 80° C steady state) Pattern 2a: ® S ® @ 0.4mm pitch Characteristic Impedance: 44 Ω Time Delay: 21 pSec Loop Inductance: 0.95 nH Signal Pin to Return Capacitance: 0.48 pF -1 dB Insertion Loss Bandwidth: > 20 GHz

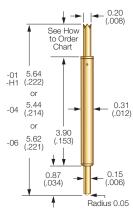
How to Order			
Part No.	Device Side Tip	PCB Side Tip	Spring Force
200-000940-001	0.125 4-pt. Crown	Conical	26g
200-000940-H1	0.125 4-pt. Crown	Conical	26g

H1 has the homogeneous alloy on the device side of the contact. Prolonged exposure of greater than one hour reduces the maximum operating temperature of music wire springs to 85°C.

Specifications subject to change without notice. Dimensions in millimeters (inches)

623-0248 Ркове





PROBE SPECIFICATIONS

Minimum Device Pitch: 0.40mm (.016) Signal Path Length: 01 & H1- 5.04mm (.198) 04 - 4.84mm (.190) 06 - 5.02mm (.198) Force per Contact: 25g (.88 oz.) @ 0.60mm (.024) travel

Device Compliance: 0.40mm (.016) DUT Board Compliance: 0.20mm (.008)

Operating Temperature: -55°C to 120°C

(Higher operating temperature probes available, consult factory) Insertions: > 500,000

MATERIALS

Barrel: Brass, gold plated Spring: Music wire, gold plated

Device Side Contact:

- 01 & 06 Full-hard beryllium copper, gold plated
- 04 Carbon steel, gold plated
- H1 Homogeneous alloy

Board Side Contact: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

Typical Resistance: 01 & H1 < 60 m Ω 04 & 06 < 50 m Ω Current Carrying Capacity: 3 amps continuous (Current DC carry capability @ 80° C steady state) Pattern 2a: © © © 0.4mm pitch Characteristic Impedance: 46 Ω Time Delay: 30 pSec Loop Inductance: 1.38 nH Signal Pin to Return Capacitance: 0.67 pF -1 dB Insertion Loss Bandwidth: > 13.2 GHz

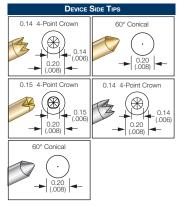
How to Order			
Part No.	Device Side Tip	Plunger Length	PCB Side Tip
623-0248-01	0.20 4-pt. Crown	0.87mm (.034)	Conical
623-0248-04	Conical	0.67mm (.026)	Conical
623-0248-06	0.125 4-pt. Crown	0.85mm (.033)	Conical
623-0248-H1	0.20 4-pt. Crown	0.87 mm(.034)	Conical

H1 has the homogeneous alloy on the device side of the contact.

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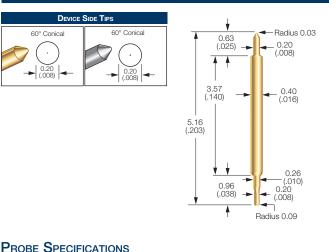
0.50MM PITCH Semiconductor Probes

623-0249 PROBE





623-0290 PROBE



PROBE SPECIFICATIONS

Minimum Device Pitch: 0.50mm (.020) Signal Path Length: 2.49mm (.098) Force per Contact: 25g (.88 oz.) @ 0.38mm (.015) travel Device Compliance: 0.23mm (.009) DUT Board Compliance: 0.15mm (.006) Operating Temperature: -55°C to 120°C Insertions: > 500,000

MATERIALS

Barrel: Phosphorous bronze, gold plating Spring: Music wire, gold plated

Device Side Contact:

- 01 & 03 Full-hard beryllium copper, gold plated 02 Carbon steel, gold plated
- H1 & H2 Homogeneous alloy

Board Side Contact: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

Typical Resistance: < 50 mΩ Current Carrying Capacity: 3.5 amps continuous (Current DC carry capability @ 80° C steady state) Pattern 2a: R S R @ 0.5mm pitch Characteristic Impedance: 50 Ω Time Delay: 18 pSec Loop Inductance: 0.89 nH Signal Pin to Return Capacitance: 0.36 pF -1 dB Insertion Loss Bandwidth: > 20 GHz

How to Order			
Part No.	Device Side Tip	PCB Side Tip	Spring Force
623-0249-01	0.14 4-pt Crown	Conical	25g
623-0249-02	Conical	Conical	25g
623-0249-03	0.15 4-pt Crown	Conical	25g
623-0249-H1	0.14 4-pt Crown	Conical	25g
623-0249-H2	Conical	Conical	25g

H1 & H2 have the homogeneous alloy on the device side of the contact.

Minimum Device Pitch: 0.50mm (.020)

Signal Path Length: 4.56mm (.180) Force per Contact: 40g (1.4oz.) @ 0.60mm (.024) travel Device Compliance: 0.45mm (.018) DUT Board Compliance: 0.15mm (.006) Operating Temperature: -55°C to 120°C (Higher operating temperature probes available, consult factory) Insertions: > 500,000

MATERIALS

Barrel: Phosphorous bronze, gold plated Spring: Music wire, gold plated Device Side Contact: Carbon steel, gold plated or Homogeneous alloy Board Side Contact: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

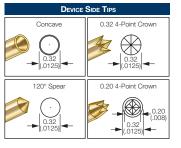
Typical Resistance: 01: $< 50 \text{ m}\Omega \& \text{H1:} < 40 \text{ m}\Omega$ Current Carrying Capacity: 3.5 amps continuous (Current DC carry capability @ 80° C steady state) Pattern 2a: R S R @ 0.5mm pitch Characteristic Impedance: 38 Ω Time Delay: 32 pSec Loop Inductance: 1.19 nH Signal Pin to Return Capacitance: 0.82 pF -1 dB Insertion Loss Bandwidth: > 9.6 GHz

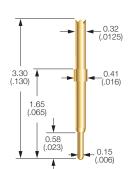
How to Order				
Part No. Device Side Tip PCB Side Tip Spring Force				
623-0290-01	Conical	Radius	40g	
623-0290-H1	Conical	Radius	40g	

H1 has the homogeneous alloy on the device side of the contact. Prolonged exposure of greater than one hour reduces the maximum operating temperature of music wire springs to 85°C.

Semiconductor Probes 0.50MM PITCH

101267 Ркове





DEVICE SIDE TIPS 120° Spea 4-Point Crown 0.32 0.32 \otimes (.0125) 0.32 3.30 _0.41 (.016) (.130) Reduced 4-Point Cro \mathbf{x} 1.65 (.065) 0.60 (.024) 0.15 (.006)

623-0326 PROBE

PROBE SPECIFICATIONS

Minimum Device Pitch: 0.50mm (.020) Signal Path Length: 2.92mm (.115) Force per Contact: 24g (0.86 oz.), 27g (.94 oz.), 31.1g (1.10 oz.) or 37g (1.30 oz.) @ 0.38mm (.015) travel

Device Compliance: 0.23mm (.009)

DUT Board Compliance: 0.15mm (.006)

Operating Temperature:

-55°C to 150°C for stainless steel spring -55°C to 120°C for music wire spring Insertions: > 500,000

MATERIALS

Barrel: Full-hard beryllium copper, Endura plating Spring:

Stainless steel, gold plated – 24g & 27g spring Music wire, gold plated – 32g & 37g spring

Device Side Contact: Full-hard beryllium copper, gold plated Board Side Contact: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

Typical Resistance: $< 40 \text{ m}\Omega$ Current Carrying Capacity: 3.5 amps continuous (Current DC carry capability @ 80° C steady state) Pattern 2a: **(R) (G) (C) (C)**

How to Order			
Part No.	Device Side Tip	PCB Side Tip	Spring Force
101267-200	Concave	Radius	24g
101267-202	0.32 4-pt. Crown	Radius	24g
101267-203	120° Spear	Radius	24g
101267-206	0.32 4-pt. Crown	Radius	31.1g
101267-208	0.20 4-pt. Crown	Radius	37g
101267-209	0.20 4-pt. Crown	Radius	27g

Specifications subject to change without notice. Dimensions in millimeters (inches)

PROBE SPECIFICATIONS

Minimum Device Pitch: 0.50mm (.020) Signal Path Length: 2.9mm (.114) Force per Contact: 25.3g (0.89 oz.) or 30g (1.06 oz.) @ 0.38mm (.015) travel Device Compliance: 0.23mm (.009) DUT Board Compliance: 0.15mm (.006) Operating Temperature: -55°C to 150°C for stainless steel spring -55°C to 120°C for music wire spring Insertions: > 500,000

MATERIALS

Barrel: Phosphorous bronze, gold plating Spring:

Stainless steel, gold plated – 25.3g spring Music wire, gold plated – 30g spring

Device Side Contact: Homogeneous alloy Board Side Contact: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

Typical Resistance: $< 55 \text{ m}\Omega$ Current Carrying Capacity: 3.5 amps continuous (Current DC carry capability @ 80° C steady state) Pattern 2a: **(R) (S) (Q)** 0.5mm pitch Characteristic Impedance: 61 Ω Time Delay: 18 pSec Loop Inductance: 1.12 nH Signal Pin to Return Capacitance: 0.30 pF -1 dB Insertion Loss Bandwidth: > 20 GHz

How to Order			
Part No.	Device Side Tip	PCB Side Tip	Spring Force
623-0326-H3	120° Spear	Radius	25.3g
623-0326-H6	0.32 4-pt. Crown	Radius	25.3g
623-0326-H9	0.20 4-pt. Crown	Radius	30g

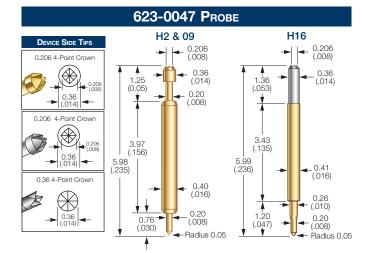
H3, H6 & H9 has the homogeneous alloy on the device side of the contact.

Prolonged exposure of greater than one hour reduces the maximum operating temperature of music wire springs to 85°C.

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0.50мм & 0.65мм Ритсн Semiconductor Probes



PROBE SPECIFICATIONS

Minimum Device Pitch: 0.50mm (.020) Signal Path Length: 5.28mm (.208)

Force per Contact:

09 - 32g (1.1 oz.) @ 0.70mm (.028) travel H2 - 22g (0.78 oz.), @ 0.70mm (.028) travel H16 - 35g (1.24 oz.) @ 0.70mm (.028) travel Device Compliance: 0.40mm (.016)

DUT Board Compliance: 0.30mm (.012)

Operating Temperature:

-55°C to 150°C for stainless steel spring -55°C to 120°C for music wire spring (Higher operating temperature probes available, consult factory) Insertions: > 500,000

MATERIALS

Barrel: Phosphorous bronze, gold plating Spring:

09 & H2 - Stainless steel, gold plated

H16 - Music wire, gold plated

Device Side Contact: Full-hard beryllium copper, gold plated or Homogeneous alloy

Board Side Contact: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

Typical Resistance: H2 & H9 < 45 mΩ; H16 < 50 mΩ Current Carrying Capacity: 2.2 amps continuous (Current DC carry capability @ 80° C steady state) Pattern 2a: R S R @ 0.65mm pitch Characteristic Impedance: 50 Ω

Time Delay: 31 pSec

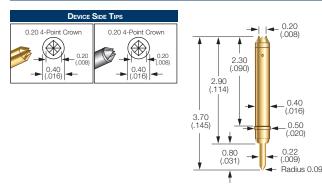
Loop Inductance: 1.56 nH

Signal Pin to Return Capacitance: 0.62 pF -1 dB Insertion Loss Bandwidth: > 20 GHz

How to Order				
Part No.	Device Side Tip	PCB Side Tip		
623-0047-09	0.206 4-pt Crown	Conical		
623-0047-H2	0.36 4-pt Crown	Conical		
623-0047-H16	0.206 4-pt Crown	Conical		

H2 & H16 has the homogeneous alloy on the device side of the contact.

623-0303 PROBE



PROBE SPECIFICATIONS

Minimum Device Pitch: 0.65mm (.026) Signal Path Length: 3.10mm (.122) Force per Contact: 30g (1.06 oz.) @ 0.60mm (.024) travel Device Compliance: 0.40mm (.016) DUT Board Compliance: 0.20mm (.008) Operating Temperature: -55°C to 120°C (Higher operating temperature probes available, consult factory) Insertions: > 500,000

MATERIALS

Barrel: Phosphorous bronze, gold plating
Spring: Music wire, gold plated
Device Side Contact: Carbon steel, gold plated or Homogeneous alloy
Board Side Contact: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

How to Order			
Part No.	Device Side Tip	PCB Side Tip	
623-0303-01	0.20 4-pt. Crown	Conical	
623-0303-H1	0.20 4-pt. Crown	Conical	

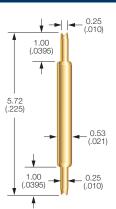
H1 has the homogeneous alloy on the device side of the contact.

Prolonged exposure of greater than one hour reduces the maximum operating temperature of music wire springs to 85°C.

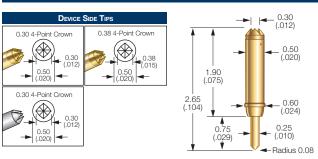
Semiconductor Probes 0.65MM & 0.80MM PITCH

100938 PROBE





623-0270 PROBE



PROBE SPECIFICATIONS

Minimum Device Pitch: 0.65mm (.026) Signal Path Length: 4.75mm (.187) Force per Contact: 31g (1.1oz.) @ 0.97mm (.038) travel Device Compliance: 0.48mm (.019) DUT Board Compliance: 0.48mm (.019) Operating Temperature: -55°C to 150°C Insertions: > 500,000

MATERIALS

Barrel: Nickel/silver, gold plated Spring: Stainless steel, gold plated Device Side Contact: Full-hard beryllium copper, gold plated Board Side Contact: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

How to Order		
Part No.	Device Side Tip	PCB Side Tip
100938-001	0.25 4-pt Crown	0.25 4-pt Crown
100938-014	0.25 4-pt Crown	Radius
100938-016	Radius	Radius

PROBE SPECIFICATIONS

Minimum Device Pitch: 0.80mm (.031) Signal Path Length: 2.15mm (0.085) Force per Contact: 27.5g (0.97 oz.) @ 0.50mm (.020) travel Device Compliance: 0.30mm (.012) DUT Board Compliance: 0.20mm (.008) Operating Temperature: -55°C to 120°C (Higher operating temperature probes available, consult factory) Insertions: > 500,000

MATERIALS

Barrel: Phosphorous bronze, gold plating
Spring: Music Wire, gold plated
Device Side Contact:

01 & 03 Carbon steel, gold plated
H1 Homogeneous alloy

Board Side Contact: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

Typical Resistance: $< 40 \text{ m}\Omega$ Current Carrying Capacity: 3 amps continuous (Current DC carry capability @ 80° C steady state) Pattern 2a: **(R) (S) (R)** @ 0.8mm pitch Characteristic Impedance: 44 Ω Time Delay: 14 pSec Loop Inductance: 0.59 nH Signal Pin to Return Capacitance: 0.31 pF -1 dB Insertion Loss Bandwidth: > 20 GHz

How to Order		
Part No.	Device Side Tip	PCB Side Tip
623-0270-01	0.30 4-pt. Crown	Conical
623-0270-03	0.38 4-pt. Crown	Conical
623-0270-H1	0.30 4-pt. Crown	Conical

H1 has the homogeneous alloy on the device side of the contact.

Prolonged exposure of greater than one hour reduces the maximum operating temperature of music wire springs to 85° C.

Specifications subject to change without notice. Dimensions in millimeters (inches)

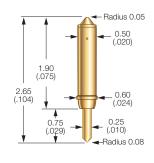
42



0.80MM PITCH Semiconductor Probes

623-0271 PROBE







0.34 (.013)

0.60

(.024)

0.70

(.027)

0.30

(.012)

Radius 0.10

Probe Specifications

Minimum Device Pitch: 0.80mm (.031) Signal Path Length: 4.04mm (.159) Force per Contact: 33.4g (1.18 oz.) @ 0.80mm (.031) travel Device Compliance: 0.50mm (.020) DUT Board Compliance: 0.30mm (.012) Operating Temperature: -55°C to 120°C

(Higher operating temperature probes available, consult factory) Insertions: > 500,000

MATERIALS

Barrel: Phosphorous bronze, gold plating
Spring: Music wire, gold plated
Device Side Contact:

02 & 03 Carbon steel, gold plated
08 & 09 Full-hard beryllium copper, gold plated
H2, H8, & H9 Homogeneous alloy

Board Side Contact: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

Typical Resistance: $03 < 35 \text{ m}\Omega$; $02, 08, 09, H2, H8, & H9 < 50 \text{ m}\Omega$ Carrying Capacity: 3 amps continuous (Current DC carry capability @ 80° C steady state) Pattern 2a: $0 \leq 0 = 0.8 \text{ mm}$ pitch Characteristic Impedance: 37Ω Time Delay: 23 pSec Loop Inductance: 0.86 nHSignal Pin to Return Capacitance: 0.62 pF-1 dB Insertion Loss Bandwidth: > 20 GHz

How to Order		
Part No.	Device Side Tip	PCB Side Tip
623-0195-02	0.34 4-pt. Crown	Conical
623-0195-03	Conical	Conical
623-0195-08	0.20 4-pt. Crown	Conical
623-0195-09	0.40 4-pt. Crown	Conical
623-0195-H2	0.34 4-pt. Crown	Conical
623-0195-H8	0.20 4-pt. Crown	Conical
623-0195-H9	0.40 4-pt. Crown	Conical

H2, H8 & H9 has the homogeneous alloy on the device side of the contact.

Specifications subject to change without notice. Dimensions in millimeters (inches)

PROBE SPECIFICATIONS

Minimum Device Pitch: 0.80mm (.031) Signal Path Length: 2.15mm (0.085) Force per Contact: 27.5g (0.97 oz.) @ 0.50mm (.020) travel Device Compliance: 0.30mm (.012) DUT Board Compliance: 0.20mm (.008) Operating Temperature: -55°C to 120°C Insertions: > 500,000

MATERIALS

Barrel: Phosphorous bronze, gold plating Spring: Music wire, gold plated Device Side Contact: Carbon steel, gold plated Board Side Contact: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

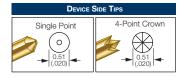
Typical Resistance: < 40 m Ω Current Carrying Capacity: 3 amps continuous (Current DC carry capability @ 80° C steady state) Pattern 2a: **R S R** @ 1.0 mm pitch Characteristic Impedance: 54 Ω Time Delay: 13 pSec Loop Inductance: 0.72 nH Signal Pin to Return Capacitance: 0.25 pF -1 dB Insertion Loss Bandwidth: > 20 GHz

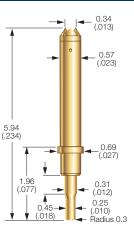
How to Order		
Part No.	Device Side Tip	PCB Side Tip
623-0271-01	Conical	Conical

Prolonged exposure of greater than one hour reduces the maximum operating temperature of music wire springs to 85°C.

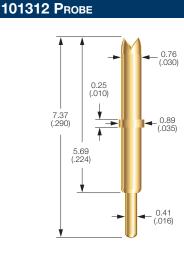
Semiconductor Probes 0.80MM & 1.00MM PITCH

101785 PROBE





4-Point Crown



PROBE SPECIFICATIONS

Minimum Device Pitch: 0.80mm (.031) Signal Path Length: 5.21mm (.205) Force per Contact: 35.4g (1.25 oz..) @ 0.74mm (.029) travel Device Compliance: 0.33mm (.013) DUT Board Compliance: 0.41mm (.016) Operating Temperature: -55°C to 150°C Insertions: > 500,000

MATERIALS

Barrel: Full-hard beryllium copper, Endura plating Spring: Stainless steel, gold plated Device Side Contact: Full-hard beryllium copper, gold plated Board Side Contact: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

Typical Resistance: < 40 mΩ</th>Current Carrying Capacity: 5 amps continuous
(Current DC carry capability @ 80° C steady state)Pattern 2a: **® ③ ®** at 0.8mm pitchCharacteristic Impedance: 38 ΩTime Delay: 27 pSecLoop Inductance: 1.03 nHSignal Pin to Return Capacitance: 0.71 pF-1 dB Insertion Loss Bandwidth: > 10 GHz

How to Order		
Part No.	Device Side Tip	PCB Side Tip
101785-001	Single Point	Radius

PROBE SPECIFICATIONS

Minimum Device Pitch: 1.00mm (.039) Signal Path Length: 6.97mm (.274) Force per Contact: 31g (1.1 oz.) @ 1.02mm (.040) travel Device Compliance: 0.25mm (.010) DUT Board Compliance: 0.76mm (.030) Operating Temperature: -55°C to 150°C Insertions: > 500,000

MATERIALS

Barrel: Full-hard beryllium copper, Endura plating Spring: Stainless steel, gold plated Device Side Contact: Full-hard beryllium copper, gold plated Board Side Contact: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

Typical Resistance: < 40 m Ω Current Carrying Capacity: 5 amps continuous (Current DC carry capability @ 80° C steady state) Pattern 2a: **(R) (S) (R)** at 1.00mm pitch Characteristic Impedance: 36 Ω Time Delay: 33 pSec Loop Inductance: 1.19 nH Signal Pin to Return Capacitance: 0.92 pF -1 dB Insertion Loss Bandwidth: > 10 GHz

	How to Order		
īр	Part No.	Device Side Tip	PCB Side Tip
	101312-001	0.76 4-pt. Crown	Radius

Specifications subject to change without notice. Dimensions in millimeters (inches)

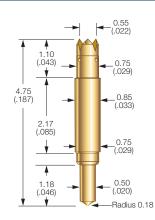
44

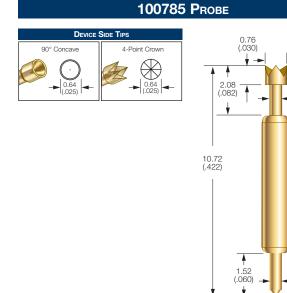


1.00MM & 1.27MM PITCH Semiconductor Probes

623-0117 PROBE







0.64

0.91

0.38

PROBE SPECIFICATIONS

Minimum Device Pitch: 1.00mm (.039) Signal Path Length: 3.90mm (.154) Force per Contact: 35.5g (1.25 oz.) @ 0.85mm (.033) travel Device Compliance: 0.45mm (.018) DUT Board Compliance: 0.40mm (.016) Operating Temperature: -55°C to 120°C Insertions: > 500,000

MATERIALS

Barrel: Phosphorous bronze, gold plating Spring: Music wire, gold plated Device Side Contact: Full-hard beryllium copper, gold plated Board Side Contact: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

Typical Resistance: $< 60 \text{ m}\Omega$ Current Carrying Capacity: 3 amps continuous (Current DC carry capability @ 80° C steady state) Pattern 2a: **R S R** @ 1.27mm pitch Characteristic Impedance: 43 Ω Time Delay: 24 pSec Loop Inductance: 1.02 nH Signal Pin to Return Capacitance: 0.56 pF -1 dB Insertion Loss Bandwidth: > 20 GHz

How to Order		
Part No.	Device Side Tip	PCB Side Tip
623-0117-02	0.55 4-pt Crown	Conical

Prolonged exposure of greater than one hour reduces the maximum operating temperature of music wire springs to 85°C.

PROBE SPECIFICATIONS

Minimum Device Pitch: 1.27mm (.050) Signal Path Length: 9.2mm (.362) Force per Contact: 42.5g (1.5 oz.) @ 1.52mm (.060) travel Device Compliance: 0.76mm (.030) DUT Board Compliance: 0.76mm (.030) Operating Temperature: -55°C to 150°C Insertions: > 250,000

MATERIALS

Barrel: Full-hard beryllium copper, gold plated Spring: Stainless steel, gold plated Device Side Contact: Full-hard beryllium copper, gold plated Board Side Contact: Full-hard beryllium copper, gold plated

ELECTRICAL SPECIFICATIONS

Typical Resistance: $< 50 \text{ m}\Omega$ Carrying Capacity: 3 amps continuous (Current DC carry capability @ 80° C steady state) Pattern 2a: **R S R** @ 1.27mm pitch Characteristic Impedance: 41 Ω Time Delay: 47 pSec Loop Inductance: 1.93 nH Signal Pin to Return Capacitance: 1.15 pF -1 dB Insertion Loss Bandwidth: > 16.2 GHz

How to Order		
Part No.	Device Side Tip	PCB Side Tip
100785-002	.064 4-pt. Crown	Conical
100785-003	90° Concave	Conical

IDI Test Probes

IDI offers a wide range of spring contact probes to meet your testing requirements and has long been recognized as the world's largest probe manufacturer. This section of our catalog has over 60 different probe series that includes our Standard PCB Probes as well as our Specialty Probe Series.

MICRO SERIES

The Micro Series Probes ranges in pitch from .010 (0.25) to .025 (0.64) pitch and are typically between half an inch to an inch in length. Shorter fine pitch probes can be found in our Semiconductor Probe section.

STANDARD PROBES

IDI standard probes range in pitch from 0.039 (1.00) to .187 (4.75). Within most of the pitch series, you will find multiple length and travel options. Also included in the Standard Probe Section are

our more aggressive probes that are



dimensionally equivalent to the standard probes.

ICT PROBES

The ICT probe design features a bifurcated barrel with four separate fingers. The barrel is compliant, and formed against the plunger, thus eliminating any gap between the plunger and barrel. ICT probes are more accurate and most stable in resistance than standard designs.

LEAD FREE PROBES

The Lead Free Probe Series is based on IDI's ICT Probes Series. The plunger material, plating and tip geometry have been optimized to provide less wear and contamination build-up while using a moderate spring force of 7 to 8 ounces.

ROTATOR PROBES

Ideal for no-clean and lead-free applications, this aggressive probe rotates 90° at the rated travel, virtually drilling through contaminants with a low spring force.

DOUBLE ENDED PROBES AND RECEPTACLES

Double ended probes feature both a top side and bottom side compliant plunger. Double ended receptacles are available with a permanent bottom side plunger and a replaceable probe on the top side. They are also available with both a top side and bottom side replaceable probe.

Switch Probes

A Switch Probe is a spring contact probe and receptacle that has two individual current paths. One current path is closed, the other is open and after a designated travel the second current path closes.

HIGH CURRENT PROBES

IDI offers two different high current probe designs in four different pitches. The SH Series features a bias ball, which is the most aggressive biasing technique to aid in assuring a low and consistent resistance, cycle after cycle. The SHE Series features a bias spring, an effective biasing technique for many applications.

THERMOCOUPLE PROBES

The Thermocouple Probe is an ungrounded, thermally conductive probe used for the measurement of variations in temperature. IDI offers two Thermocouple Probes, Type T for up to 300°F and Type K for up to 500°F.

Kelvin Probes

The Kelvin Probe has two paths on the same axis (inner path and outer path) that are insulated from each other and are capable of testing low levels of resistance.

COAXIAL PROBES

IDI Coax Probes provide a low noise, controlled impedance signal path with reliable easy connect/disconnect options. Many designs include a spring loaded signal probe and a spring loaded shielding plunger for the ground.

CONNECTOR & SEMICONDUCTOR PROBES

If you cannot find what you are looking for in this section of our catalog, be sure to check out the OEM Probes and Semiconductor Test Probe sections.

In the OEM Probes you will find a variety of probes that are primarily designed to mount in plastic or on a PCB, ranging in centers and lengths.

In the Semiconductor Probe section,

you will find extremely fine pitch probes with very short lengths.



Spring Contact Probes

BOARD TEST PROBES TABLE OF CONTENTS

Micro Series \leq .025 (0.64) centers	Double Ended Receptacles80
Standard Probes	Interface Probes 82
.039 (1.00) centers 51	Interface Pins83
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.075 (1.91) centers62	Switch Probes
.100 (2.54) centers	Thermocouple Probes90
≥ .125 (3.18) centers76	Kelvin Probes91
Double Ended Probes79	Coaxial Probes 92

Crimping Pliers



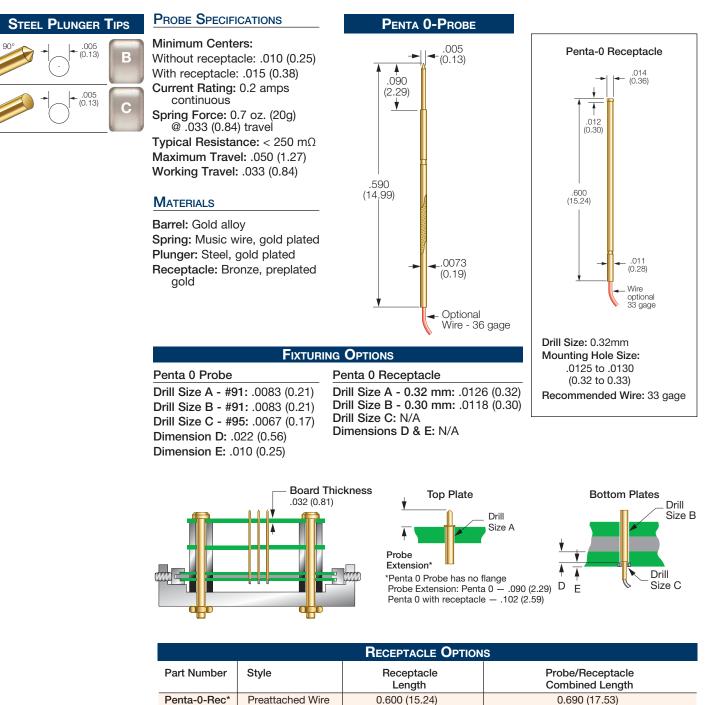
CRIMP TOOLS			
Model	Receptacle Size/Blank	Wire Range	
CP00T	R00T	30 GA	
CP00W	R00W	30 GA	
CP0	0	28-30 GA	
CPR-50J	R-50J	28-30 GA	
CPR-50C	R-50C	28-30 GA	
CP1	1	24-28 GA	
CPR-075	R-075	24-28 GA	
CP2	2	22-26 GA	
CPR-100	R-100	22-26 GA	
CP3	3	22-26 GA	
CP4	4	22-26 GA	
CP5	5	22-26 GA	
CP-SS30	RSS-30	28-30 GA	
CP-SS40-T	RSS-40-T	30 GA	
CP-SS40-W	RSS40-W	30 GA	
CP-SS50	RSS-50	28-30 GA	
CP-SS75	RSS-75	24-28 GA	
CP-SS100	RSS-100	28-30 GA	

Receptacle Insertion Tools

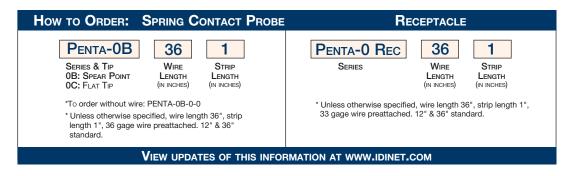


INSERTION TOOLS		
Model	Receptacle Size	
RT00	00	
RT0	0	
RTR50C, RTR50J	R-50C, R-50J	
RT1	1	
RTR075	R-075	
RT2	2	
RTR100	100	
RT3	3	
RT4	4	
RT5	5	
RT-SS30	RSS30	
RT-SS40	RSS40	
RT-SS50	RSS50	
RT-SS75	RSS75	
RT-SS100	RSS100	

Penta 0 .010 - .015 Centers



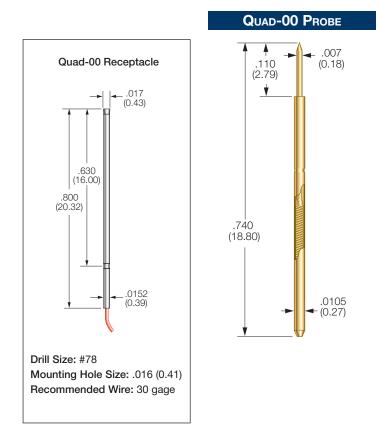
* Unless otherwise sp	pecified, wire lend	ath 36", strip lend	th 1". 36 gage wir	e preattached



Specifications subject to change without notice. Dimensions in inches (millimeters)

Interconnect Devices, Inc. welcomes your e-mail at info@idinet.com

.020 Centers Quad 00



PROBE SPECIFICATIONS

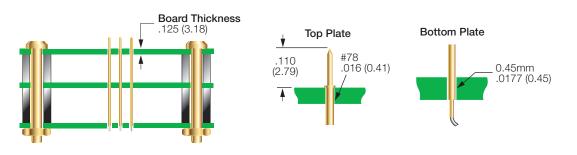
Minimum Centers: .020 (0.51) Current Rating: 0.3 amps continuous Spring Force: 0.75 oz. (21g) @ .067 (1.70) travel Preload Force: 0.23 oz. (6.5g) Typical Resistance: < 160 mΩ Maximum Travel: .100 (2.54) Working Travel: .067 (1.70)



MATERIALS

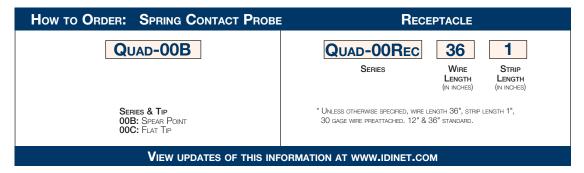
Barrel: Gold alloy Spring: Music wire, gold plated Plunger: Steel, gold plated over nickel Receptacle: Nickel/silver, gold lined inside

FIXTURING OPTIONS



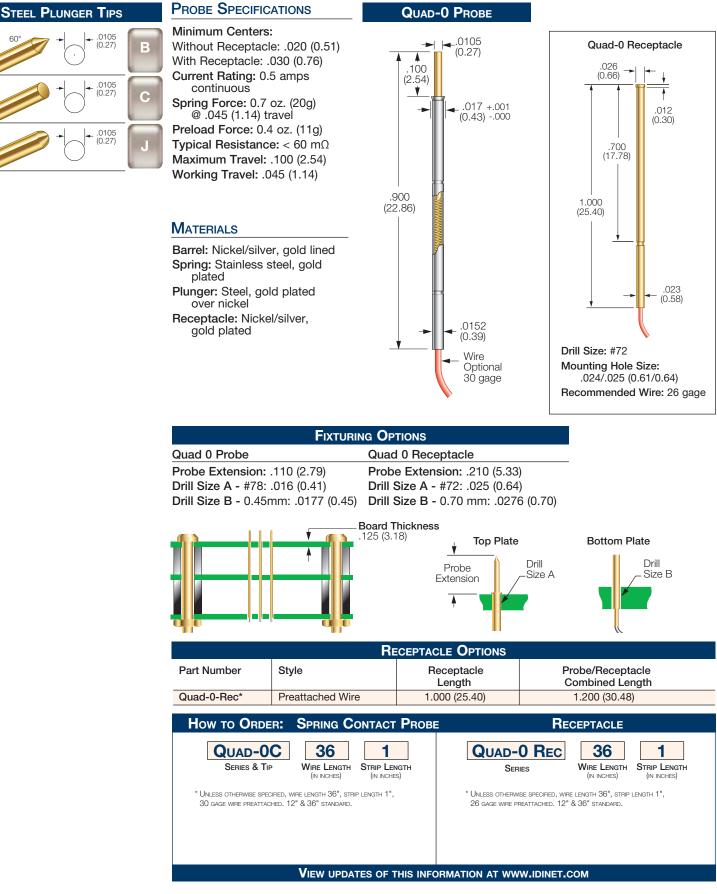
RECEPTACLE OPTIONS					
Part Number	Style	Receptacle Length	Probe/Receptacle Combined Length		
Quad-00-Rec*	Preattached Wire	0.800 (20.32)	0.910 (23.11)		

* Unless otherwise specified, wire length 36", strip length 1", 30 gage wire preattached



Specifications subject to change without notice. Dimensions in inches (millimeters)

Quad 0 .020 - .030 Centers



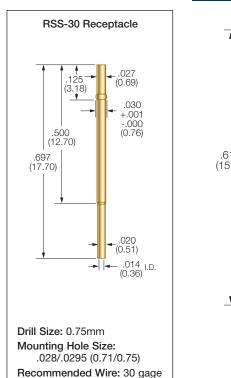
Specifications subject to change without notice. Dimensions in inches (millimeters)

50



Interconnect Devices, Inc. welcomes your e-mail at info@idinet.com

.039 Centers - Size 30 Series SS



SS-30 Probe

PROBE SPECIFICATIONS

Minimum Centers: .039 (0.99) Current Rating: 3 amps continuous Spring Force: 1.3 or 1.6 oz. @ .067 (1.70) travel

Typical Resistance: < 40 mΩ Maximum Travel: .100 (2.54) Working Travel: .067 (1.70)

Rated Force oz. (g)	Preload oz. (g)	Material
1.3 (37)	0.5 (14)	SS
1.6 (45)	0.5 (14)	MW

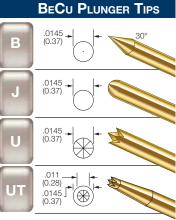
MATERIALS

Barrel: Nickel/silver, preplated gold

Spring: Stainless steel or music wire, gold plated

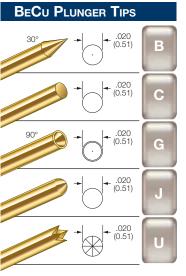
Plunger: Beryllium copper, gold plated over nickel or Duralloy[™]

Receptacle: Nickel/silver, preplated gold



RECEPTACLE OPTIONS					
Part Number	Style	Receptacle Length	Probe/Rec Combined		Comments –
R-SS-30-CR	Crimp	0.697 (17.70)	0.807 (20	.50)	-
R-SS-30-SC	Solder Cup	0.697 (17.70)	0.807 (20	.50)	-
R-SS-30-PS	Preattached Wire*	0.697 (17.70)	0.807 (20	.50)	30 gage, vacuum sealed
SERIES	30 B Size Tip Style			R-S Series	
1.3	NG FORCE: DZ. @ .067 (1.70) TRAVEL DZ. @ .067 (1.70) TRAVEL	PLATING OPTIONS: G: GOLD PLATED PLI D: DURALLOY [™] PLATE CRIMPING PLIERS: CF	unger ed Plunger PSS30		np Jer Cup attached Wire*
Insertion tool: RTSS30 * Unless otherwise specified, wire length 36" with a 1" semi-strip. 12" & 36" standard. View updates of this information at www.jdinet.com					

Series S Size 00 - .039 Centers



PROBE SPECIFICATIONS

Minimum Centers: .039 (0.99) Current Rating: 3 amps continuous

Spring Force: 1.3 or 1.6 oz. @ .050 (1.27) travel Typical Resistance: < 55 mΩ Maximum Travel: .090 (2.29) Working Travel: .050 (1.27)

Rated Force oz. (g)	Preload oz. (g)	Material
1.3 (37)	0.6 (17)	BeCu
1.6 (45)	0.7 (20)	SS

MATERIALS

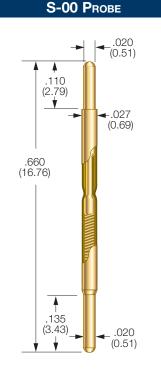
Barrel: Nickel/silver, preplated gold

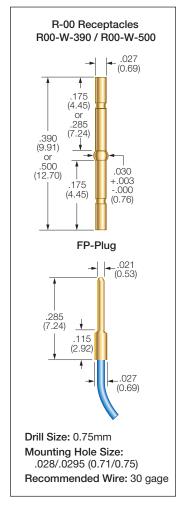
Spring: Beryllium copper or stainless steel, gold plated

Plunger: Beryllium copper, gold plated over nickel or Duralloy™

Receptacle: Nickel/silver, gold plated

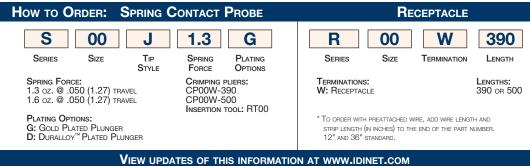
Plug-In Terminal: Beryllium copper, preplated gold



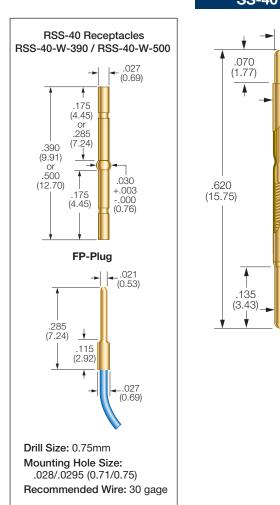


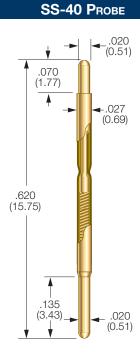
	RECEPTACLE OPTIONS				
Part Number	Style	Receptacle or Terminal Length	Probe/Receptacle Combined Length	Probe/Receptacle/Terminal Combined Length	
R-00-W-390	Receptacle	0.390 (9.91)	0.915 (23.24)	1.03 (26.16)	
R-00-W-500	Receptacle	0.500 (12.70)	1.025 (26.04)	1.14 (28.96)	
FP-Plug	Plug-In Terminal*	0.285 (7.24)	—	-	

*To order with preattached wire, add wire length and strip length (in inches) to the end of the part number. For example: R-00-W-390-36-1 or FP-Plug-36-1



.039 Centers - Size 40 Series SS





PROBE SPECIFICATIONS

Minimum Centers: .039 (0.99) Current Rating: 3 amps continuous

Spring Force: 1.8 or 2.4 oz. @ .050 (1.27) travel Typical Resistance: < 55 mΩ Maximum Travel: .050 (1.27) Working Travel: .050 (1.27)

Rated Force oz. (g)	Preload oz. (g)	Material
1.8 (51)	1.1 (31)	BeCu
2.4 (68)	1.5 (43)	SS

MATERIALS

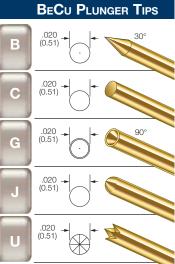
Barrel: Nickel/silver, preplated gold

Spring: Beryllium copper or stainless steel, gold plated

Plunger: Beryllium copper, gold plated over nickel or Duralloy

Receptacle: Nickel/silver, gold plated

Plug-In Terminal: Beryllium copper, preplated gold

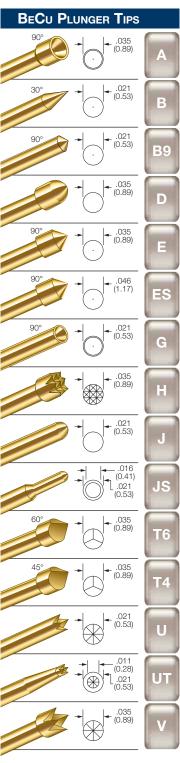


	RECEPTACLE OPTIONS				
Part Number	Style	Receptacle or Terminal Length	Probe/Receptacle Combined Length	Probe/Receptacle/Terminal Combined Length	
RSS-40-W-390	Receptacle	0.390 (9.91)	0.875 (22.23)	.990 (25.15)	
RSS-40-W-500	Receptacle	0.500 (12.70)	0.985 (25.02)	1.100 (27.94)	
FP-Plug	Plug-In Terminal*	0.285 (7.24)	_	_	

*To order with preattached wire, add wire length and strip length (in inches) to the end of the part number. For example: R-00-W-390-36-1 or FP-Plug-36-1

How to Order: Spring Contact Probe	Receptacle
SS 40 J 1.8 G	R-SS 40 W 390
Series Size Tip Spring Plating Style Force Options	Series Size Termination Length
Spring Force: Crimping pliers: 1.8 oz. @ .050 (1.27) travel CPSS40W-390 2.4 oz. @ .050 (1.27) travel CPSS40W-500 Insertion tool: RTSS40	TERMINATIONS: LENGTHS: W: RECEPTACLE 390 OR 500
Plating Options: G: Gold Plated Plunger D: Duralloy [™] Plated Plunger	* To order with preattached wire, add wire length and strip length (in inches) to the end of the part number. For example: RSS-40-W-390-36-1. 12" & 36" standard.
VIEW UPDATES OF THIS INFORMATION	ON AT WWW.IDINET.COM

Series S Size 0 - .050 Centers



PROBE SPECIFICATIONS

Minimum Centers: .050 (1.27) Current Rating: 3 amps continuous

Spring Force: 2.2, 2.5 or 3.7 oz. @ .070 (1.78) travel Typical Resistance: < 35 mΩ Maximum Travel: .100 (2.54) Working Travel: .070 (1.78)

Rated Force	Preload	Material
oz. (g)	oz. (g)	
2.2 (62)	0.6 (17)	BeCu
2.5 (71)	0.6 (17)	SS
3.7 (105)	1.9 (54)	MW

MATERIALS

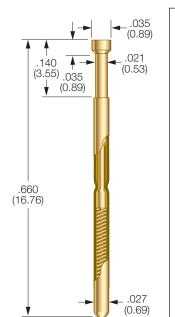
Barrel: Nickel/silver, gold plated

Spring: Beryllium copper, music wire or stainless steel, gold plated

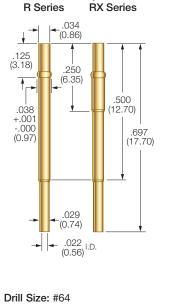
Plunger: Beryllium copper, gold plated over nickel or Duralloy[™]

Receptacle: Nickel/silver, gold plated, gold plated post Plug-In Terminal: Beryllium

copper, preplated gold



S-0 PROBE

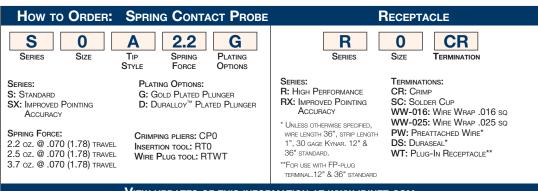


R-0 Receptacles

Mounting Hole Size: .035/.0365 (0.89/0.93) Recommended Wire: 28-30 gage

RECEPTACLE OPTIONS				
Part Number	Style	Receptacle Length	Probe/Receptacle Combined Length	Comments
R-0-CR	Crimp	0.697 (17.70)	0.857 (21.77)	—
R-0-SC	Solder Cup	0.697 (17.70)	0.857 (21.77)	_
R-0-WW-016	Wire Wrap	0.947 (24.05)	1.107 (28.12)	.250 post length016 sq.
R-0-WW-025	Wire Wrap	0.997 (25.32)	1.157 (29.39)	.300 post length025 sq.
R-0-PW	Preattached Wire	0.697 (17.70)	0.857 (21.77)	30 gage - non vacuum sealed*
R-0-DS	Duraseal®	0.697 (17.70)	0.857 (21.77)	30 gage - vacuum sealed*
R-0-WT	Plug-In Receptacle	0.697 (17.70)	0.857 (21.77)	For use with FP-Plug terminal
FP-Plug	Plug-In Terminal	_	_	Plugs into R-0-WT receptacle*

* Unless otherwise specified, wire length 36", strip length 1", 30 gage Kynar

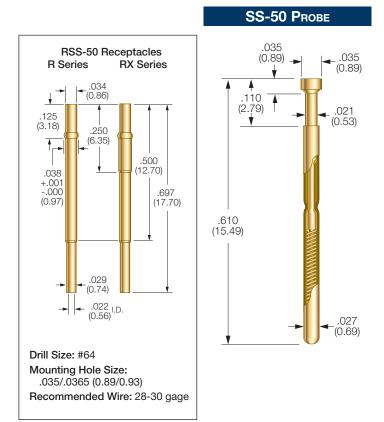


VIEW UPDATES OF THIS INFORMATION AT WWW.IDINET.COM

Specifications subject to change without notice. Dimensions in inches (millimeters)

54

.050 Centers - Size 50 Series SS



PROBE SPECIFICATIONS

Minimum Centers: .050 (1.27) Current Rating: 3 amps continuous

Spring Force: 2.9, 3.3 or 5.1 oz. @ .050 (1.27) travel Typical Resistance: < 35 mΩ Maximum Travel: .070 (1.78) Working Travel: .050 (1.27)

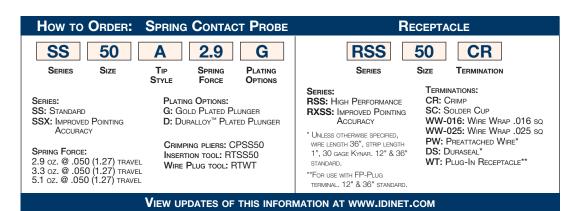
Rated Force oz. (g)	Preload oz. (g)	Material
2.9 (82)	1.1 (31)	BeCu
3.3 (94)	1.7 (48)	SS
5.1 (145)	1.5 (42)	MW

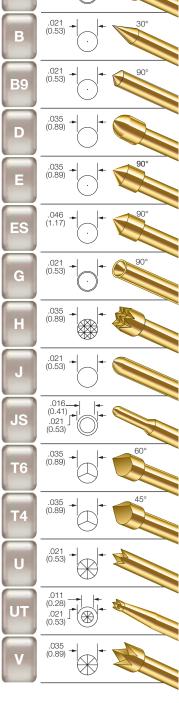
MATERIALS

- Barrel: Nickel/silver, gold plated
- Spring: Beryllium copper, stainless steel or music wire, gold plated
- Plunger: Beryllium copper, gold plated over nickel or Duralloy[™]
- Receptacle: Nickel/silver, gold plated, gold plated post Plug-In Terminal: Beryllium copper, preplated gold

	RECEPTACLE OPTIONS					
Part Number	Style	Receptacle Length	Probe/Receptacle Combined Length			
RSS-50-CR	Crimp	0.697 (17.70)	0.807 (20.50	-		
RSS-50-SC	Solder Cup	0.697 (17.70)	0.807 (20.50)	-		
RSS-50-WW-016	Wire Wrap	0.947 (24.05)	1.057 (26.85)	.250 post length016 sq.		
RSS-50-WW-025	Wire Wrap	0.997 (25.32)	1.107 (28.12)	.300 post length025 sq.		
RSS-50-PW	Preattached Wire	0.697 (17.70)	.807 (20.50)	30 gage - non vacuum sealed*		
RSS-50-DS	Duraseal®	0.697 (17.70)	.807 (20.50)	30 gage - vacuum sealed*		
RSS-50-WT	Plug-In Receptacle	0.697 (17.70)	.807 (20.50)	For use with FP-Plug terminal		
FP-Plug	Plug-In Terminal	_	—	Plugs into R-SS-50-WT receptacle*		

* Unless otherwise specified, wire length 36", strip length 1", 30 gage Kynar



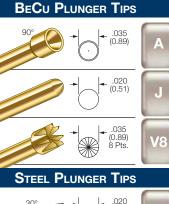


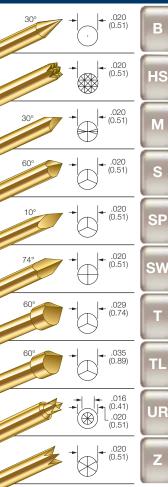
BECU PLUNGER TIPS

.035

(0.89)

ICT-50C and S-50C Size 50C - .050 Centers





PROBE SPECIFICATIONS

Minimum Centers: .050 (1.27) Current Rating: 3 amps continuous

Spring Force: 4.3 or 5.6 oz. @ .170 (4.32) travel Typical Resistance: < 20 m Ω for ICT-50C < 25 m Ω for S-50C Maximum Travel: .250 (6.35)

Working Travel: .170 (4.32)

Rated Force	Preload	Material
oz. (g)	oz. (g)	
4.3 (122)	1.9 (54)	SS
5.6 (159)	2.1 (60)	MW
0.0 (100)	2.1 (00)	10100

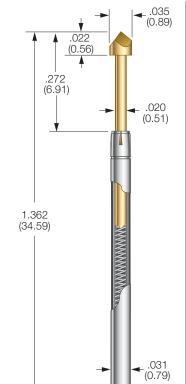
MATERIALS

Barrel: Nickel/silver, gold lined Spring: Music wire, nickel

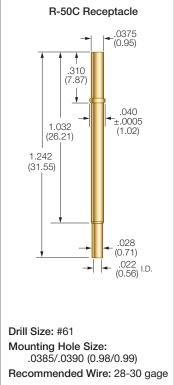
plated or stainless steel **Plunger:** Beryllium copper or steel, gold plated over nickel

Receptacle: Beryllium copper, preplated gold, gold plated post

Terminal: Beryllium copper, preplated gold

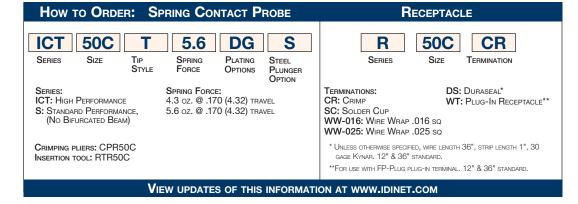


ICT-50C/S-50C PROBE

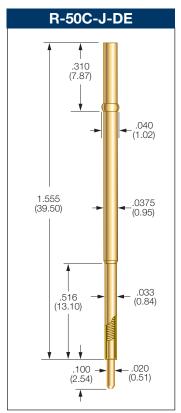


	RECEPTACLE OPTIONS					
Part Number	Style	Receptacle Length	Probe/Receptacle Combined Length	Comments		
R-50C-CR	Crimp	1.242 (31.54)	1.572 (39.92)	_		
R-50C-SC	Solder Cup	1.242 (31.54)	1.572 (39.92)	_		
R-50C-WW-016	Wire Wrap	1.492 (37.89)	1.822 (46.27)	.250 post length016 sq.		
R-50C-WW-025	Wire Wrap	1.542 (39.16)	1.872 (47.55)	.300 post length025 sq.		
R-50C-DS	Duraseal®	1.242 (31.54)	1.572 (39.92)	30 gage wire, vacuum sealed*		
R-50C-WT	Plug-In Receptacle	1.242 (31.54)	1.572 (39.92)	For use with FP-Plug plug-in terminal		
FP-Plug	Plug-In Terminal	_	_	Plugs into R-50C-WT receptacle*		
* Uplease attention appendix wire length 26" atrin length 1" 20 ages Kunor						

* Unless otherwise specified, wire length 36", strip length 1", 30 gage Kynar







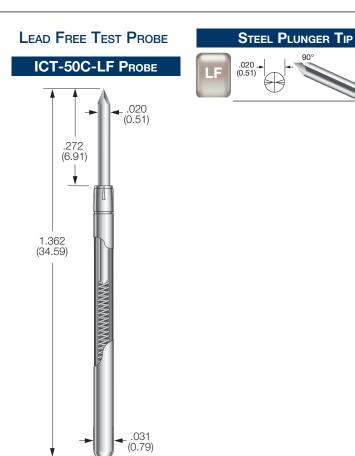
PROBE SPECIFICATIONS

Minimum Centers: .050 (1.27) Drill Size: #61 Mounting Hole Size: .0385/.0390 (0.98/0.99) Spring Force: 2.7 oz. (77g) @ .069 (1.75) travel Maximum Travel: .100 (2.54) Working Travel: .070 (1.77)

MATERIALS

Receptacle: Beryllium copper, gold plated Spring: Music wire, gold plated Plunger: Beryllium copper, gold plated over nickel

How to Order						
R	50C	J	DE			
SERIES	SIZE	Tip Style	TERMINATION			



PROBE SPECIFICATIONS

Minimum Centers: .050 (1.27)
Current Rating: 3 amps continuous
Spring Force: 5.6 oz. @ .170 (4.32) travel
Typical Resistance: < 60 mΩ against a lead free surface
Maximum Travel: .250 (6.35)
Working Travel: .170 (4.32)

MATERIALS

Barrel: Nickel/silver, gold lined Spring: Music wire, nickel plated Plunger: Steel, Duralloy[™] plated

How to Order					
ICT SERIES	50C SIZE	LF TIP	5.6 Spring	DGD	S STEEL
CENIES	OIZL	STYLE	FORCE	OPTIONS	PLUNGER

S-50C Rotator .050 Centers

BECU PLUNGER TIPS 60° + + (0.61) 45° + + (0.89)TL

PROBE SPECIFICATIONS

Minimum Centers: .050 (1.27) Current Rating: 3 amps continuous Spring Force: 3.7oz. @ .170

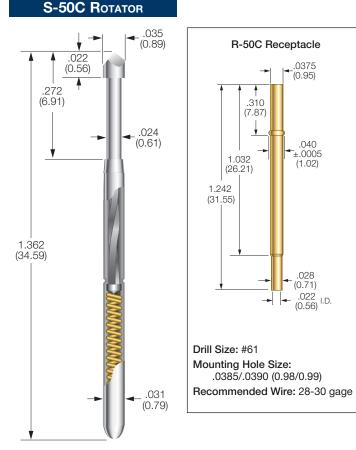
(4.32) travel Typical Resistance: $< 25 \text{ m}\Omega$ Maximum Travel: .250 (6.35) Working Travel: .170 (4.32) Rotates: 85° @ .170 (4.32) travel

Rated Force	Preload
oz. (g)	oz. (g)
3.7 (105)	1.5 (42)

MATERIALS

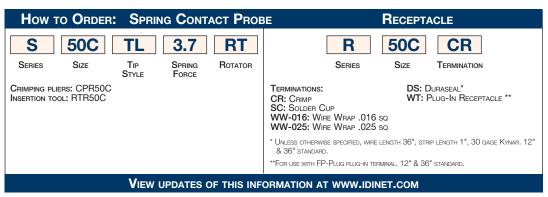
Barrel: Nickel/silver, gold lined Spring: Music wire, gold plated Plunger: Beryllium copper, Duralloy[™] plated

- Receptacle: Beryllium copper, preplated gold, gold plated post
- Plug-In Terminal: Beryllium copper, preplated gold



	RECEPTACLE OPTIONS					
Part Number	Style	Receptacle Length	Probe/Receptacle Combined Length			
R-50C-CR	Crimp	1.242 (31.55)	1.572 (39.93)	-		
R-50C-SC	Solder Cup	1.242 (31.55)	1.572 (39.93)	—		
R-50C-WW-016	Wire Wrap	1.492 (37.88)	1.822 (46.28)	.250 post length016 sq.		
R-50C-WW-025	Wire Wrap	1.542 (39.17)	1.872 (47.55)	.300 post length025 sq.		
R-50C-DS	DuraSeal®	1.242 (31.55)	1.572 (39.93)	30 gage wire, vacuum sealed *		
R-50C-WT	Plug-In Receptacle	1.242 (31.55)	1.572 (39.93)	For use with FP-Plug plug-in terminal		
FP-Plug	Plug-In Terminal	_	_	Plugs into R-50C-WT receptacle *		

* Unless otherwise specified, wire length 36", strip length 1", 30 gage Kynar

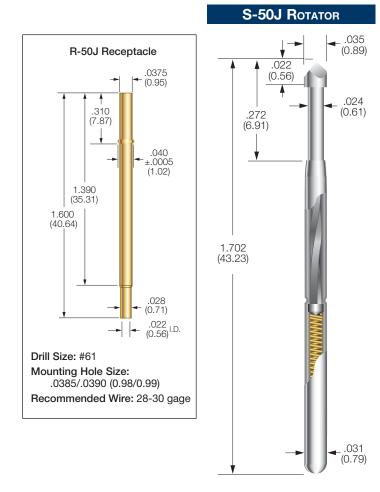


Specifications subject to change without notice. Dimensions in inches (millimeters)

58



.050 Centers S-50J Rotator



PROBE SPECIFICATIONS

Minimum Centers: .050 (1.27) Current Rating: 3 amps continuous

Spring Force: 3.6, 5.5, 7.0 or 10.0 oz. @ .170 (4.32) travel Typical Resistance: < 25 mΩ Maximum Travel: .250 (6.35) Working Travel: .170 (4.32) Rotates: 85° @ .170 (4.32) travel

Rated Force Preload Material						
oz. (g)	oz. (g)					
3.6 (102)	2.0 (57)	SS				
5.5 (156)	2.9 (82)	MW				
7.0 (198)	2.6 (74)	MW				
10.0 (284)	2.6 (74)	MW				

MATERIALS

Barrel: Nickel/silver, gold lined Spring: Stainless steel or music wire, gold plated

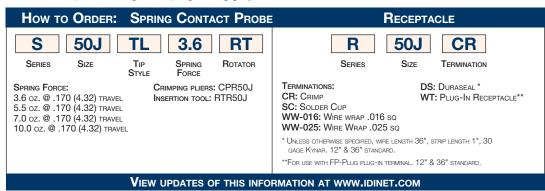
Plunger: Beryllium copper, Duralloy[™] plated

Receptacle: Beryllium copper, preplated gold, gold plated post

Plug-In Terminal: Beryllium copper, gold plated

RECEPTACLE OPTIONS					
Part Number	Style		Probe/Receptacle Combined Length		
R-50J-CR	Crimp	1.600 (40.64)	1.912 (48.56)	-	
R-50J-SC	Solder Cup	1.600 (40.64)	1.912 (48.56)	-	
R-50J-WW-016	Wire Wrap	1.850 (46.99)	2.162 (54.91)	.250 post length016 sq.	
R-50J-WW-025	Wire Wrap	1.900 (48.26)	2.212 (56.18)	.300 post length025 sq.	
R-50J-DS	DuraSeal®	1.600 (40.64)	1.912 (48.56)	30 gage wire, vacuum sealed*	
R-50J-WT	Plug-In Receptacle	1.600 (40.64)	1.912 (48.56)	For use with FP-Plug plug-in terminal	
FP-Plug	Plug-In Terminal	—	-	Plugs into R-50J-WT receptacle*	

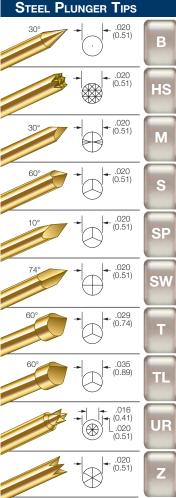
* Unless otherwise specified, wire length 36", strip length 1", 30 gage Kynar





ICT-50J and S-50J Size 50J - .050 Centers





PROBE SPECIFICATIONS

Minimum Centers: .050 (1.27) Current Rating: 3 amps continuous

Spring Force: 4.0, 5.6, 7.0 or 10.0 oz. @ .170 (4.32) travel Typical Resistance: < 20 mΩ for ICT-50J

< 25 mΩ for S-50J</p>
Maximum Travel: .250 (6.35)
Working Travel: .170 (4.32)

Rated Force oz. (g)	Preload oz. (g)	Material
4.0 (113)	1.8 (51)	SS
5.6 (159)	2.5 (71)	SS
7.0 (198)	3.1 (88)	MW
10.0 (283)	4.6 (130)	MW

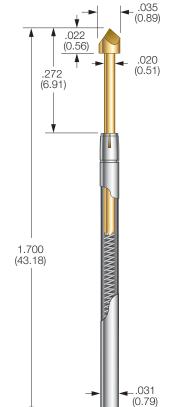
MATERIALS

Barrel: Nickel/silver, gold lined Spring: Music wire, nickel plated or stainless steel

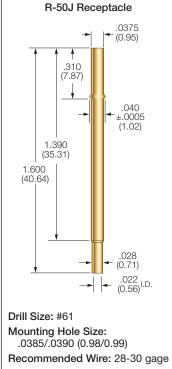
Plunger: Beryllium copper or steel, gold plated over nickel

Receptacle: Beryllium copper, preplated gold, gold plated post

Terminal: Beryllium copper, preplated gold



ICT-50J/S-50J PROBE



	RECEPTACLE OPTIONS					
Part Number	Style	Receptacle Length	Probe/Receptacle Combined Length	Comments		
R-50J-CR	Crimp	1.600 (40.64)	1.910 (48.51)	—		
R-50J-SC	Solder Cup	1.600 (40.64)	1.910 (48.51)	-		
R-50J-WW-016	Wire Wrap	1.850 (46.99)	2.160 (54.86)	.250 post length016 sq.		
R-50J-WW-025	Wire Wrap	1.900 (48.26)	2.210 (56.13)	.300 post length025 sq.		
R-50J-DS	Duraseal®	1.600 (40.64)	1.910 (48.51)	30 gage wire, vacuum sealed*		
R-50J-WT	Plug-In Receptacle	1.600 (40.64)	1.910 (48.51)	For use with FP-Plug plug-in terminal		
FP-Plug	Plug-In Terminal	_	—	Plugs into R-50J-WT receptacle *		
Unless otherwise specified, wire length 36", strip length 1", 30 gage Kynar						

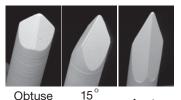
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How to Order: S	PRING CONTACT PROBE	RECEPTACLE			
ICT 50J T	5.6 DG S	R 50J CR			
Series Size Tip Style	Spring Plating Steel Force Options Plunger Option	Series Size Termination			
Series: Spring Force: ICT: High Performance 4.0 oz. @ .170 (4.32) travel S: Standard Performance, (No Bifurcated Beam) 5.6 oz. @ .170 (4.32) travel 7.0 oz. @ .170 (4.32) travel 10.0 oz. @ .170 (4.32) travel		TERMINATIONS: DS: DURASEAL* CR: CRIMP WT: PLUG-IN RECEPTACLE** SC: SOLDER CUP WW-016: WIRE WRAP .016 SQ WW-025: WIRE WRAP .025 SQ			
CRIMPING PLIERS: CPR50J INSERTION TOOL: RTR50J		* UNLESS OTHERWISE SPECIFIED, WIRE LENGTH 36", STRIP LENGTH 1", 30 gage Kynar. 12" & 36" standard. ** For use with FP-Plug plug-in terminal. 12" & 36" standard.			

VIEW UPDATES OF THIS INFORMATION AT WWW.IDINET.COM

OPTIMIZED TIP GEOMETRY FOR LEAD FREE TESTING

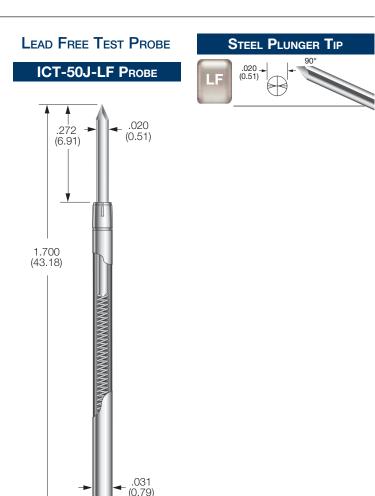
IDI has invested significantly in the discovery of the ideal tip for lead-free applications. IDI's research and testing laboratory, the industry's most advanced, developed a special test system which permitted IDI to compare the performance of various tip styles when cycled against matte tin, the most aggressive test contact material in terms of contamination and rapid tip wear. Through this process, the obtuse blade ('LF') tip showed itself to be by far the most reliable-its rugged shape retains its integrity far longer than more acute designs.



Obtuse 15° blade 3-sided chisel

Acute dagger

IDI's unique Duralloy[™] plating provides a clear advantage over competitors. Duralloy is noble and is exceptionally resistant to corrosion and oxidation. It remains bright and untarnished in atmospheric exposure. Duralloy is extremely smooth when plated and does not develop microcracks. It is very thick and completely nonporous. This surface greatly contributes to Duralloy's ability to resist corrosion and limit wear. Duralloy is slightly more resistive than gold, and is not recommended for extremely sensitive measurements.



PROBE SPECIFICATIONS

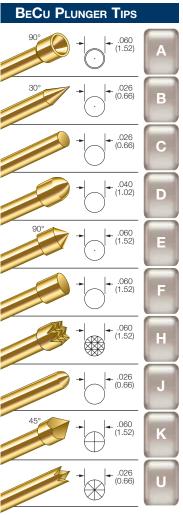
Minimum Centers: .050 (1.27) Current Rating: 3 amps continuous Spring Force: 7.0 oz. @ .170 (4.32) travel Typical Resistance: < 60 mΩ against a lead free surface Maximum Travel: .250 (6.35) Working Travel: .170 (4.32)

MATERIALS

Barrel: Nickel/silver, gold lined Spring: Music wire, nickel plated Plunger: Steel, Duralloy[™] plated

		Ноw то	Order		
ICT	50J	LF	7	DGD	S
SERIES	SIZE	Tip Style	SPRING FORCE	PLATING OPTIONS	STEEL Plunger

Series S Size 1 - .075 Centers



PROBE SPECIFICATIONS

Minimum Centers: .075 (1.91) Current Rating: 3 amps continuous

Spring Force: 2.0, 3.8 or 6.6 oz. @ .070 (1.78) travel Typical Resistance: < 25 mΩ Maximum Travel: .100 (2.54) Working Travel: .070 (1.78)

SS
SS
MW

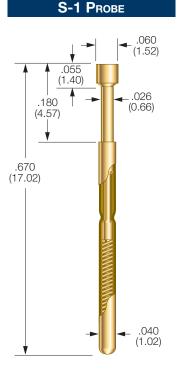
MATERIALS

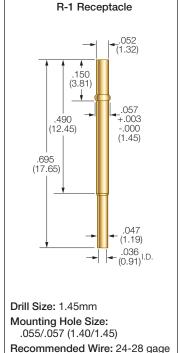
Barrel: Nickel/silver, gold plated

Spring: Stainless steel or music wire, gold plated

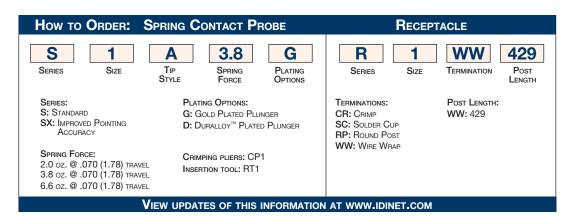
Plunger: Beryllium copper, gold plated over nickel or Duralloy[™]

Receptacle: Nickel/silver, gold plated, gold plated post





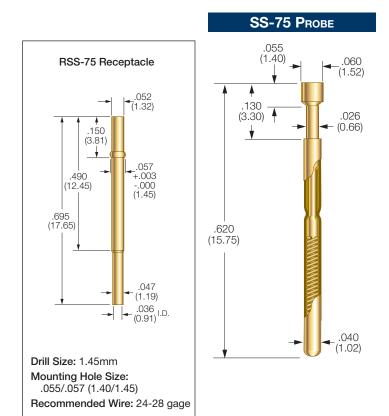
RECEPTACLE OPTIONS				
Part Number	Style	Receptacle Length	Probe/Receptacle Combined Length	Comments
R-1-CR	Crimp	0.695 (17.65)	0.875 (22.23)	-
R-1-SC	Solder Cup	0.695 (17.65)	0.875 (22.23)	-
R-1-RP	Round Post	1.070 (27.18)	1.250 (31.75)	.375 post length025 dia.
R-1-WW-429	Wire Wrap	1.124 (28.55)	1.304 (33.12)	.429 post length025 sq.



Specifications subject to change without notice. Dimensions in inches (millimeters)

IDI

.075 Centers - Size 75 Series SS



PROBE SPECIFICATIONS

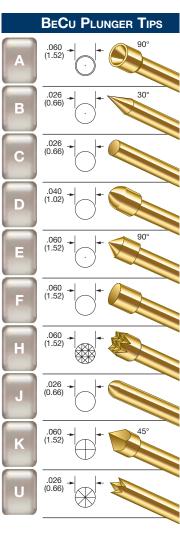
Minimum Centers: .075 (1.91) Current Rating: 3 amps continuous

Spring Force: 2.4 or 4.9 oz. @ .050 (1.27) travel Typical Resistance: < 25 mΩ Maximum Travel: .050 (1.27) Working Travel: .050 (1.27)

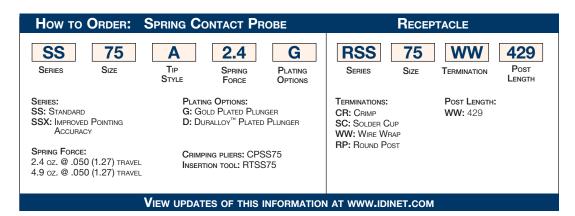
Rated Force oz. (g)	Preload oz. (g)	Material
2.4 (68)	1.7 (48)	SS
4.9 (139)	3.1 (88)	SS

MATERIALS

- Barrel: Nickel/silver, gold plated
- Spring: Stainless steel, gold plated
- Plunger: Beryllium copper, gold plated over nickel or Duralloy[™]
- Receptacle: Nickel/silver, gold plated, gold plated post



RECEPTACLE OPTIONS				
Part Number	Style	Receptacle Length	Probe/Receptacle Combined Length	Comments
RSS-75-CR	Crimp	0.695 (17.65)	0.825 (20.96)	_
RSS-75-SC	Solder Cup	0.695 (17.65)	0.825 (20.96)	_
RSS-75-RP	Round Post	1.070 (27.18)	1.200 (30.48)	.375 post length025 dia.
RSS-75-WW-429	Wire Wrap	1.124 (28.55)	1.254 (31.85)	.429 post length025 sq.



ICT-075 and S-075 Size 075 - .075 Centers



PROBE SPECIFICATIONS

Minimum Centers: .075 (1.91) Current Rating: 3 amps

continuous Spring Force: 3.0, 5.0, 7.0 or 10.0 oz. @ .170 (4.32)

travel Typical Resistance: < 25 mΩ Maximum Travel: .250 (6.35) Working Travel: .170 (4.32)

Rated Force oz. (g)	Preload oz. (g)
3.0* (85)	1.2 (34)
5.0 (142)	2.0 (57)
7.0 (198)	2.9 (82)
10.0 (283)	3.3 (94)
3.0 oz., S-075 only	

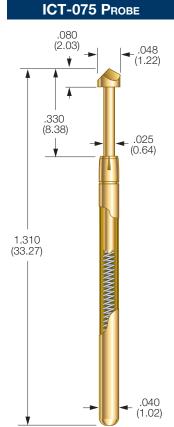
MATERIALS

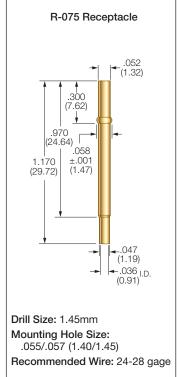
Barrel: G2

Spring: Music wire, nickel plated

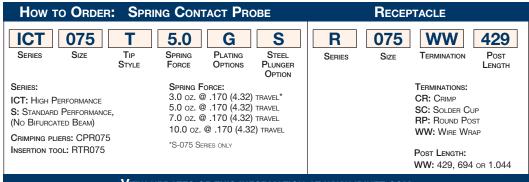
Plunger: Beryllium copper or steel, gold plated over nickel

Receptacle: Nickel/silver, gold plated; gold plated post



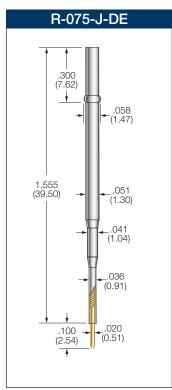


RECEPTACLE OPTIONS				
Part Number	Style	Receptacle Length	Probe/Receptacle Combined Length	Comments
R-075-CR	Crimp	1.170 (29.72)	1.500 (38.10)	—
R-075-SC	Solder Cup	1.170 (29.72)	1.500 (38.10)	-
R-075-RP	Round Post	1.545 (39.24)	1.875 (47.63)	.375 post length025 dia.
R-075-WW-429	Wire Wrap	1.599 (40.61)	1.929 (49.00)	.429 post length025 sq.
R-075-WW-694	Wire Wrap	1.864 (47.35)	2.194 (55.73)	.694 post length025 sq.
R-075-WW-1.044	Wire Wrap	2.214 (56.24)	2.544 (64.62)	1.044 post length025 sq.



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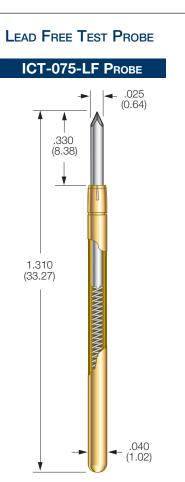
PROBE SPECIFICATIONS

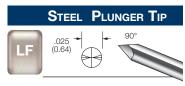
Minimum Centers: .075 (1.91) Drill Size: 1.45mm Mounting Hole Size: .055/.057 (1.40/1.45) Spring Force: 2.7 oz. (77g) @ .070 (1.77) travel Maximum Travel: .100 (2.54) Working Travel: .070 (1.77)

MATERIALS

Receptacle: Nickel/silver, gold lined inside Spring: Music wire, gold plated Plunger: Beryllium copper, gold plated over nickel

How to Order			
R	075	J	DE
SERIES	SIZE	Tip Style	PLATING OPTION





PROBE SPECIFICATIONS

Minimum Centers: .075 (1.91) Current Rating: 3 amps continuous Spring Force: 7.0 oz. @ .170 (4.32) travel Typical Resistance: < 40 m Ω against a lead free surface Maximum Travel: .250 (6.35) Working Travel: .170 (4.32)

MATERIALS

Barrel: G2 Spring: Music wire, nickel plated Plunger: Steel, Duralloy[™] plated

How to Order					
ICT	075	LF	7	D	S
SERIES	SIZE	TIP Style	SPRING FORCE	PLATING OPTIONS	STEEL Plunger

S-075 ROTATOR .075 CENTERS

BECU PLUNGER TIPS 90° + (1.22) 60° + (1.22) 60° + (0.74) (0.74) S

PROBE SPECIFICATIONS

Minimum Centers: .075 (1.91) Current Rating: 3 amps continuous

Spring Force: 3.8 or 6.6 oz. @ .170 (4.32) travel Typical Resistance: < 25 mΩ Maximum Travel: .225 (5.72) Working Travel: .170 (4.32) Rotates: 90° @ .170 (4.32) travel

Rated Force	Preload
oz (g)	oz (g)
3.8 (108)	0.5 (14)
6.6 (187)	1.6 (45)

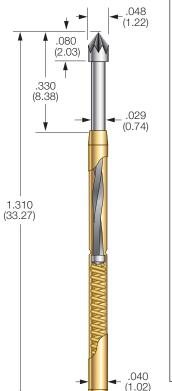
MATERIALS

Barrel: G2

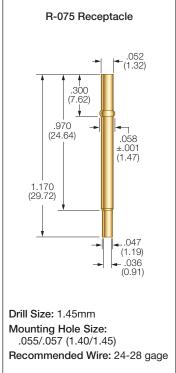
Spring: Music wire, gold plated

Plunger: Beryllium copper, Duralloy[™] plated

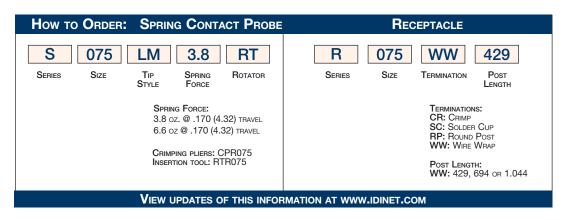
Receptacle: Nickel/silver, gold plated; gold plated post



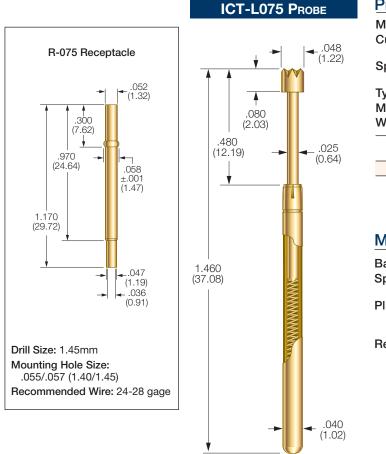
S-075-ROTATOR



RECEPTACLE OPTIONS				
Part Number	Style	Receptacle Length	Probe/Receptacle Combined Length	Comments
R-075-CR	Crimp	1.170 (29.72)	1.500 (38.10)	_
R-075-SC	Solder Cup	1.170 (29.72)	1.500 (38.10)	_
R-075-RP	Round Post	1.545 (39.24)	1.875 (47.63)	.375 post length025 dia.
R-075-WW-429	Wire Wrap	1.599 (40.61)	1.929 (49.00)	.429 post length025 sq.
R-075-WW-694	Wire Wrap	1.864 (47.35)	2.194 (55.73)	.694 post length025 sq.
R-075-WW-1.044	Wire Wrap	2.214 (56.24)	2.544 (64.62)	1.044 post length025 sq.



.075 CENTERS SIZE L075 ICT-L075



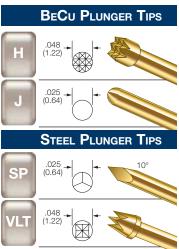
PROBE SPECIFICATIONS

Minimum Centers: .075 (1.91) Current Rating: 3 amps continuous Spring Force: 4.3 oz. @ .317 (8.05) travel Typical Resistance: < 15 m Ω Maximum Travel: .400 (10.16) Working Travel: .317 (8.05)

Rated Force	Preload
oz (g)	oz (g)
4.3 (122)	1.8 (51)

MATERIALS

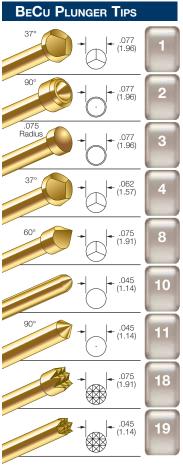
Barrel: G2
Spring: Music wire, gold plated
Plunger: Beryllium copper or steel, gold plated over nickel
Receptacle: Nickel/silver, gold plated; gold plated post



RECEPTACLE OPTIONS						
Part Number	Style	Receptacle Length	Probe/Receptacle Combined Length			
R-075-CR	Crimp	1.170 (29.72)	1.650 (41.91)	-		
R-075-SC	Solder Cup	1.170 (29.72)	1.650 (41.91)	-		
R-075-RP	Round Post	1.545 (39.24)	2.025 (51.44)	.375 post length025 dia.		
R-075-WW-429	Wire Wrap	1.599 (40.61)	2.079 (52.81)	.429 post length025 sq.		
R-075-WW-694	Wire Wrap	1.864 (47.35)	2.344 (59.54)	.694 post length025 sq.		
R-075-WW-1.044	Wire Wrap	2.214 (56.24)	2.694 (68.43)	1.044 post length025 sq.		

How to Order: Spring Contact Probe			RECEPTACLE						
	L075	Н	4.3	G	S	R	075	WW	429
SERIES	Size	TIP Style	SPRING FORCE	PLATING OPTIONS	Steel Plunger Option	SERIES	Size	TERMINATION	Post Length
	Spring Force:			TERMINATIONS:					
4.3 oz. @ .317 (8.05) TRAVEL					CR: CRIMF	b			
					SC: SOLDE	ER CUP			
CRIMPING PLIERS: CPR075					WW: WIRE	E WRAP			
INSERTION TOOL: RTR075					RP: ROUN	d Post			
								POST LENG	TH:
								WW: 429,	, 694 or 1.044
VIEW UPDATES OF THIS INFORMATION AT WWW.IDINET.COM									

SERIES SS & GSS .100 CENTERS



PROBE SPECIFICATIONS

Minimum Centers: .100 (2.54) Current Rating: 3 amps continuous

Spring Force: 3.8 or 7.0 oz. @ .050 (1.27) travel Typical Resistance: SS: < 65 mΩ

GSS: < 30 mΩ Maximum Travel: .060 (1.52) *for SS-8 .050 (1.27)

Working Travel: .050 (1.27)

oz (g)	Material
1.6 (45)	SS
1.3 (37)	MW
	1.6 (45)

MATERIALS

Barrel:

SS: Nickel/silver GSS: Nickel/silver, gold plated

Spring: SS: Stainless steel or music wire

GSS: Stainless steel or music wire, gold plated

Plunger: Beryllium copper, gold plated over nickel

Receptacle: Nickel/silver



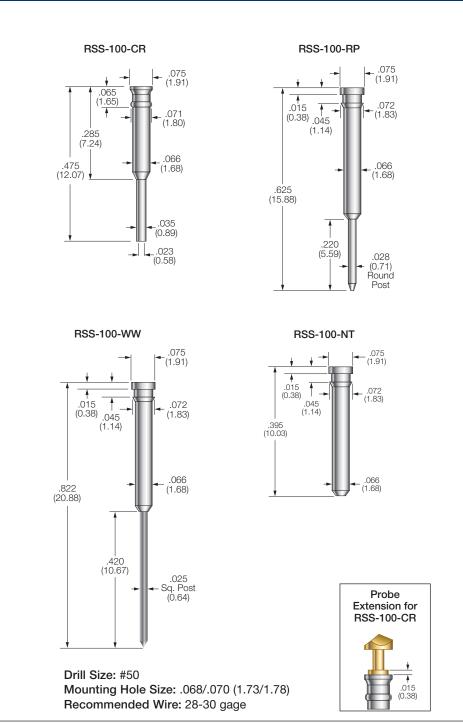
Head Length By Tip Style - SS & GSS Probe					
TIP	HEAD LENGTH	TIP	Head Length		
1	.040 (1.02)	10	.028 (0.71)		
2	.028 (0.71)	11	.040 (1.02)		
3	.028 (0.71)	18	.060 (1.52)		
4	.040 (1.02)	19	.055 (1.40)		
8	.080 (2.03)				

RECEPTACLE OPTIONS					
Part Number	Style	Receptacle Length	Probe/Receptacle Combined Length	Comments	
RSS-100-CR	Crimp	0.475 (12.07)	0.550 (13.97)*	-	
RSS-100-NT	No Tail	0.402 (10.21)	0.462 (11.73)*	-	
RSS-100-RP	Round Post	0.625 (15.88)	0.685 (17.40)*	.220 post length028 dia.	
RSS-100-WW	Wire Wrap	0.822 (20.88)	0.882 (22.40)*	.420 post length025 sq.	

* Plus head length per tip style from chart



RSS-100 Receptacles



R-SS/SS RECEPTACLE 150 (3.81) .345 (8.76) 4 .072 (1.83) .620 (15.75) .066 (1.68) .255 (6.48) t .100** (2.54)4 .850 (21.59).030 (0.76) ¥ 100° (2.54) * For plunger with .040 (1.02) tip length ** Headed plunger only this end **RECEPTACLE OPTIONS** Minimum Centers: .100 (2.54) Drill Size: #50 Mounting Hole Size: .068/.070 (1.73/1.78) MATERIALS

Standard Series: Nickel/silver

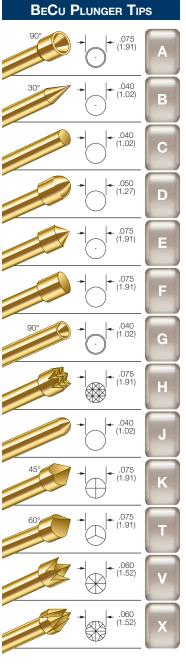
High Performance Series: Nickel/silver, gold plated

This receptacle houses an SS100 or GSS100 on each end.

How to Order

STANDARD SERIES: RS-SS/SS HIGH PERFORMANCE: R-SS/SS

Series S SIZE 2 .100 CENTERS



PROBE SPECIFICATIONS

Minimum Centers: .100 (2.54) Current Rating: 3 amps continuous

Spring Force: 4.0, 7.0, 8.3 or 10.0 oz. @ .100 (2.54) travel

Typical Resistance: < 35 mΩ Maximum Travel: .160 (4.06) Working Travel: .100 (2.54)

Rated Force	Preload	Material
oz (g)	oz (g)	
4.0 (113)	1.6 (45)	BeCu
7.0 (198)	2.9 (82)	SS
8.3 (235)	3.3 (93)	MW
10.0 (283)	3.9 (110)	MW

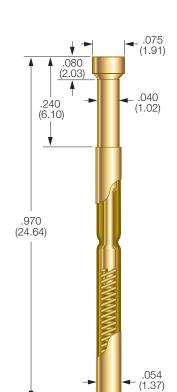
MATERIALS

Barrel: Nickel/silver, gold plated Spring: Beryllium copper, precious metal plated,

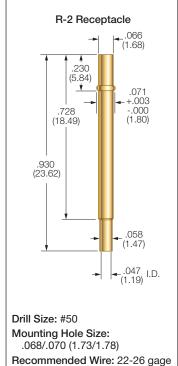
music wire or stainless steel, gold plated Plunger: Beryllium copper,

gold plated over nickel or Duralloy™

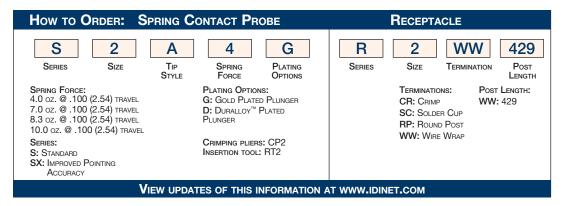
Receptacle: Nickel/silver, gold plated; gold plated post



S-2 PROBE



RECEPTACLE OPTIONS						
Part Number	Style	Receptacle Length	Probe/Receptacle Combined Length	Comments		
R-2-CR	Crimp	0.930 (23.62)	1.170 (29.72)	_		
R-2-SC	Solder Cup	0.930 (23.62)	1.170 (29.72)	-		
R-2-RP	Round Post	1.305 (31.15)	1.545 (39.24)	.375 post length025 dia.		
R-2-WW-429	Wire Wrap	1.359 (34.52)	1.599 (40.61)	.429 post length025 sq.		



Specifications subject to change without notice. Dimensions in inches (millimeters)

Interconnect Devices, Inc. welcomes your e-mail at info@idinet.com

Interface Probes

GENRAD INTERFACE PROBES

.855 GENRAD INTERFACE PROBE

.880 GenRad Interface Probe

SGR-2-B-4-G w/o bend

- GenRad 2270
- GenRad 2271
- GenRad 2272
- GenRad 2282

SPGR-2-B-4-G w/bend

- GenRad 2283
- GenRad 2284
- GenRad 2286
- GenRad 2287
- (models prior to 07/95)

SGR-2-B-3.7-G-880

w/o bend

- GenRad 2280
- GenRad 2281
- GenRad 2281A
- GenRad 2287A
- GenRad 228x ICA

SPGR-2-B-3.7-G-880

- GenRad 2283
- GenRad 2284
- GenRad 2286
- GenRad LX 228

(models prior to 07/95)



PROBE SPECIFICATIONS

Minimum Centers: .100 (2.54) Current Rating: 3 amps continuous Spring Force: 4.0 oz. @ .083 (2.10) travel

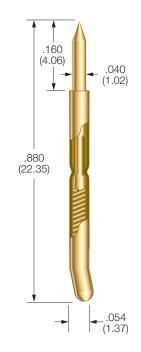
Preload Force: 1.3 (37g) Typical Resistance: < 25 mΩ Maximum Travel: .125 (3.18) Working Travel: .083 (2.10)

MATERIALS

 Barrel: Nickel silver, gold plated
 Spring: Beryllium copper, precious metal plated
 Plunger: Beryllium copper, gold plated over nickel

How to Order

SGR-2-B-4-G w/o BEND SPGR-2-B-4-G WITH BEND



PROBE SPECIFICATIONS

 $\begin{array}{l} \mbox{Minimum Centers: .100 (2.54)} \\ \mbox{Current Rating: 3 amps continuous} \\ \mbox{Spring Force: 3.7 oz. @ .107 (2.72)} \\ \mbox{travel} \\ \mbox{Preload Force: 1.4 (40g)} \\ \mbox{Typical Resistance: < 25 m} \\ \mbox{Maximum Travel: .160 (4.06)} \end{array}$

Working Travel: .107 (2.72)

MATERIALS

 Barrel: Nickel silver, gold plated
 Spring: Beryllium copper, precious metal plated
 Plunger: Beryllium copper, gold plated over nickel

How to Order

SGR-2-B-3.7-G-880 W/O BEND SPGR-2-B-3.7-G880 WITH BEND

ICT-100 and S-100 Size 100 .100 CENTERS



PROBE SPECIFICATIONS

Minimum Centers: .100 (2.54) Current Rating: 3 amps continuous

Spring Force: 3.5, 5.5, 6.7, 8.0, 10.0 or 17.0 oz. @.170 (4.32) travel

Typical Resistance: < 8 mΩ Maximum Travel: .250 (6.35) Working Travel: .170 (4.32)

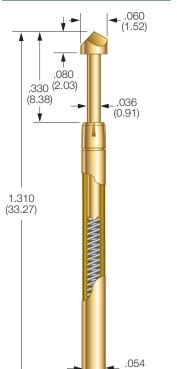
Rated Force oz (g)	Preload oz (g)	Material
3.5 (99)	1.5 (43)	BeCu*
5.5 (156)	2.4 (68)	MW**
6.7 (190)	2.8 (80)	SS
8.0 (227)	3.3 (94)	MW**
10.0 (283)	3.7 (105)	MW
17.0 (483)	6.8 (193)	MW
* 3.5 oz spring S-10	0 only ** BeC	Cu for S Series

MATERIALS

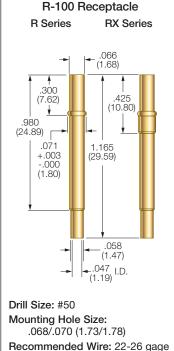
Barrel: G2

Spring: Beryllium copper, music wire, nickel plated or stainless steel

Plunger: Beryllium copper or steel, gold plated over nickel Receptacle: Nickel/silver, gold plated; gold plated post

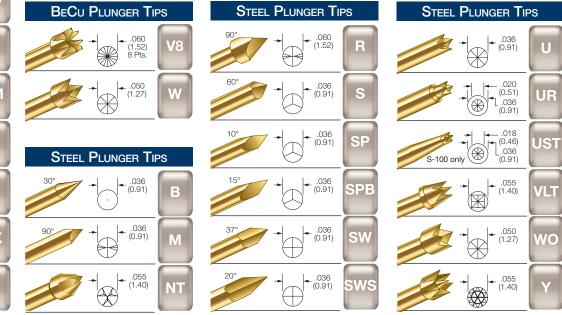


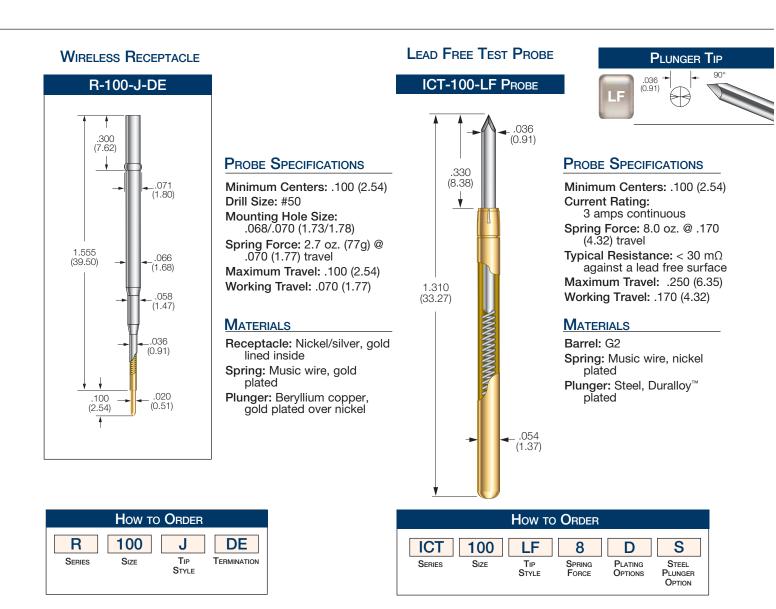
ICT-100 PROBE

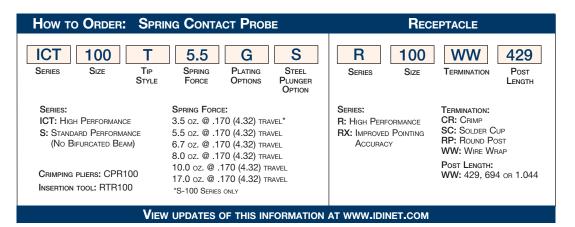


	RECEPTACLE OPTIONS				
Part Number	Style	Receptacle Length	Probe/Receptacle Combined Length	Comments	
R-100-CR	Crimp	1.165 (29.59)	1.495 (37.97)	_	
R-100-SC	Solder Cup	1.165 (29.59)	1.495 (37.97)	_	
R-100-RP	Round Post	1.540 (39.12)	1.870 (47.50)	.375 post length025 dia.	
R-100-WW-429	Wire Wrap	1.594 (40.49)	1.924 (48.87)	.429 post length025 sq.	
R-100-WW-694	Wire Wrap	1.859 (47.22)	2.189 (55.60)	.694 post length025 sq.	
R-100-WW-1.044	Wire Wrap	2.209 (56.11)	2.539 (64.49)	1.044 post length025 sq.	

(1.37)







S-100 Rotator .100 CENTERS



PROBE SPECIFICATIONS

Minimum Centers: .100 (2.54) Current Rating: 3 amps

continuous Spring Force: 4.0, 5.5, 6.7, 8.0 or 10.0 oz. @ .170 (4.32)

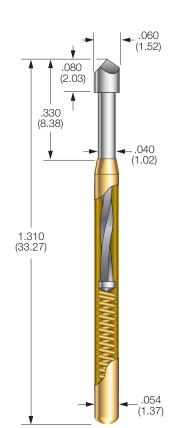
travel Typical Resistance: < 50 mΩ Maximum Travel: .220 (5.59) Working Travel: .170 (4.32) Rotates: 90° @ .170 (4.32) travel

Rated Force oz (g)	Preload oz (g)	Material
4.0 (113)	1.5 (43)	SS
5.5 (156)	2.0 (57)	SS
6.7 (190)	1.5 (43)	SS
8.0 (227)	2.8 (80)	MW
10.0 (283)	1.8 (51)	MW

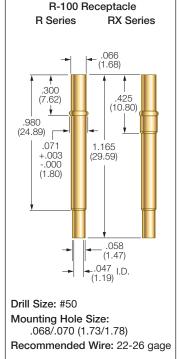
MATERIALS

Contact Barrel: G2

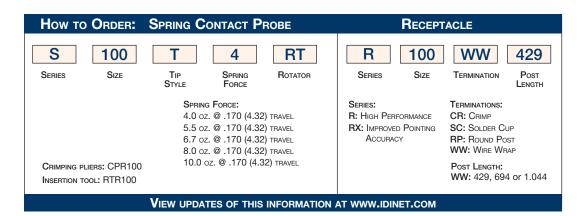
- Spring: Music wire or stainless steel, gold plated
- Plunger: Beryllium copper, Duralloy[™] plated
- Receptacle: Nickel/silver, gold plated; gold plated post



S-100 ROTATOR



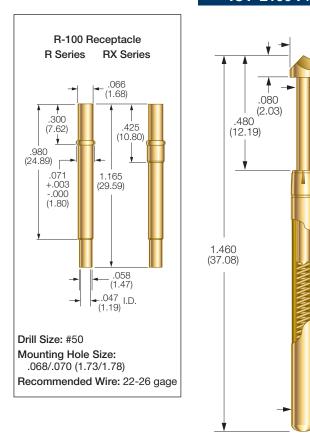
RECEPTACLE OPTIONS					
Part Number	Style	Receptacle Length	Probe/Receptacle Combined Length	Comments	
R-100-CR	Crimp	1.165 (29.59)	1.495 (37.97)	-	
R-100-SC	Solder Cup	1.165 (29.59)	1.495 (37.97)	-	
R-100-RP	Round Post	1.540 (39.12)	1.870 (47.50)	.375 post length025 dia.	
R-100-WW-429	Wire Wrap	1.594 (40.49)	1.924 (48.87)	.429 post length025 sq.	
R-100-WW-694	Wire Wrap	1.859 (47.22)	2.189 (55.60)	.694 post length025 sq.	
R-100-WW-1.044	Wire Wrap	2.209 (56.11)	2.539 (64.49)	1.044 post length025 sq.	



Specifications subject to change without notice. Dimensions in inches (millimeters)



.100 CENTERS SIZE L100 Series ICT



ICT-L100 PROBE

.060

(1.52)

.036

(0.91)

PROBE SPECIFICATIONS

Minimum Centers: .100 (2.54) Current Rating: 3 amps continuous Spring Force: 5.7 oz. @.317 (8.05) travel Typical Resistance: < 10 mΩ Maximum Travel: VLT tip: .385 (9.78) All others: .400 (10.16) Working Travel: .317 (8.05) Rated Force Preload

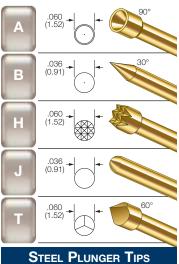
Rated Force	Preload
oz (g)	oz (g)
5.7 (162)	1.8 (51)

MATERIALS

Barrel: G2

Spring: Music wire, gold plated over nickel Plunger: Beryllium copper or steel, gold plated over nickel

Receptacle: Nickel/silver, gold plated; gold plated post



BECU PLUNGER TIPS

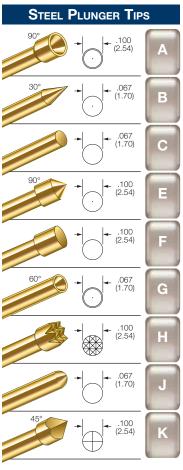


RECEPTACLE OPTIONS					
Part Number	Style	Receptacle Length	Probe/Receptacle Combined Length	Comments	
R-100-CR	Crimp	1.165 (29.59)	1.645 (41.78)	-	
R-100-SC	Solder Cup	1.165 (29.59)	1.645 (41.78)	-	
R-100-RP	Round Post	1.540 (39.12)	2.020 (51.31)	.375 post length025 dia.	
R-100-WW-429	Wire Wrap	1.594 (40.49)	2.074 (52.68)	.429 post length025 sq.	
R-100-WW-694	Wire Wrap	1.859 (47.22)	2.339 (59.41)	.694 post length025 sq.	
R-100-WW-1.044	Wire Wrap	2.209 (56.11)	2.689 (68.30)	1.044 post length025 sq.	

How to Order	SPRING CONTACT PROBE	RECEPTACLE
ICT L100	T 5.7 G S	R 100 WW 429
Series Size	TIP SPRING PLATING STEEL Style Force Options Plunger Option	Series Size Termination Post Length
	Spring Force: 5.7 oz. @ .317 (8.05) travel	Series: Terminations: R: High Performance CR: Crimp RX: Improved Pointing Accuracy, High Performance SC: Solder Cup WW: Wire Wrap RP: Round Post
	CRIMPING PLIERS: CPR100 INSERTION TOOL: RTR100	Розт Length: WW: 429, 694 or 1.044

V UPDATES OF THIS INFORMATION AT WWW.IDINET.COM

Series S SIZE 3 .125 CENTERS



PROBE SPECIFICATIONS

Minimum Centers: .125 (3.18) Current Rating: 5 amps continuous

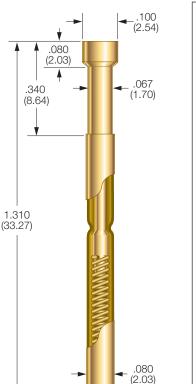
Spring Force: 4.0 or 7.0 oz. @ .170 (4.32) travel Typical Resistance: < 20 mΩ Maximum Travel: .250 (6.35) Working Travel: .170 (4.32)

Rat	ed Force oz (g)	Preload oz (g)	
4	.0 (113)	1.8 (51)	
7	.0 (198)	2.9 (82)	
-			

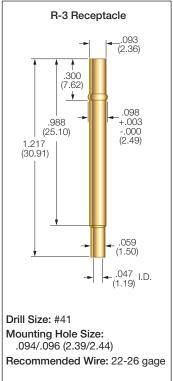
MATERIALS

Barrel: Nickel/silver, gold plated

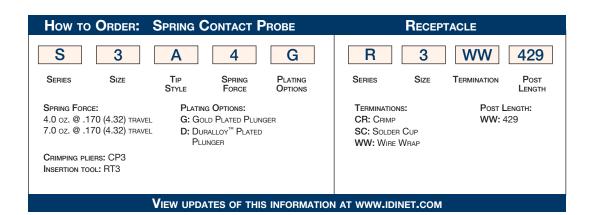
- Spring: Stainless steel, gold plated
- Plunger: Beryllium copper, gold plated over nickel or Duralloy
- Receptacle: Nickel/silver, gold plated, gold plated post



S-3 PROBE

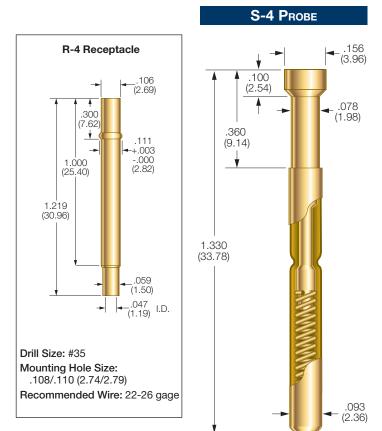


RECEPTACLE OPTIONS				
Part Number	Style	Receptacle Length	Probe/Receptacle Combined Length	Comments
R-3-CR	Crimp	1.217 (30.91)	1.539 (39.09)	-
R-3-SC	Solder Cup	1.217 (30.91)	1.539 (39.09)	_
R-3-WW-429	Wire Wrap	1.646 (41.81)	1.968 (49.99)	.429 post length025 sq.



Specifications subject to change without notice. Dimensions in inches (millimeters)

.156 OR .187 CENTERS SIZE 4 Series S



PROBE SPECIFICATIONS

Minimum Centers:

Tip Styles B, C, D, G, J, K .156 (3.96)
.150 (5.90)
Tip Styles A, E, F, H .187 (4.75)
Current Rating: 5 amps continuous
Spring Force: 5.0 or 7.0 oz. @ .170 (4.32) travel
Typical Resistance: < 20 mΩ
Maximum Travel: .250 (6.35)

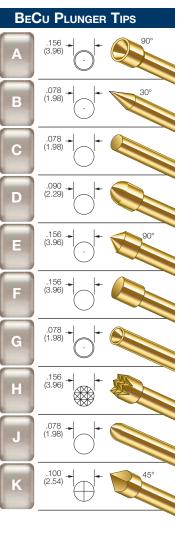
Rated Force oz (g)	Preload oz (g)
5.0 (142)	2.0 (57)
7.0 (198)	2.8 (79)

Working Travel: .170 (4.32)

MATERIALS

Barrel: Nickel/silver, gold plated

- Spring: Stainless steel, gold plated
- Plunger: Beryllium copper, gold plated over nickel or Duralloy™
- Receptacle: Nickel/silver, gold plated, gold plated post

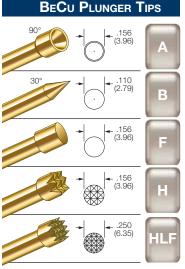


RECEPTACLE OPTIONS				
Part Number	Style	Receptacle Length	Probe/Receptacle Combined Length*	Comments
R-4-CR	Crimp	1.219 (30.96)	1.549 (39.34)	-
R-4-SC	Solder Cup	1.219 (30.96)	1.549 (39.34)	-
R-4-WW-429	Wire Wrap	1.648 (41.86)	1.978 (50.24)	.429 post length025 sq.

* Headless probes sit .020" deeper in receptacle. Dimension shown is for headed probe.



Series S Size 5 .187 CENTERS



PROBE SPECIFICATIONS

Minimum Centers: .187 (4.75) .275 (6.99) for HLF tip style Current Rating: 5 amps continuous

Spring Force: 8.0, or 16.4 oz. @ .170 (4.32) travel Typical Resistance: < 8 mΩ Maximum Travel: .250 (6.35) Working Travel: .170 (4.32)

Rated Force oz (g)	Preload oz (g)	Material
8.0 (227)	3.1 (88)	SS
16.4 (465)	2.8 (79)	MW

MATERIALS

plated Spring: Music wire or stainless

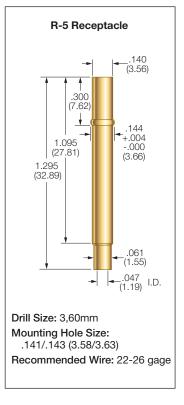
Barrel: Nickel/silver, gold

steel Plunger: Beryllium copper, gold plated over nickel or Duralloy™

Receptacle: Nickel/silver, gold plated, gold plated post



S-5 PROBE



RECEPTACLE OPTIONS				
Part Number	Style	Receptacle Length	Probe/Receptacle Combined Length	Comments
R-5-CR	Crimp	1.295 (32.89)	1.620 (41.15)	—
R-5-SC	Solder Cup	1.295 (32.89)	1.620 (41.15)	_
R-5-WW-429	Wire Wrap	1.724 (43.79)	2.049 (52.04)	.429 post length025 sq.



Specifications subject to change without notice. Dimensions in inches (millimeters)

Double Ended Interconnect Probes

.100

(2.54)

.520

(13.21)

.035

(0.89)

DE-100 PROBE

.062

.054

(1.37)

.066

(1.68)

.073

(1.85)

.054

(1.37)

033 (0.84) .100 .026 (2.54) .035 (0.66)(0.89).034 (0.86).520 (13.21) 025 .038 (0.64)(0.97) t .026 (0.66)

DE-50 PROBE

PROBE SPECIFICATIONS

Minimum Centers: .050 (1.27) Drill Size: #64 – .0350/.0365 (0.89/0.93) Current Rating: 3 amps continuous Spring Force: 2.0 oz. (57g) @ .050 (1.27) travel Typical Resistance: $< 50 \text{ m}\Omega$ Maximum Travel: .080 (2.03) Working Travel: .050 (1.27)

MATERIALS

Barrel: Nickel/silver, gold plated Spring: Music wire, gold plated Plunger: Beryllium copper, gold plated Contact: Beryllium copper, gold plated

MATERIALS

Barrel: Nickel/silver, gold plated Spring: Music wire, gold plated Plunger: Beryllium copper, gold plated Contact: Beryllium copper, gold plated

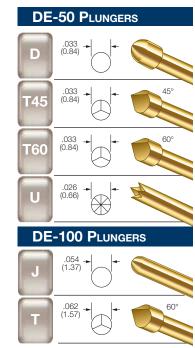
How to ORDER

DE-50-D-2-G DE-50-T45-2-G DE-50-T60-2-G DE-50-U-2-G

How to Order

DE-100-T-3-G DE-100-J-3-G

Specifications subject to change without notice. Dimensions in inches (millimeters)

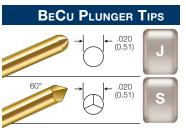


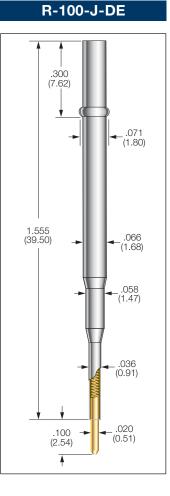
PROBE SPECIFICATIONS

.025 (0.64)

Minimum Centers: .100 (2.54) Drill Size: 1.75mm – .067/.069 (1.70/1.75) Current Rating: 3 amps continuous Spring Force: 3.0 oz. (85g) @ .050 (1.27) travel Typical Resistance: $< 50 \text{ m}\Omega$ Maximum Travel: .080 (2.03) Working Travel: .050 (1.27)

Wireless Receptacles





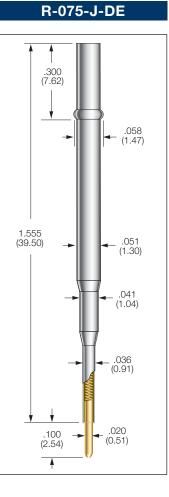
PROBE SPECIFICATIONS

Minimum Centers: .100 (2.54) Drill Size: #50 Mounting Hole Size: .068/.070 (1.73/1.78) Spring Force: 2.7 oz. (77g) @ .070 (1.77) travel

MATERIALS

- Receptacle: Nickel/silver, gold lined inside Spring: Music wire, gold plated
- Plunger: Beryllium copper, gold plated over nickel

R-100-DE: Uses ICT-100, S-100 or ICT-L100 probe



PROBE SPECIFICATIONS

Minimum Centers: .075 (1.91) Drill Size: 1.45mm Mounting Hole Size: .055/.057 (1.40/1.45) Spring Force: 2.7 oz. (77g) @ .070 (1.77) travel

MATERIALS

- Receptacle: Nickel/silver, gold lined inside
- Spring: Music wire, gold plated
- Plunger: Beryllium copper, gold plated over nickel R-075-DE: Uses ICT-075,
 - S-075 or ICT-L075 probe

.310 (7.87).040 (1.02)1 555 (39.50) .0375 (0.95) .516 033 (13.10) (0.84) 100 020 (2.54) (0.51) 4

R-50C-J-DE

PROBE SPECIFICATIONS

Minimum Centers: .050 (1.27) Drill Size: #61 Mounting Hole Size: .0385/.0390 (0.98/0.99) Spring Force: 2.7 oz. (77g) @ .070 (1.77) travel

MATERIALS

- Receptacle: Beryllium copper, gold plated Spring: Music wire, gold plated
- Plunger: Beryllium copper, gold plated over nickel
- R-50C-DE: Uses ICT-50C or S-50C probe

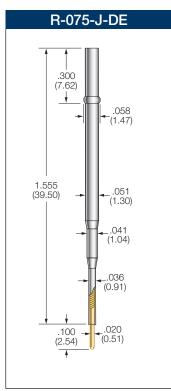
How to Order:			
R	100	J	DE
SERIES	Size	Tip Style	TERMINATION



How to Order:			
R Series	50C Size	J Tip Style	TERMINATION

Specifications subject to change without notice. Dimensions in inches (millimeters)





Minimum Centers: .075 (1.91) Drill Size: 1.45mm

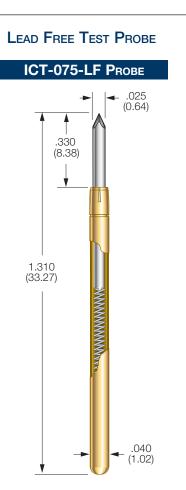
PROBE SPECIFICATIONS

Mounting Hole Size: .055/.057 (1.40/1.45) Spring Force: 2.7 oz. (77g) @ .070 (1.77) travel Maximum Travel: .100 (2.54) Working Travel: .070 (1.77)

MATERIALS

Receptacle: Nickel/silver, gold lined inside Spring: Music wire, gold plated Plunger: Beryllium copper, gold plated over nickel

How to Order			
R	075	J	DE
SERIES	Size	Tip Style	PLATING OPTION





PROBE SPECIFICATIONS

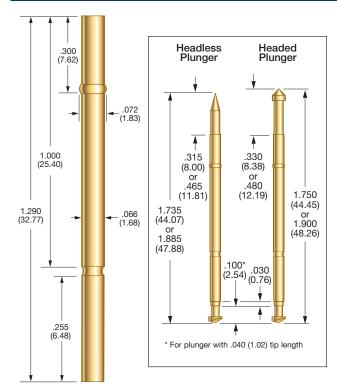
Minimum Centers: .075 (1.91) Current Rating: 3 amps continuous Spring Force: 7.0 oz. @ .170 (4.32) travel Typical Resistance: < 40 m Ω against a lead free surface Maximum Travel: .250 (6.35) Working Travel: .170 (4.32)

MATERIALS

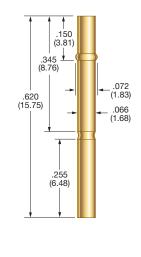
Barrel: G2 Spring: Music wire, nickel plated Plunger: Steel, Duralloy[™] plated

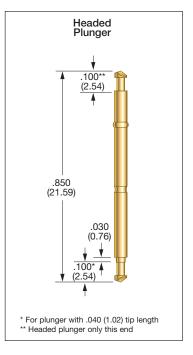


R-100/SS



R-SS/SS





RECEPTACLE SPECIFICATIONS

Minimum Centers: .100 (2.54) Drill Size: #50 Mounting Hole Size: .068/.070 (1.73/1.78)

MATERIALS

High Performance Series: Nickel/silver, gold plated Standard Series: Nickel/silver This receptacle houses a S-100, ICT-100 or ICT-L100 probe on the top end and an SS100 or GSS100 probe on the bottom end.

RECEPTACLE SPECIFICATIONS

Minimum Centers: .100 (2.54) Drill Size: #50 Mounting Hole Size: .068/.070 (1.73/1.78)

MATERIALS

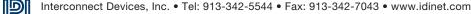
High Performance Series: Nickel/silver, gold plated Standard Series: Nickel/silver This receptacle houses an SS100 or GSS100 probe on each end.

How to ORDER

R-100/SS High Performance Series RS-100/SS Standard Series

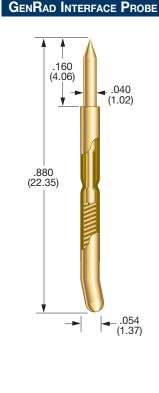
How to ORDER

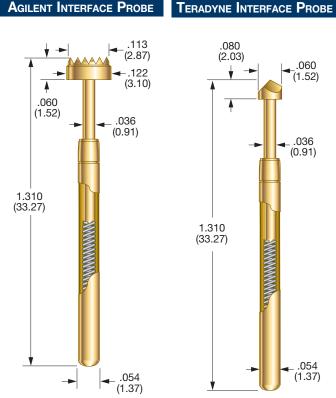
R-SS/SSHigh Performance SeriesRS-SS/SSStandard Series

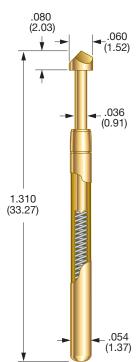


Interface Probes









PROBE SPECIFICATIONS

PROBE SPECIFICATIONS

Minimum Centers: .100 (2.54) Current Rating: 3 amps continuous Spring Force: 4.0 oz. (113g) @ .083 (2.10) travel Preload Force: 1.3 (37g) Typical Resistance: < 25 mΩ Maximum Travel: .125 (3.18) Working Travel: .083 (2.10)

MATERIALS

- Barrel: Nickel silver, gold plated
- Spring: Beryllium copper, precious metal plated Plunger: Beryllium copper, gold plated over nickel

How to ORDER

SGR-2-B-4-G W/O BEND For use in GenRad 2270, 2271, 2272, 2282

SPGR-2-B-4-G WITH BEND For use in GenRad 2283, 2284, 2286, 2287 - models prior to 7/95

Minimum Centers: .100 (2.54) Current Rating: 3 amps continuous

Spring Force: 3.7 oz. (105g) @ .107 (2.72) travel Preload Force: 1.4 (40g) Typical Resistance: < 25 mΩ Maximum Travel: .160 (4.06) Working Travel: .107 (2.72)

MATERIALS

- Barrel: Nickel silver, gold plated
- Spring: Beryllium copper, precious metal plated Plunger: Beryllium copper,
- gold plated over nickel

How to ORDER

SGR-2-B-3.7-G-880 W/O BEND For use in GenRad 2280, 2281, 2281A, 2287A, 228x ICA

SPGR-2-B-3.7-G-880 WITH BEND For use in GenRad 2283, 2284, 2286, 2287, LX228 - models prior to 7/95

PROBE SPECIFICATIONS

Minimum Centers: .150 (3.81) Current Rating: 3 amps continuous Spring Force: 3.5 oz. (99g) @ .170 (4.32) travel Preload Force: 1.5 (43g) Typical Resistance: < 25 mΩ Maximum Travel: .250 (6.35) Working Travel: .170 (4.32)

MATERIALS

Barrel: G2 Spring: Beryllium copper, precious metal plated Plunger: Beryllium copper, gold plated over nickel

How to ORDER

S-100-HP-3.5-G For use in HP 3070, Series I and Series III

PROBE SPECIFICATIONS

Minimum Centers: .100 (2.54) Current Rating: 3 amps continuous Spring Force: 3.5 oz. (99g) @ .170 (4.32) travel Preload Force: 1.5 (43g) Typical Resistance: < 25 mΩ Maximum Travel: .250 (6.35) Working Travel: .170 (4.32)

MATERIALS

Barrel: G2 Spring: Beryllium copper, precious metal plated Plunger: Beryllium copper,

gold plated over nickel

How to Order

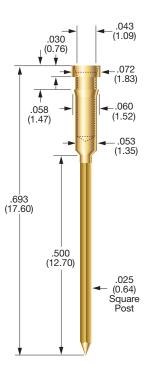
S-100-T-3.5-G For use in 1800, Series 7878

Specifications subject to change without notice. Dimensions in inches (millimeters)

IDI

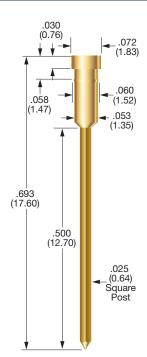
Interface Pins

PI-301



PIN SPECIFICATIONS

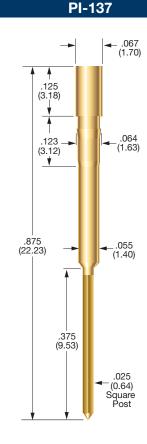
Drill Size: 1.45mm Mounting Hole: .057 (1.45)



PI-410

PIN SPECIFICATIONS

Drill Size: 1.45mm Mounting Hole: .057 (1.45)



PIN SPECIFICATIONS

Drill Size: 1.55mm Mounting Hole: .061 (1.55)

MATERIALS

Material: Brass Plating: Gold over nickel

MATERIALS

Material: Brass Plating: Gold over nickel

How to ORDER

MATERIALS

Material: Brass Plating: Gold over nickel

How to Order

PI-410

How to Order PI-137

PI-301

SH-100 and SHE-100 .100 CENTERS

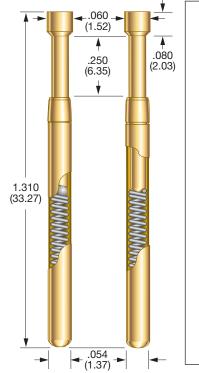


.060 (1.52)

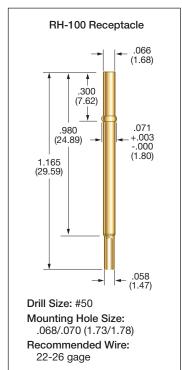
F

PROBE SPECIFICATIONS SH-100 Minimum Centers: .100 (2.54) Current Rating: SHE-100: 8 amps continuous SH-100: 15 amps continuous (Individual probe in free air @ ambient temperature) Spring Force: 4.0 oz. or 6.7 oz. @ .170 (4.32) travel Maximum Travel: .250 (6.35) Working Travel: .170 (4.32) **Rated Force** Preload oz. (g) oz. (g) 1.310 4.0* (113) 1.6 (45) (33.27)6.7 (190) 2.4 (68) * SH-100 only MATERIALS Barrel: High performance copper alloy, gold plated Spring: Stainless steel Plunger: Beryllium copper, gold plated

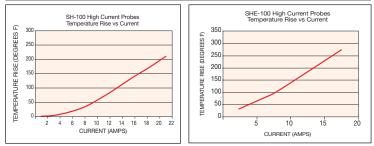
Ball: SH probe: Stainless steel Receptacle: Copper alloy, gold plated



SHE-100

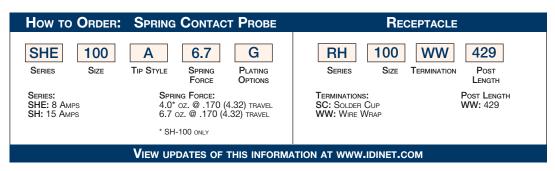


.100 CENTER HIGH CURRENT PROBES



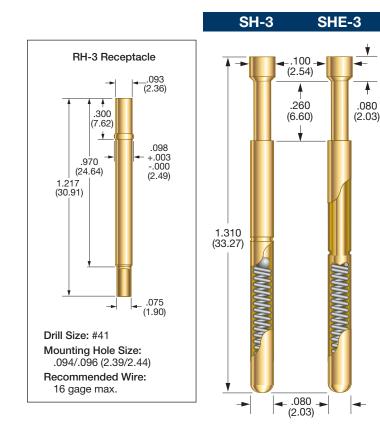
IDI current ratings are defined as the maximum current at which the temperature rise of the probe does not exceed 144°F (80°C) for a single probe in free air at ambient temperature for one hour.

RECEPTACLE OPTIONS				
Part Number	Style	Receptacle Length	Probe/Receptacle Combined Length	Comments
RH-100-SC	Solder Cup	1.165 (29.59)	1.495 (37.97)	-
RH-100-WW-429	Wire Wrap	1.594 (40.49)	1.924 (48.87)	.429 post length025 sq.



Specifications subject to change without notice. Dimensions in inches (millimeters)

.125 CENTERS SH-3 and SHE-3



PROBE SPECIFICATIONS

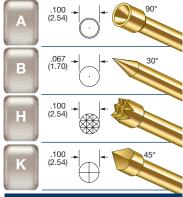
Minimum Centers: .125 (3.18) Current Rating: SHE-3: 14 amps continuous SH-3: 27 amps continuous (Individual probe in free air @ ambient temperature) Spring Force: 7.0 oz. @ .170 (4.32) travel Maximum Travel: .250 (6.35) Working Travel: .170 (4.32)

Rated Force	Preload
oz. (g)	oz. (g)
7.0 (199)	2.9 (82)

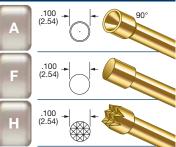
MATERIALS

Barrel: High performance copper alloy, gold plated Spring: Stainless steel Plunger: Beryllium copper, gold plated Ball: SH probe: Stainless steel Receptacle: Copper alloy, gold plated

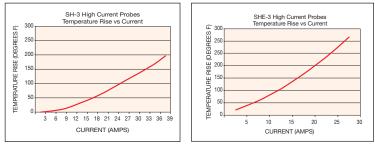




SH-3 PLUNGER TIPS



.125 CENTER HIGH CURRENT PROBES



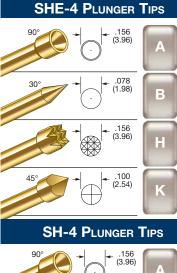
IDI current ratings are defined as the maximum current at which the temperature rise of the probe does not exceed 144°F (80°C) for a single probe in free air at ambient temperature for one hour.

RECEPTACLE OPTIONS				
Part Number	Style	Receptacle Length	Probe/Receptacle Combined Length	Comments
RH-3-SC	Solder Cup	1.217 (30.91)	1.539 (39.09)	—

How to Or	How to Order: Spring Contact Probe		RECEPTACLE
SHE	3	A 7 G	RH 3 SC
SERIES	SIZE	TIP SPRING PLATING STYLE FORCE OPTIONS	SERIES SIZE TERMINATION
SERIES: SHE: 14 AMPS SH: 27 AMPS			TERMINATIONS: SC: Solder Cup
	VIEW UPDATES OF THIS INFORMATION AT WWW.IDINET.COM		

SH-4 and SHE-4 .156 AND .187 CENTERS

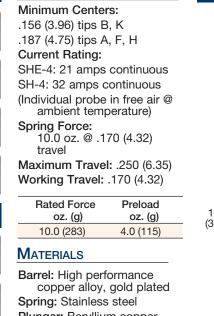
PROBE SPECIFICATIONS



.156 (3.96)

.156

(3.96)



Plunger: Beryllium copper, gold plated Ball: SH probe: Stainless steel Receptacle: Copper alloy,

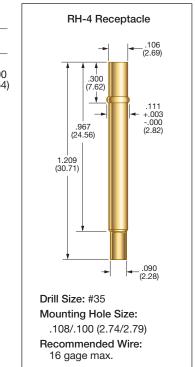
gold plated

156 (3.96) 100 .260 (2.54)(6.60)1.330 (33.78) .093

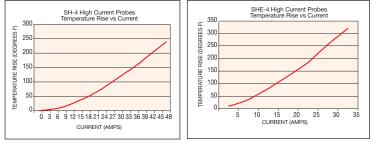
(2.36)

SH-4

SHE-4



.156 AND .187 CENTER HIGH CURRENT PROBES



->

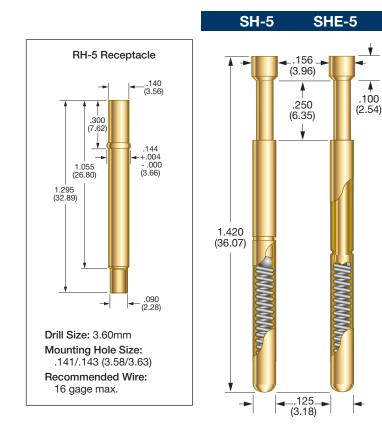
IDI current ratings are defined as the maximum current at which the temperature rise of the probe does not exceed 144°F (80°C) for a single probe in free air at ambient temperature for one hour.

RECEPTACLE OPTIONS				
Part Number	Style	Receptacle Length	Probe/Receptacle Combined Length	Comments
RH-4-SC	Solder Cup	1.209 (30.71)	1.539 (39.09)	-

How to Order:	SPRING CONTACT PROBE	Receptacle
SHE 4 SERIES SIZE	A 10 G TIP SPRING FORCE PLATING OPTIONS	RH 4 SC Series Size Termination
SERIES: SHE: 21 Amps SH: 32 Amps		TERMINATIONS: SC: Solder Cup
VIEW UPDATES OF THIS INFORMATION AT WWW.IDINET.COM		

Specifications subject to change without notice. Dimensions in inches (millimeters)

.187 CENTERS SH-5 and SHE-5



PROBE SPECIFICATIONS

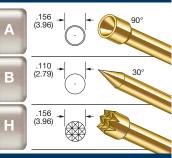
Minimum Centers: .187 (4.75) Current Rating: SHE-5: 23 amps continuous SH-5: 39 amps continuous (Individual probe in free air @ ambient temperature) Spring Force: 18.7 oz. @ .170 (4.32) travel Maximum Travel: .250 (6.35) Working Travel: .170 (4.32)

Rated Force	Preload
oz. (g)	oz. (g)
18.7 (531)	7.2 (204)

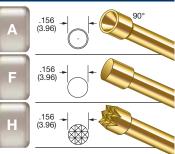
MATERIALS

Barrel: High performance copper alloy, gold plated Spring: Stainless steel Plunger: Beryllium copper, gold plated Ball: SH probe: Stainless steel Receptacle: Copper alloy, gold plated

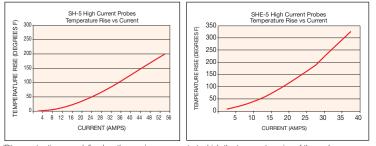
SHE-5 PLUNGER TIPS



SH-5 PLUNGER TIPS



.187 CENTER HIGH CURRENT PROBES



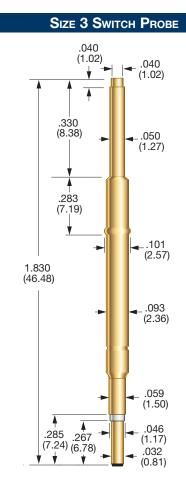
IDI current ratings are defined as the maximum current at which the temperature rise of the probe does not exceed 144°F (80°C) for a single probe in free air at ambient temperature for one hour.

RECEPTACLE OPTIONS				
Part Number	Style	Receptacle Length	Probe/Receptacle Combined Length	Comments
RH-5-SC	Solder Cup	1.295 (32.89)	1.620 (41.15)	_

How to Order: Spring Contact Probe	Receptacle
SHE 5 A 18.7 G Series Size Tip STYLE Spring Force PLATING OPTIONS Series: SHE: 23 AMPS SH: 39 AMPS SH: 39 AMPS	RH 5 SC SERIES SIZE TERMINATION TERMINATIONS: SC: SOLDER CUP
VIEW UPDATES OF THIS INFORMATION AT W	/ww.idinet.com

Switch Probes

The most common use for Switch Probes is in the cable harness testing industry. The Switch Probe is used to verify the correct location of a terminal in a connector while also checking the retention force. In addition. Switch Probes also verify the presence of non conductive components such as caps for connectors or devices on a circuit board. There are two separate current paths in a Switch Probe. From the plunger tip to the tail is normally open and closes only after the probe deflects to the designated travel. The second path, from the plunger tip to the outside of the receptacle, is always closed.



PROBE SPECIFICATIONS

Minimum Centers: .125 (3.18) Current Rating: 3 amps continuous Maximum Travel: .295 (7.49) Working Travel: .197 (5.00) Travel to Switch Point: .025 (0.64) Spring Force at Switch Point: 1.8 oz.

Rated Force	Rated Force @ Switch	Preload
oz. (g)	oz. (g)	oz. (g)
4.0 (114)	1.8 (51)	1.4 (40)

MATERIALS

Barrel: Nickel/silver, gold plated Spring: Music wire Plungers: Full-hard beryllium copper, gold plated Insulator: Delrin Contact: Beryllium copper, gold plated

MOUNTING

Drill Size: #41

Mounting Hole Size: .094/.096 (2.39/2.44) The size 3 switch probe shown does not require a receptacle. The barrel of the switch probe is designed to mount directly in the mounting plate.

Specifications subject to change without notice. Dimensions in inches (millimeters)

(1.99).265 (6.73).093 .425 (2.36)(10.80)¥ 1.930 (49.02) .093 (2.36).046 (1.17)535 (13.59)1 .275 (6.99).032 (0.81) ¥

SIZE 4 SWITCH PROBE

0785

PROBE SPECIFICATIONS

Minimum Centers: .156 (3.96)
Current Rating: 3 amps continuous
Maximum Travel: .160 (4.06)
Working Travel: .120 (3.05)
Travel to Switch Point: .107 (2.72)
Spring Force at Switch Point: 4.4 oz.

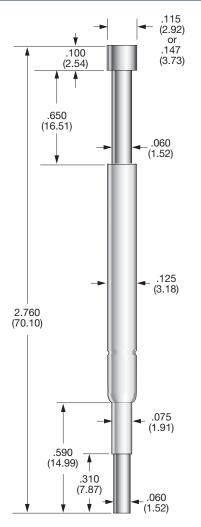
Rated Force	Rated Force @ Switch	Preload
oz. (g)	oz. (g)	oz. (g)
4.8 (136)	4.4 (125)	2.5 (71)

MATERIALS

Barrel: Nickel/silver, gold plated Spring: Stainless steel Plunger: Beryllium copper, nickel plated Insulator: Delrin Contact: Beryllium copper, gold plated

IDI





PROBE SPECIFICATIONS

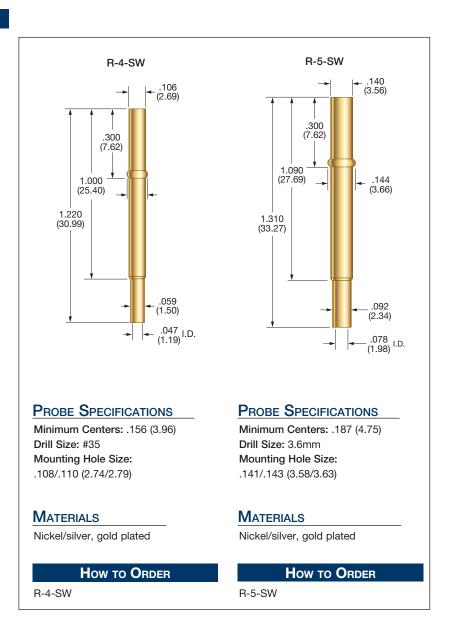
Minimum Centers: .187 (4.75) Current Rating: 3 amps continuous Maximum Travel: .190 (4.83) Working Travel: .137 (3.48) Travel to Switch Point: .030 (0.76) Spring Force at Switch Point: 4.0 or 10.3 oz.

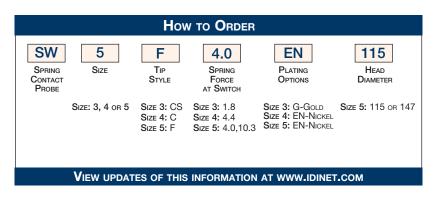
Rated Force oz. (g)	Force @ Switch oz. (g)	Preload oz. (g)	Material
8.6 (244)	4.0 (113)	1.8 (51)	SS
20.4 (579)	10.3 (293)	5.2 (148)	MW
20.4 (010)	10.0 (200)	0.2 (140)	14144

MATERIALS

Barrel: Nickel/silver, silver plated Spring: Music wire or stainless steel Plunger: Beryllium copper, nickel plated Insulator: Delrin

Contact: Beryllium copper, nickel plated





Thermocouple Probe

The Thermocouple Probe is an ungrounded, thermally conductive probe used for the measurement of variations in temperature. This probe is ideal for applications such as thermostat testing, semiconductor testing (burn-in), or any application in which accurate local temperature data is needed.

TEMPERATURE RANGE

Type T – up to 220° F

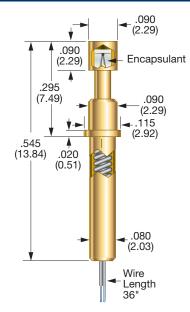
Type K- up to 350° F

THERMOCOUPLE PROBE DESIGN

The Thermocouple Probe's unique design insures that the wires are internally fixed. This is done to prevent the two thermocouple wires from becoming dislodged from the plunger head cavity. This result is increased durability, which extends the service life of the probe.

- The plunger material is gold plated over full hard beryllium copper
- Thes pring force is 3.0 oz. @ .060" rated travel
- The barrel is gold plated over brass.
- The plunger head cavity is filled with a thermally conductive, electrically insulative epoxy, encapsulating the thermocouple tip. The insulative epoxy allows for more efficient flow of heat to the thermocouple tip for faster temperature readings, while insulating it from electrical interference.

100895 THERMOCOUPLE PROBE



PROBE SPECIFICATIONS

Minimum Centers: .156 (3.96) Spring Force: 3.0 oz. @ .060 (1.52) travel Maximum Travel: .060 (1.52) Working Travel: .060 (1.52) Temperature Range: Type T: up to 220° F Type K: up to 350° F

MATERIALS

Barrel: Brass, gold plated Spring: Stainless steel Plunger: Brass, gold plated Tip: Beryllium copper, gold plated Encapsulant: Thermally conductive, electrically insulative epoxy Wire: 36 Gage Type T - Red & Blue Type K - Red & Yellow

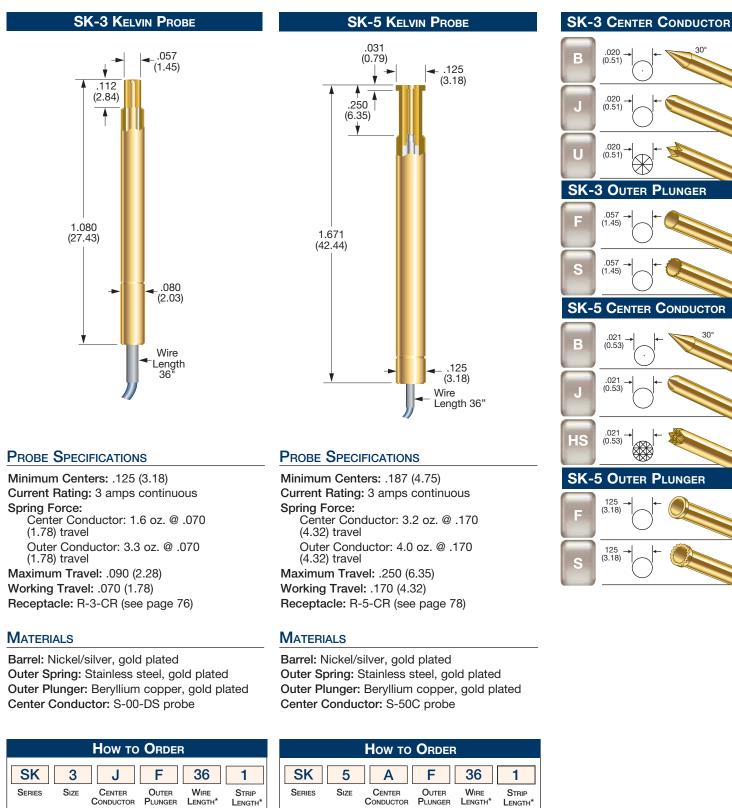
How to ORDER

100895-000: for Type K 100895-002: for Type T

Specifications subject to change without notice. Dimensions in inches (millimeters)



Kelvin Probes



Specifications subject to change without notice. Dimensions in inches (millimeters)

LENGTH

PLUNGER

S: SERRATED

* WIRE LENGTH 36", STRIP LENGTH 1". 12" & 36" STANDARD.

F: FLAT

LENGTH

I ENGTH

LENGTH

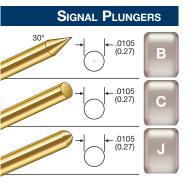
F: FLAT

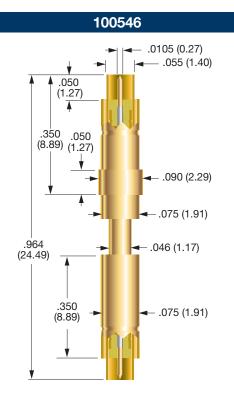
S: SERRATED

* WIRE LENGTH 36", STRIP LENGTH 1", 12" & 36" STANDARD

CONDUCTOR

Coax Probes DOUBLE ENDED





PROBE SPECIFICATIONS

Minimum Centers: .100 (2.54) Current Rating: 0.5 amps continuous Spring Force:

Signal Conductor: 1.1 oz. @ .023 (0.58) travel, each end Shielding Plunger:

2.2 oz. @ .023 (0.58) travel, each end Nominal Impedance: 50 Ω Maximum Travel: .050 (1.27), each end Working Travel: .023 (0.58), each end

MATERIALS

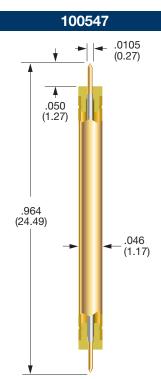
Barrel: Brass, gold plated Spring:

Signal Conductor: Music wire, gold plated Shielding Plunger: Music wire, gold plated Shielding Plunger: Copper alloy, gold plated Isolation Plug: Torlon

Dielectric Insulator: Air

Shielding Tube: Stainless steel, gold plated Signal Conductor: Special Quad-0 probe

How to Order			
100546	В	В	F
Base Part Number	Top Signal Probe Tip		Mounting Flange



PROBE SPECIFICATIONS

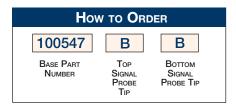
Minimum Centers: .070 (1.78) Current Rating: 0.5 amps continuous Spring Force:

Signal Conductor:

1.1 oz. @ .023 (0.58) travel, each end Nominal Impedance: 50 Ω Maximum Travel: .050 (1.27), each end Working Travel: .023 (0.58), each end

MATERIALS

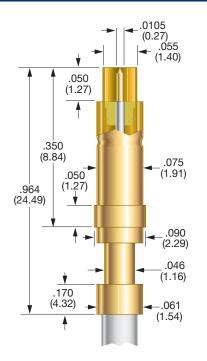
Spring: Music wire, gold plated Isolation Plug: Torlon Dielectric Insulator: Air Shielding Tube: Stainless steel, gold plated Signal Conductor: Special Quad-0 probe

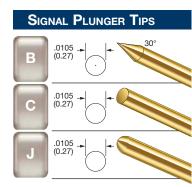


Specifications subject to change without notice. Dimensions in inches (millimeters)

ATTACHED CABLE COax Probe

100780





PROBE SPECIFICATIONS

Minimum Centers: .100 (2.54) Current Rating: 0.5 amps continuous Spring Force: Signal Conductor: 1.1 oz. @ .045 (1.14) travel Shielding Plunger: 2.2 oz. @ .023 (0.58) travel Nominal Impedance: 50 Ω Maximum Travel: .050 (1.27) Working Travel: .023 (0.58)

MATERIALS

Barrel: Brass, gold plated
Shielding Plunger: Beryllium copper, gold plated
Springs: Signal Conductor: Music wire, gold plated Shielding Plunger: Music wire, gold plated
Isolation Plug: Torlon
Dielectric Insulator: Air
Shielding Tube: Stainless steel, gold plated
Signal Conductor: Special Quad 0 probe

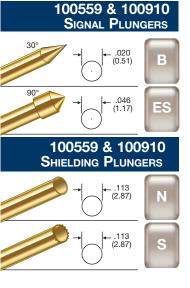
Coaxial Cable: Semi-rigid cable

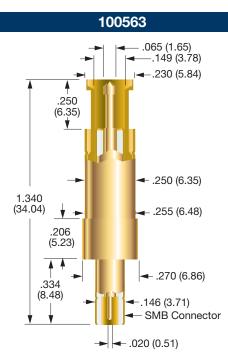
How to Order				
100780	BF	12 AM		
Base Part Number	Signal Mounting Probe Flange Tip	CABLE TERMINATION LENGTH		
	CABLE LENGTH:	AM: SMA MALE		
	12 - 12 INCHES	AF: SMA FEMALE		
	36 - 36 INCHES	NC: NO CONNECTOR		

* WHEN ORDERING WITH A PREATTACHED CONNECTOR, PLEASE NOTE THAT THE CONNECTOR WILL NOT FIT THROUGH THE PROBE MOUNTING HOLE. THE PROBE MUST BE INSERTED FROM THE BOTTOM SIDE OF THE MOUNTING PLATE.

CONSULT IDI FOR MORE INFORMATION.

Coax Probes SMB CONNECTOR



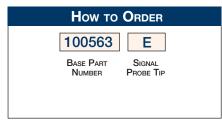


PROBE SPECIFICATIONS

 $\begin{array}{l} \mbox{Minimum Centers: } .300 \ (7.62) \\ \mbox{Current Rating: 3 amps continuous} \\ \mbox{Spring Force:} \\ \mbox{Signal Conductor:} \\ \mbox{2.3 oz. @.107 (2.72) travel} \\ \mbox{Shielding Plunger:} \\ \mbox{5.8 oz. @.107 (2.72) travel} \\ \mbox{Nominal Impedance: 50 Ω} \\ \mbox{Maximum Travel: .170 (4.32)} \\ \mbox{Working Travel: .107 (2.72)} \end{array}$

MATERIALS

Barrel: Brass, gold plated Spring: Signal Conductor: Beryllium copper, gold plated Shielding Plunger: Stainless steel, gold plated Shielding Plunger: Brass, gold plated Dielectric Insulator: Teflon Shielding Tube: Stainless steel, gold plated Signal Conductor: 100954



Specifications subject to change without notice. Dimensions in inches (millimeters)

020 (0.51) .113 (2.87).110 (2.79)330 (8.38) .170 (4.32) 1.118 (28.40).100 (2.54) .150 (3.81) .145 (3.68) .020 (0.51) SMB Connector

100559 & 100910

PROBE SPECIFICATIONS

Minimum Centers: .300 (7.62) Current Rating: 3 amps continuous Spring Force: Signal Conductor: 1.6 oz. @ .070 (1.78) travel: tip B 2.0 oz. @ .070 (1.78) travel: tip ES Shielding Plunger: 4.3 oz. @ .070 (1.78) travel Nominal Impedance: 50 Ω Maximum Travel: .090 (2.29) for tip B .075 (1.91) for tip ES Working Travel: .070 (1.78)

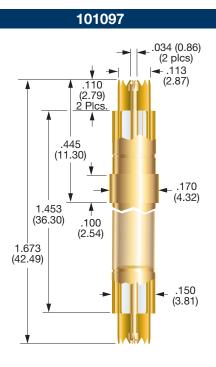
MATERIALS

Barrel: Brass, gold plated Spring: Signal Conductor: Beryllium copper, gold plated Shielding Plunger: Stainless steel, gold plated Shielding Plunger: Beryllium copper, gold plated Dielectric Insulator: Teflon Shielding Tube: Brass, gold plated Signal Conductor: Series S, Size 00



Interconnect Devices, Inc. welcomes your e-mail at info@idinet.com

DOUBLE ENDED & ATTACHED CABLE COAX Probe



PROBE SPECIFICATIONS

Minimum Centers: .200 (5.08) Current Rating: 3 amps continuous Spring Force:

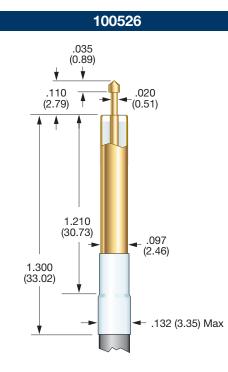
Signal Conductor: 1.6 oz. @ .037 (0.94) travel, each end Shielding Plunger: 3.4 oz. @ .037 (0.94) travel, each end

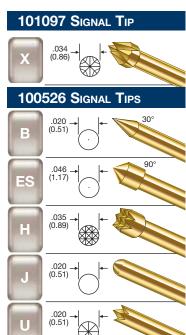
Nominal Impedance: 50Ω Maximum Travel: .075 (1.91) each end Working Travel: .037 (0.94) each end

MATERIALS

Barrel: Brass, gold plated Spring: Stainless steel, gold plated Shielding Plunger: Beryllium copper, gold plated Dielectric Insulator: Teflon Shielding Tube: Brass, gold plated Signal Conductor: 100617-000 probe





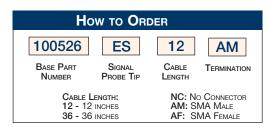


PROBE SPECIFICATIONS

Minimum Centers: .150 (3.18) Current Rating: 3 amps continuous Spring Force: Signal Conductor: 1.6 oz. @ .070 (1.78) travel: tips B, J, U 2.0 oz. @ .070 (1.78) travel: tips ES, H Nominal Impadence: 50 Ω Maximum Travel: .090 (2.29) for tips B, J, & U .075 (1.91) for tips ES, & H Working Travel: .070 (1.78)

MATERIALS

Spring: Beryllium copper, gold plated Dielectric Insulator: Teflon Shielding Tube: Brass, gold plated Signal Conductor: Series S, Size 00 probe Coaxial Cable: RG 316



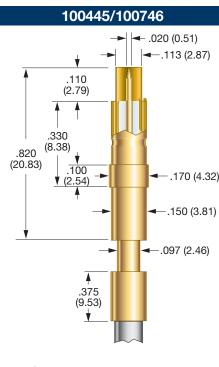
* WHEN ORDERING WITH A PREATTACHED CONNECTOR, PLEASE NOTE THAT THE CONNECTOR WILL NOT FIT THROUGH THE PROBE MOUNTING HOLE. THE PROBE MUST BE INSERTED FROM THE BOTTOM SIDE OF THE MOUNTING PLATE.

CONSULT IDI FOR MORE INFORMATION.

Coax Probes Attached Cable



100445 & 100746



PROBE SPECIFICATIONS

Minimum Centers: .200 (5.08) Current Rating: 3 amps continuous Spring Force: Signal Conductor: B Tip: 1.6 oz. @ .070 (1.78) travel A, ES, H Tips: 2.0 oz. @ .070 (1.78) travel Shielding Plunger: 4.3 oz. @ .070 (1.78) travel Nominal Impedance: 50 Ω Maximum Travel:

.090 (2.29) for tip B .075 (1.91) for tips A, ES, H Working Travel: .070 (1.78)

MATERIALS

Barrel: Brass, gold plated Spring:

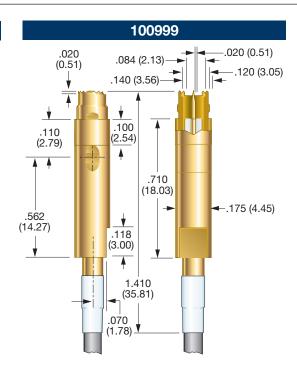
Signal Conductor: Beryllium copper, gold plated

Shielding Plunger: Stainless steel, gold plated Shielding Plunger: Beryllium copper, gold plated Dielectric Insulator: Teflon

Shielding Tube: Stainless steel, gold plated Signal Conductor: Series S, Size 00 probe

Crimp Ferrule: Brass, gold plated Coaxial Cable: 100445: RG 174U

100746: RG 316



PROBE SPECIFICATIONS

Minimum Centers: .200 (5.08) Current Rating: 3 amps continuous Spring Force: Signal Conductor: B Tip: 1.6 oz. @ .070 (1.78) travel U Tip: 3.3 oz. @ .070 (1.78) travel Shielding Plunger: 4.5 oz. @ .070 (1.78) travel Nominal Impedance: 50 Ω Maximum Travel: .090 (2.29) Working Travel: .070 (1.78)

MATERIALS

Barrel: Brass, gold plated Spring:

> Signal Conductor: Beryllium copper, gold plated Shielding Plunger: Stainless steel, gold plated

Shielding Plunger: Beryllium copper, gold plated Dielectric Insulator: Teflon

Shielding Tube: Brass, gold plated

Signal Conductor: Series S, Size 00 probe Coaxial Cable: Semi-flex or flex cable

How to Order	How to Order
100445 B F N 12 AM	100999 B 12 AM F
BASE PART SIGNAL MOUNTING SHIELDING CABLE TERMINATION NUMBER PROBE TIP FLANGE PLUNGER LENGTH	BASE PART SIGNAL CABLE TERMINATION CABLE NUMBER PROBE TIP LENGTH TYPE
N: Without flange F: With flange	
Shielding Plunger: Cable Length: AM: SMA Male S: Serrated 12 - 12 INCHES AF: SMA Female N: FLat 36 - 36 INCHES NC: NO CONNECTOR	CABLE LENGTH: AM: SMA MALE F: FLEX 12 - 12 INCHES AF: SMA FEMALE S: SEMI-FLEX 36 - 36 INCHES NC: NO CONNECTOR

* WHEN ORDERING WITH A PREATTACHED CONNECTOR, PLEASE NOTE THAT THE CONNECTOR WILL NOT FIT THROUGH THE PROBE MOUNTING HOLE. THE PROBE MUST BE INSERTED FROM THE BOTTOM SIDE OF THE MOUNTING PLATE.

CONSULT IDI FOR MORE INFORMATION.

Specifications subject to change without notice. Dimensions in inches (millimeters)

COMPREHENSIVE SOURCE BOOK

Our comprehensive IDI Source Book can now be found on our web site: www.idinet.com, in the technology section. Our purpose for the IDI Source Book was to compile an easy to use, informative reference manual for test engineers, probe specifiers, purchasers and others involved in the test probe industry. It is intended to introduce design engineers to the concept of using spring contact probes as electromechanical interconnects. Growing daily in sophistication and utilization, spring contact probes are an exciting contact technology that is becoming a primary consideration in the connector world.

Product engineers are incorporating probes in cellular phones, military electronics, aerospace electronics, medical devices, and the most cutting-edge portable devices. Designers select from probes that offer exceptional DC or RF performance, controlled impedance, very low profiles, semiconductor scale pitch, or million cycle reliability; however, probes offer design engineers an almost infinitely customizable interconnect to form precisely the best probe for their particular application.

GREEN INITIATIVE POLICY STATEMENT

Interconnect Devices, Inc., strives to continually reduce our impact on the environment and promote awareness of environmental issues. By implementing responsible cost saving or cost neutral practices wherever possible, we confirm our commitment to minimizing our overall environmental impact.

As a part of this effort, we have reduced the size of our printed catalog and have chosen to put the information online, therefore making it more readily available while conserving and reducing resources. In addition, we make every effort to chose printers who strive to do their part to reduce their impact on the environment.

It is our intent to educate and integrate our employees, customers, and our business partners on environmental responsibility. We commit to doing our part in keeping the world environmentally healthy.



	D	
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